COMPAL CONFIDENTIAL

MODEL NAME : *VAW30*

PCB NO : *LA-9832P (DA8000XL000)*

BOM P/N : *4319M931L01*

GPIO MAP: X.X

Alpine 14"

Haswell ULT

2013-08-23(Gerber)

REV : 1.0

@ : Nopop Component

1@ : M/B SPI ROM

TAA@ : TAA/B SPI ROM

CONN@ : Connector Component

DIS@ : Discrete Pop Component

UMA@ : UMA Pop Component

EMI@ : EMI Component

ESD@ : ESD Component

RF@ : RF Component

XDP@ : XDP Component

eTP@ : TS eTP Component

NeTP@ : TS non - eTP Component

76_U3@ : USB 3.0 Redriver

: Short_Pad

Interleaved Memory

MB PCB

Part Number	Description
DAXXXXXXXXX	PCB 0LD LA-9832P REV1 M/B DIS

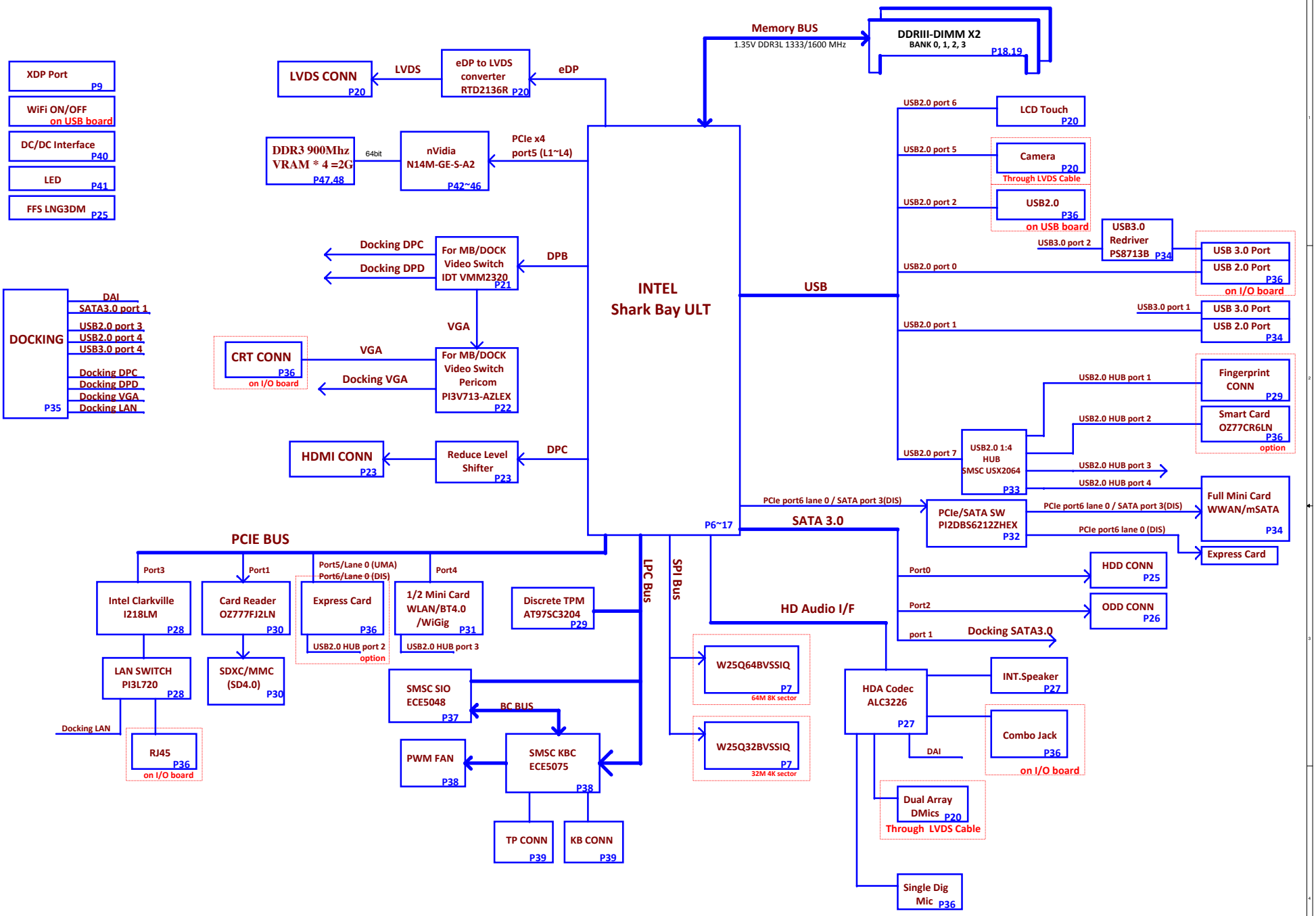
DELL CONFIDENTIAL/PROPRIETARY

Compal Electronics, Inc.

Title: Cover Sheet

Size | Document Number: LA-9832P | Rev: 0.5

Date: Thursday, August 15, 2013 | Sheet 1 of 64



DELL CONFIDENTIAL/PROPRIETARY

Compal Electronics, Inc.

Title: Block Diagram

Size | Document Number: LA-9832P | Rev: 0.5

Date: Thursday, June 13, 2013 | Sheet 2 of 64

POWER STATES

State \ Signal	SLP S3#	SLP S4#	SLP S5#	SLP A#	ALWAYS PLANE	M PLANE	SUS PLANE	RUN PLANE	CLOCKS
S0 (Full ON) / M0	HIGH	HIGH	HIGH	HIGH	ON	ON	ON	ON	ON
S3 (Suspend to RAM) / M3	LOW	HIGH	HIGH	HIGH	ON	ON	ON	OFF	OFF
S4 (Suspend to DISK) / M3	LOW	LOW	HIGH	HIGH	ON	ON	OFF	OFF	OFF
S5 (SOFT OFF) / M3	LOW	LOW	LOW	HIGH	ON	ON	OFF	OFF	OFF
S3 (Suspend to RAM) / M-OFF	LOW	HIGH	HIGH	LOW	ON	OFF	ON	OFF	OFF
S4 (Suspend to DISK) / M-OFF	LOW	LOW	HIGH	LOW	ON	OFF	OFF	OFF	OFF
S5 (SOFT OFF) / M-OFF	LOW	LOW	LOW	LOW	ON	OFF	OFF	OFF	OFF

PM TABLE

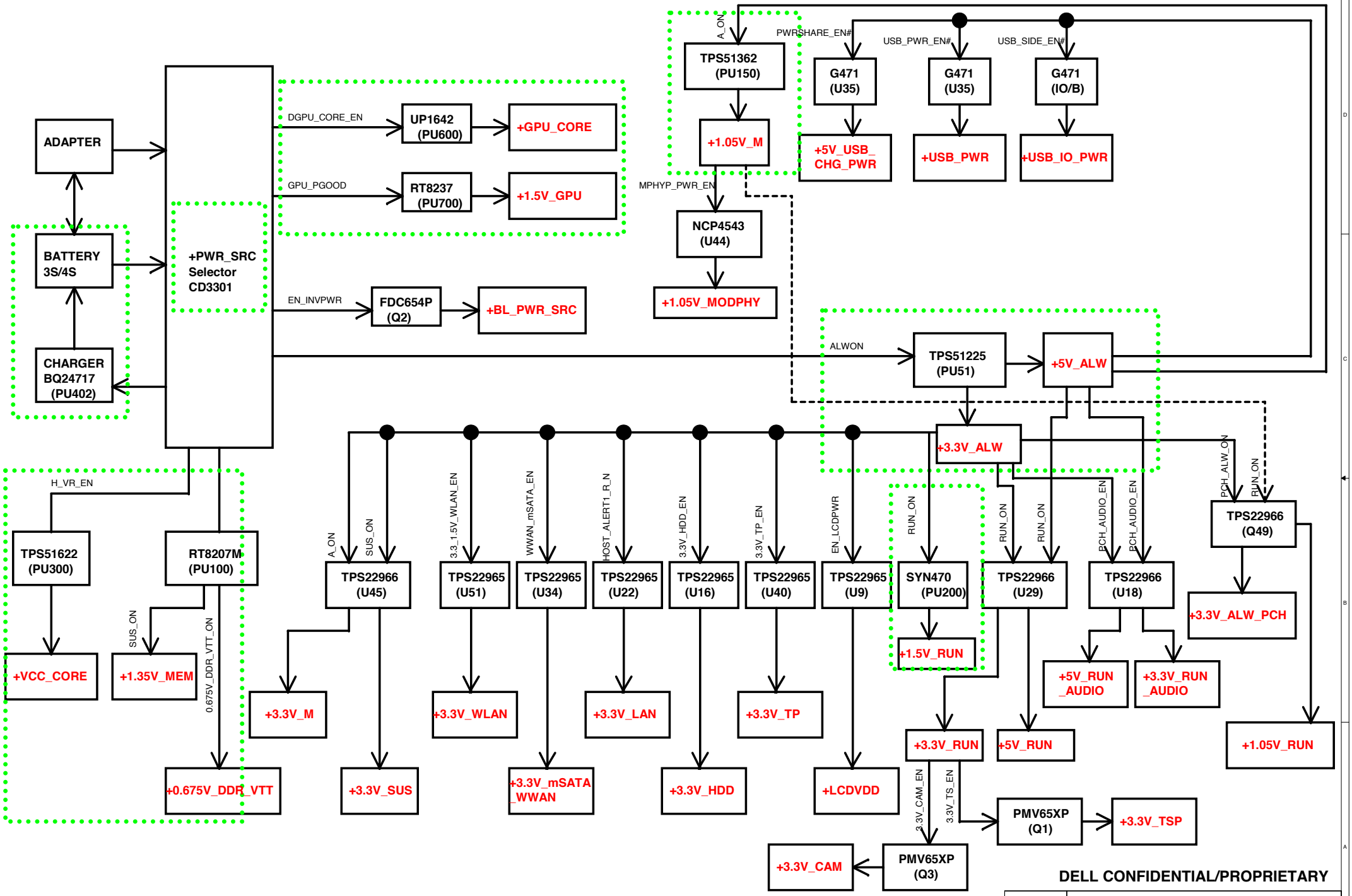
State \ power plane	+5V_ALW +3.3V_ALW +3.3V_ALW_PCH +3.3V_RTC_LDO	+3.3V_SUS +1.35V_MEM	+5V_RUN +3.3V_RUN +0.675V_DDR_VTT +1.05V_RUN +VCC_CORE	+3.3V_M +1.05V_M	+3.3V_M +1.05V_M (M-OFF)
S0	ON	ON	ON	ON	ON
S3	ON	ON	OFF	ON	OFF
S5 S4/AC	ON	OFF	OFF	ON	OFF
S5 S4/AC don't exist	OFF	OFF	OFF	OFF	OFF

need to update Power Status and PM Table

PCIE	USB3.0	SATA	DESTINATION
	USB3.0 1		JUSB1-->MB-->LEFT
	USB3.0 2		USB3.0-->IOB-->Rear Right
PCIE 1	USB3.0 3		PCIE1-->MMI PCIE
PCIE 2	USB3.0 4		USB3.0-->Docking
PCIE 3			LOM
PCIE 4			WLAN (WiGi)
PCIE 5			GPU(DIS)/Express card(UMA)
PCIE 6		SATA 3	WWAN(mSATA)/Express card(PCIE)
		SATA 2	ODD
		SATA 1	HDD
		SATA 0	DOCK

	USB PORT#	DESTINATION
HSW ULT	0	IO (Right)
	1	JUSB1(Left)
	2	USB DB(Rear Left)
	3	DOCK
	4	Dock
	5	WebCAM
	6	Touch Screen
	7	USB HUB

Compal Electronics, Inc.
Title: Index and Config.
Size: Document Number: LA-9832P
Rev: 0.5
Date: Thursday, June 13, 2013
Sheet 3 of 64



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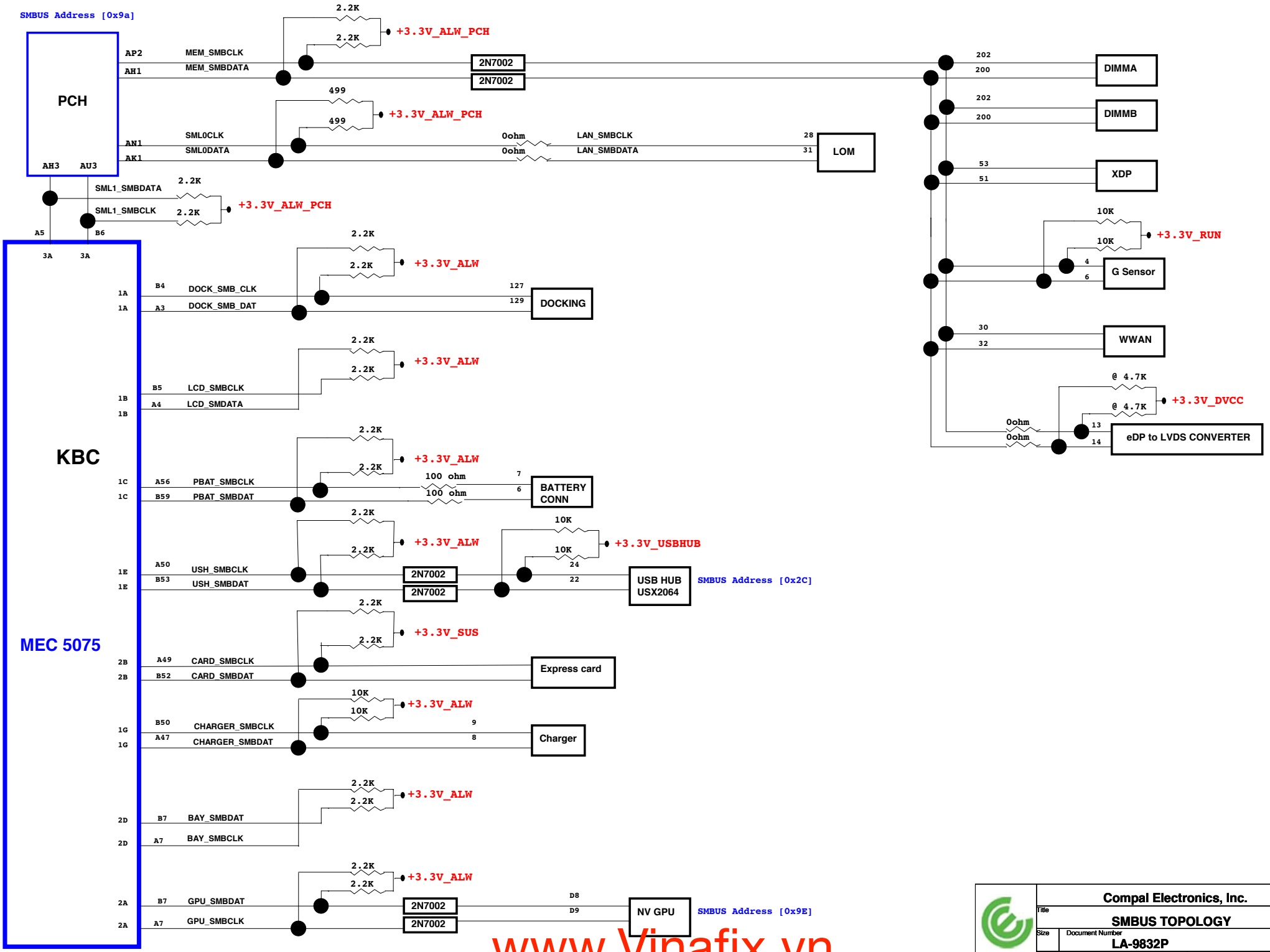
Compal Electronics, Inc.	
Title	Power Rail
Size	Document Number: LA-9832P
Rev	0.5
Date: Thursday, June 13, 2013	Sheet 4 of 64



Compal Electronics, Inc.

Title: SMBUS TOPOLOGY

Size | Document Number: LA-9832P | Rev: 0.5

Date: Thursday, June 13, 2013 | Sheet 5 of 64

+RTC_CELL

RC1 330K_0402_1%~D

PCH_INTVRMEN

RC2 330K_0402_1%~D

INTVRMEN - INTEGRATED SUS 1.05V VRM ENABLE
High - Enable Internal VRs
Low - Enable External VRs

+3.3V_ALW_PCH

@ RC3 1K_0402_1%~D PCH_AZ_SDOUT

FLASH DESCRIPTOR SECURITY OVERRIDE
LOW = DESABLED (DEFAULT)
HIGH = ENABLED

CMOS_CLR1	CMOS setting
Shunt	Clear CMOS
Open	Keep CMOS

ME_CLR1	TPM setting
Shunt	Clear ME RTC Registers
Open	Keep ME RTC Registers

CC1 15P_0402_50V8J

PCH_RTCX1_R RC4 0_0402_5% PCH_RTCX1

YC1 32.768KHZ_12.5PF_9H03200031

RC5 10M_0402_5%~D

CC2 15P_0402_50V8J

PCH_RTCX2

+RTC_CELL

RC7 1M_0402_5%~D

RC8 20K_0402_5%~D

RC6 20K_0402_5%~D

@ ME1 SHORT PADS~D

CC3 1U_0402_6.3V6K~D

@ CMOS1 SHORT PADS~D

CC4 1U_0402_6.3V6K~D

CMOS place near DIMM

9 PCH_RTCRST#

27 PCH_AZ_CODEC_SDIN0

37 ME_FWP

RC9 1K_0402_1%~D PCH_AZ_SDOUT

+1.05V_M

RC16 0_0805_5%~D

+1.05V_M_JTAG

RC17 51_0402_1%~D PCH_JTAG_TDI

RC18 51_0402_1%~D PCH_JTAG_TDO

RC20 51_0402_1%~D PCH_JTAG_TMS

@ RC10 1K_0402_1%~D PCH_JTAG_JTAGX

@ RC22 51_0402_1%~D PCH_JTAG_TCK

reference 479493 figure 7-1

UC1E HASWELL_MCP_E

RTC: RTCX1, RTCX2, INTRUDER#, INTVRMEN, SRTCRST#, RTCRST#

AUDIO: PCH_AZ_BITCLK, PCH_AZ_SYNC, PCH_AZ_RST#, PCH_AZ_CODEC_SDIN0, PCH_AZ_SDOUT, HDA_BCLK/I2S0_SCLK, HDA_SYNC/I2S0_SFRM, HDA_RST/I2S_MCLK, HDA_SDI0/I2S0_RXD, HDA_SDI1/I2S1_RXD, HDA_SDO/I2S0_TXD, HDA_DOCK_EN/I2S1_TXD, HDA_DOCK_RST/I2S1_SFRM, I2S1_SCLK

JTAG: PCH_JTAG_TRST#, PCH_JTAG_TCK, PCH_JTAG_TDI, PCH_JTAG_TDO, PCH_JTAG_TMS, PCH_JTAG_JTAGX, PCH_TRST, PCH_TCK, PCH_TDI, PCH_TDO, PCH_TMS, RSVD, JTAGX

SATA: SATA_RN0/PERN6_L3, SATA_RP0/PERP6_L3, SATA_TN0/PETN6_L3, SATA_TP0/PETP6_L3, SATA_RN1/PERN6_L2, SATA_RP1/PERP6_L2, SATA_TN1/PETN6_L2, SATA_TP1/PETP6_L2, SATA_RN2/PERN6_L1, SATA_RP2/PERP6_L1, SATA_TN2/PETN6_L1, SATA_TP2/PETP6_L1, SATA_RN3/PERN6_L0, SATA_RP3/PERP6_L0, SATA_TN3/PETN6_L0, SATA_TP3/PETP6_L0, SATA0GP/GPIO34, SATA1GP/GPIO35, SATA2GP/GPIO36, SATA3GP/GPIO37, SATA_IREF, RSVD, RSVD, SATA_RCOMP, SATALED

5 OF 19 Rev1p2

SATA_PRX_DKTX_N0_C, SATA_PRX_DKTX_P0_C, SATA_PTX_DKRX_N0_C, SATA_PTX_DKRX_P0_C — DOCK

SATA_PRX_DTX_N1_C, SATA_PRX_DTX_P1_C, SATA_PTX_DRX_N1_C, SATA_PTX_DRX_P1_C — SATA HDD

SATA_ODD_PRX_DTX_N2_C, SATA_ODD_PRX_DTX_P2_C, SATA_ODD_PTX_DRX_N2_C, SATA_ODD_PTX_DRX_P2_C — ODD

PCH Rx side need use strap pin to update PCIE +/-

EXP_PRX_EXPTX_N6, EXP_PRX_EXPTX_P6, EXP_PTX_EXPRX_N6, EXP_PTX_EXPRX_P6 — Express card/mSATA

MPCIE_RST# 31, HDD_DET# 25, PCH_GPIO36 9, MCARD_PCIE_MSATA# 37

SATA_IREF: 0_0402_5% RC14 PCH_ASATA3PLL

SATA_ACT# 41

SATA_IREF

SATA_IREF min 4mil trace at break-out and 12-15mil trace with <0.2 ohms and length total <= 500mils. Requires 12 mils isolation from all High Speed IO and clocks.

+3.3V_RUN

HDD_DET# 100K_0402_5%~D RC11

MPCIE_RST# 10K_0402_5%~D RC138

MCARD_PCIE_MSATA# 10K_0402_5%~D RC12

Shark_Bay_ULT_PDG 0.9:
the sampled value for the GPIO corresponding to the particular port during boot time.
SATA3GP/GPIO37-->SATAP3:
1:SATA
0:PCIe

SATA Impedance Compensation

+PCH_ASATA3PLL

SATA_COMP RC19 3.01K_0402_1%~D

SATA_RCOMP min 4mil trace at break-out and 12-15mil trace with <0.2 ohms and length total <= 500mils. Requires 12 mils isolation from all High Speed IO and clocks.

reference FFRD sch 0.5

HDA for Codec

27 PCH_AZ_CODEC_SDOUT — RC23 33_0402_5%~D — PCH_AZ_SDOUT

27 PCH_AZ_CODEC_SYNC — RC24 33_0402_5%~D — PCH_AZ_SYNC

27 PCH_AZ_CODEC_RST# — RC25 33_0402_5%~D — PCH_AZ_RST#

27 PCH_AZ_CODEC_BITCLK — RC26 33_0402_5%~D — PCH_AZ_BITCLK

@ CC5 27P_0402_50V8J~D

EMI

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Compal Electronics, Inc.

Title: MCP(1/12) RTC,SATA,HDA,JTAG

Size: Document Number: LA-9832P Rev: 0.5

Date: Monday, June 17, 2013 Sheet 6 of 64

BIOS ROM (4MB + 8MB) Selection:

1@ 8MB: Windbond W25Q64FVSSIQ, Micron N25Q064A, MXIC MX25L6475E, Atmel AT25DQ641A

4MB: Windbond W25Q32FVSSIQ, Micron N25Q032A, MXIC MX25L3275E, Atmel AT25DQ321

BIOS ROM (4MB + 8MB) Part Number:

8MB	Micron N25Q064A	MXIC MX25L6475E
P/N	SA000069G00	SA00006CG00

4MB	Micron N25Q032A	MXIC MX25L3275E
P/N	SA00005KR00	SA00006DI00

TAA Config

P/N:SP071210080

IF RC100 =0 ohm than zero delay

RC164, RC188 co-layout with RC160, RC184

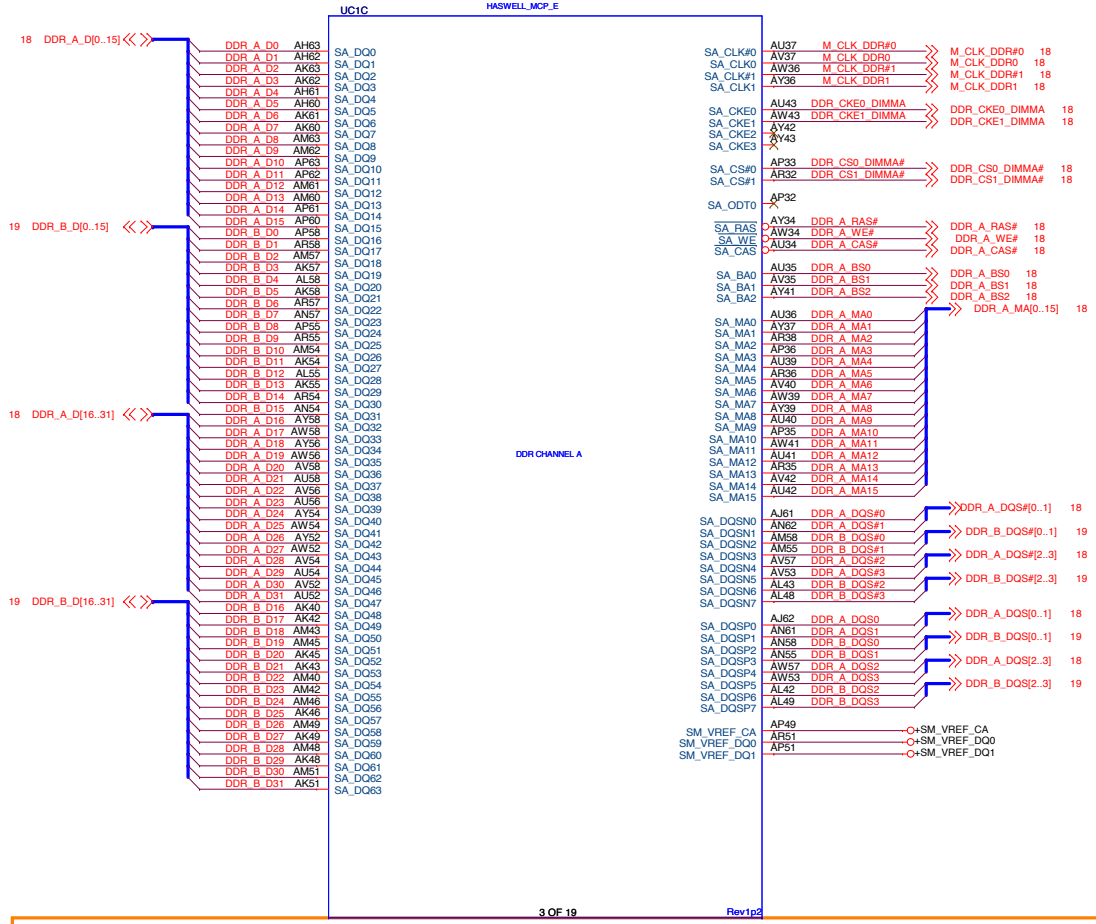
RC165, RC196 co-layout with RC157, RC179

Co-layout with UC5

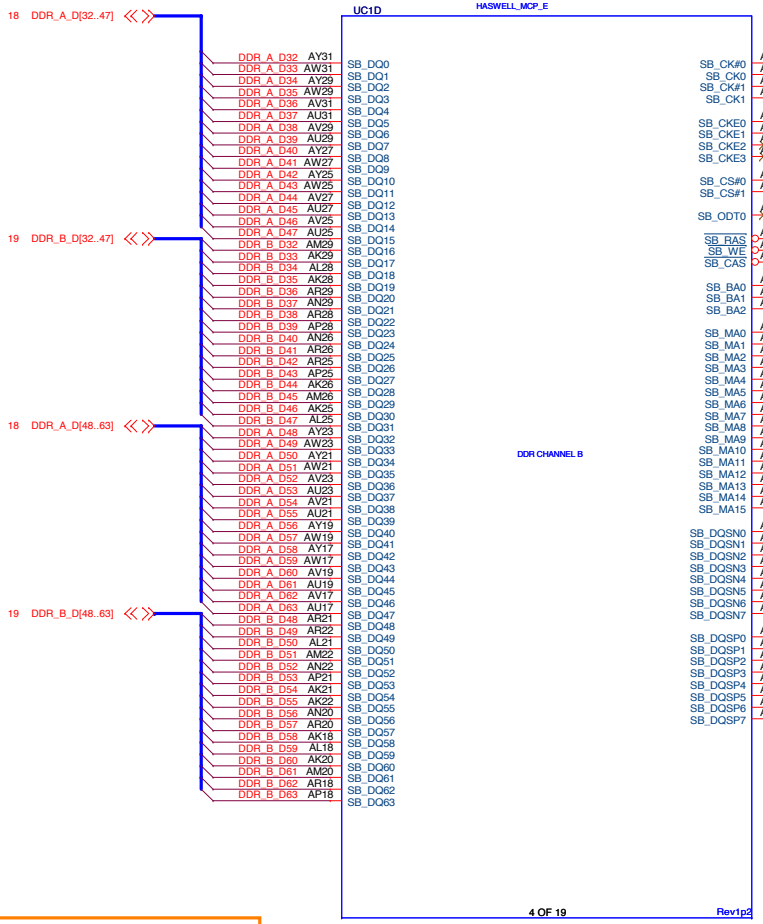
	PCIE 5	PCIE 6
Root port	Lane 0	Lane 0
Alpine 14" DSC	PCIe x 4 Graphics	PCIe MUX: Exp Card / FMC (GPE & mSATA)
PCI-E CLK DSC	CLK 4	CLK 0 / CLK 3
PCI-E REQ DSC	REQ 4	REQ 5
Alpine 14" UMA	Exp Card	FMC (GPE & mSATA)
PCI-E CLK DSC	CLK 4	CLK 3
PCI-E REQ DSC	REQ 4	REQ 5

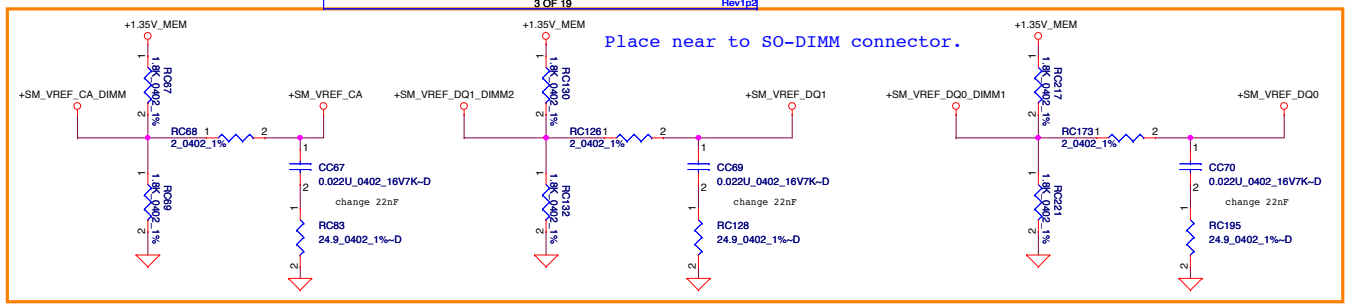
Compal Electronics, Inc.
Title: MCP(2/12)CLK,SMB,SPI,LPC,CL
Size: Document Number: LA-9832P
Rev: 0.5
Date: Monday, June 17, 2013
Sheet 7 of 64

DDR interleave routing



DDR interleave routing





Refer to Intel request PDG1.0 P148

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Interleaved Memory

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Compal Electronics, Inc.

Title: MCP(3/12) DDR3

Size | Document Number: LA-9832P | Rev: 0.5

Date: Thursday, June 13, 2013 | Sheet 8 of 64

DeepSleep and Non-DeepSleep config:

Config	DSx	Non-DSx
Pop	RC86,R319,RC267	RC79,RC82,RC265
Depop	RC79,RC82,RC265	RC86,R319,RC267

DSWODVREN - ON DIE DSW VR ENABLE
HIGH = ENABLED (DEFAULT)
LOW = DISABLED

DDR3 COMPENSATION SIGNALS

CAD Note:
Trace width=12~15 mil, Spcing=20 mils
Max trace length= 500 mil

CAD Note:
Avoid stub in the PWRGD path
while placing resistors RC115

Place near JXDP1

RC5 need to close to JCPU1

Place near JXDP1.48

Place near JXDP1.47

EMI

For ESD concern,place RC209, RC208, RC194, RC204 near to CPU

reference Shark Bay ULT Validation Customer Debug Port Implementation Requirement Rev 1.0

reference CRB

PU/PD for JTAG signals

Compal Electronics, Inc.

Title: MCP(4/12) PM, JTAG,MISC

Size: | Document Number: LA-9832P | Rev: 0.5

Date: Thursday, June 13, 2013 | Sheet 9 of 64

Intel check list has updated correctly

DP HUB <-----

HDMI<-----

UC1A — HASWELL_MCP_E — DDI / EDP — 1 OF 19 — Rev1p2

21	DDI1_LANE_N0	DDI1_LANE_N0	C54	DDI1_TXN0	EDP_TXN0	C45	EDP_CPU_LANE_N0
21	DDI1_LANE_P0	DDI1_LANE_P0	C55	DDI1_TXP0	EDP_TXP0	B46	EDP_CPU_LANE_P0
21	DDI1_LANE_N1	DDI1_LANE_N1	B58	DDI1_TXN1	EDP_TXN1	A47	EDP_CPU_LANE_N1
21	DDI1_LANE_P1	DDI1_LANE_P1	C58	DDI1_TXP1	EDP_TXP1	B47	EDP_CPU_LANE_P1
21	DDI1_LANE_N2	DDI1_LANE_N2	B55	DDI1_TXN2	EDP_TXN2	C47	
21	DDI1_LANE_P2	DDI1_LANE_P2	A55	DDI1_TXP2	EDP_TXP2	C46	
21	DDI1_LANE_N3	DDI1_LANE_N3	A57	DDI1_TXN3	EDP_TXN3	A49	
21	DDI1_LANE_P3	DDI1_LANE_P3	B57	DDI1_TXP3	EDP_TXP3	B49	
23	TMDS_N2	TMDS_N2	C51	DDI2_TXN0	EDP_AUXN	A45	EDP_CPU_AUX#
23	TMDS_P2	TMDS_P2	C50	DDI2_TXP0	EDP_AUXP	B45	EDP_CPU_AUX
23	TMDS_N1	TMDS_N1	C53	DDI2_TXN1	EDP_RCOMP	D20	EDP_COMP
23	TMDS_P1	TMDS_P1	B54	DDI2_TXP1	EDP_DISP_UTIL	A43	
23	TMDS_N0	TMDS_N0	C49	DDI2_TXN2			
23	TMDS_P0	TMDS_P0	B50	DDI2_TXP2			
23	TMDS_CLK#	TMDS_CLK#	A53	DDI2_TXN3			
23	TMDS_CLK	TMDS_CLK	B53	DDI2_TXP3			

COMPENSATION PU FOR eDP

follow intel feedback

+VCCIOA_OUT

EDP_COMP — 24.9_0402_1%~D — RC134

CAD Note:Trace width=20 mils ,Spacing=25mil, Max length=100 mils.

+3.3V_RUN

RC137	100K_0402_5%~D	ODD_DA#
RC140	10K_0402_5%~D	TOUCHPAD_INTR#
RC146	10K_0402_5%~D	PIRQ#_TPM
RC148	10K_0402_5%~D	PIRQD

reference 0.55 design chane log WW23_2

UC1I — HASWELL_MCP_E — eDP SIDEBAND / DISPLAY / GPIO — 9 OF 19 — Rev1p2

20	EDP_BIA_PWM	EDP_BIA_PWM	B8	EDP_BKLCTL	DDPB_CTRLCLK	B9	CPU_DPB_CTRLCLK
20	PANEL_BKLEN	PANEL_BKLEN	A9	EDP_BKLEN	DDPB_CTRLDATA	C9	CPU_DPB_CTRLDAT
20,37	ENVDD_PCH	ENVDD_PCH	C6	EDP_VDDEN	DDPC_CTRLCLK	D9	TMDS_DDC_SCL
					DDPC_CTRLDATA	D11	TMDS_DDC_SDA
26	ODD_DA#	ODD_DA#	U6	PIRQA/GPIO77	DDPB_AUXN	C5	CPU_DPB_AUX#
12,37,60,62	DGPU_PWROK	DGPU_PWROK	P4	PIRQB/GPIO78	DDPB_AUXP	B5	CPU_DPB_AUX
12,25	HDD_FALL_INT	PIRQ#_TPM	N4	PIRQC/GPIO79	DDPC_AUXN	B6	CPU_DPC_AUX#
		PIRQD	N2	PIRQD/GPIO80	DDPC_AUXP	A6	CPU_DPC_AUX
			AD3	PME			
		TOUCHPAD_INTR#	U7	GPIO55	DDPB_HPD	C8	DPB_HPD
12	TOUCH_RST_N_GYRO_INT1	TOUCH_RST_N_GYRO_INT1	L1	GPIO52	DDPC_HPD	A8	TMDS_HPD
49	DGPU_PWR_EN	DGPU_PWR_EN	L3	GPIO54	EDP_HPD	D6	EDP_CPU_HPD
60	DGPU_CORE_EN	DGPU_CORE_EN	R5	GPIO51			
		CODEC_IRQ	L4	GPIO53			

0_0402_5%~D — R73 PIRQ#_TPM — R75 PIRQD

RC152	100K_0402_5%~D	ENVDD_PCH
RC154	1K_0402_1%~D	CODEC_IRQ
RC306	10K_0402_5%~D	DGPU_PWR_EN
RC305	10K_0402_5%~D	DGPU_CORE_EN

100K_0402_5%~D — RC158

reference PDG 0.9

Intel WW18 Strapping option

Intel WW18 Strapping option

+3.3V_RUN

RP1 2.2K_0804_8P4R_5%

CPU_DPB_CTRLCLK	8	1
CPU_DPB_CTRLDAT	7	2
TMDS_DDC_SCL	6	3
TMDS_DDC_SDA	5	4

CPU_DPB_AUX#	100K_0402_5%~D	RC147
CPU_DPC_AUX#	100K_0402_5%~D	RC149

DPB_HPD	100K_0402_5%~D	RC156
CPU_DPB_AUX	100K_0402_5%~D	RC153
CPU_DPC_AUX	100K_0402_5%~D	RC155

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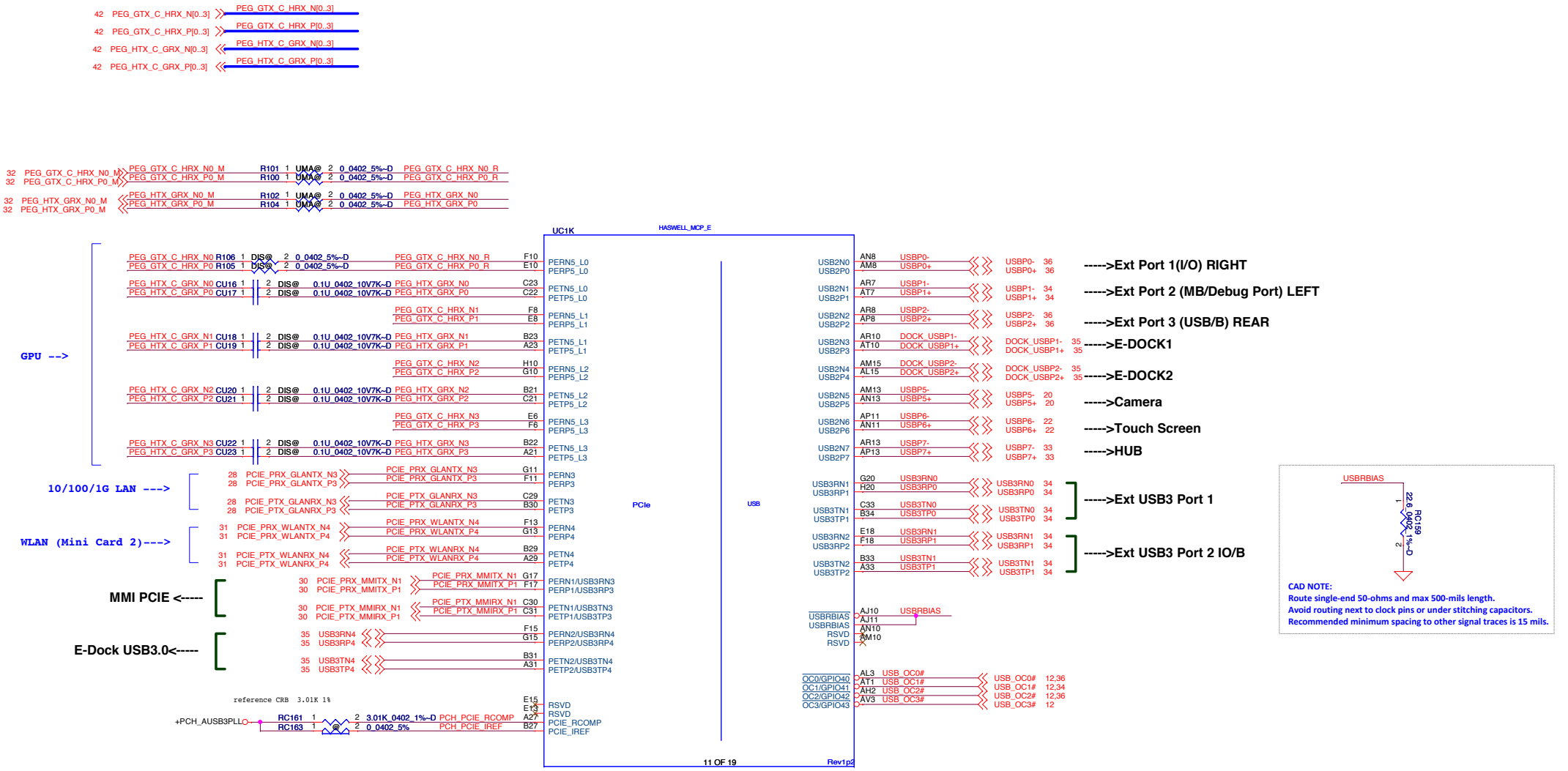
Compal Electronics, Inc.

Title: MCP(5/12) DDI,EDP,GPIO

Size: — Document Number: LA-9832P — Rev: 0.5

Date: Thursday, June 13, 2013 — Sheet 10 of 64



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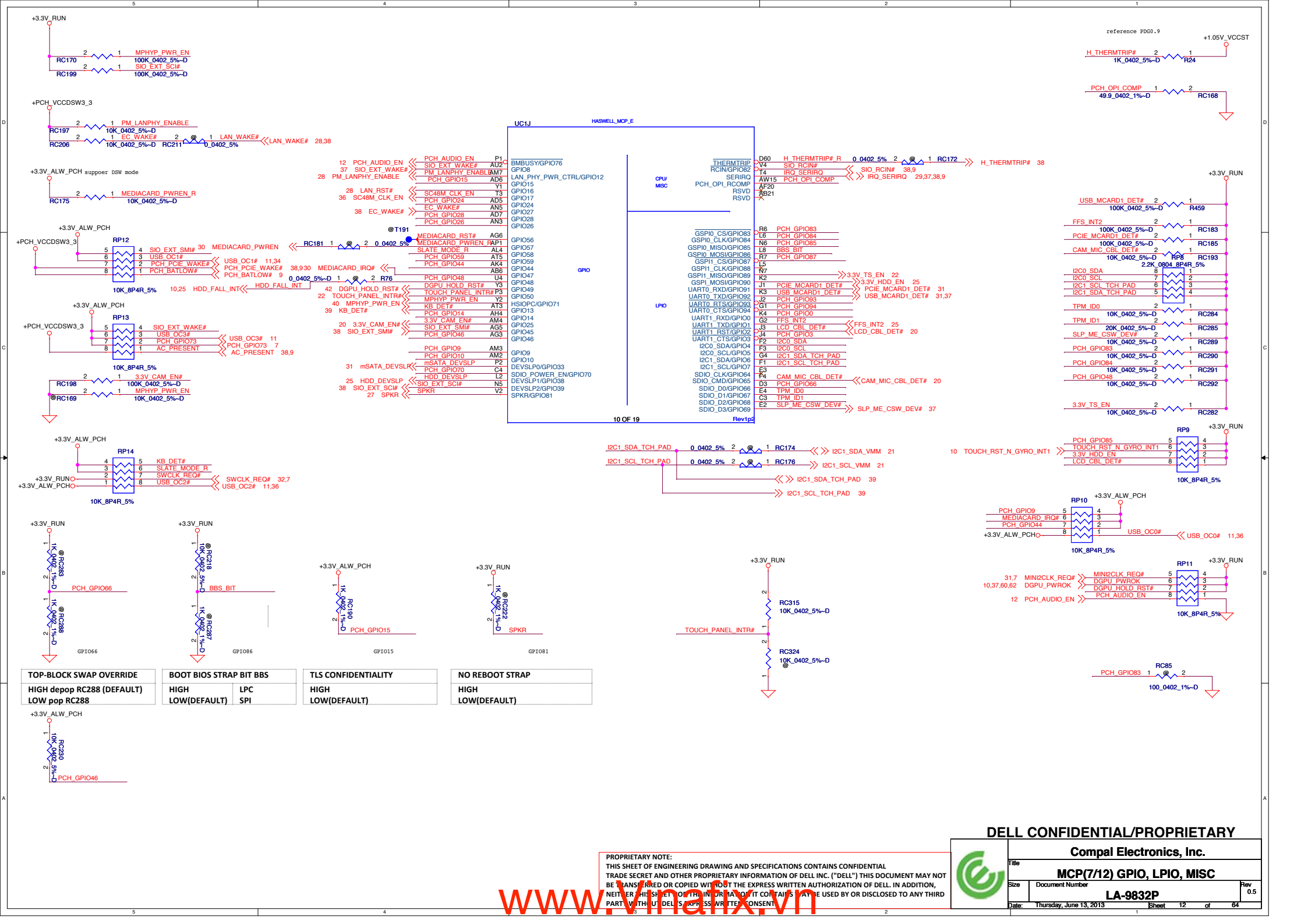
Compal Electronics, Inc.

Title: MCP(6/12) PCIE,USB

Size: | Document Number: LA-9832P | Rev: 0.5

Date: Thursday, June 13, 2013 | Sheet 11 of 64



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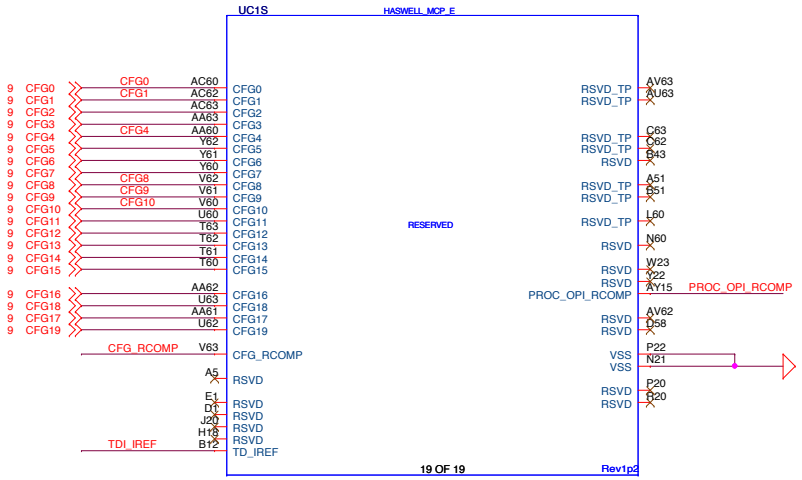
Compal Electronics, Inc.

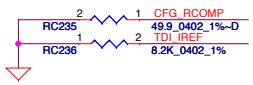
Title: MCP(7/12) GPIO, LPIO, MISC

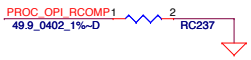
Size: Document Number: LA-9832P Rev: 0.5

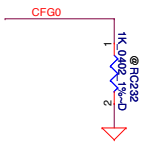
Date: Thursday, June 13, 2013 Sheet 12 of 64

CFG STRAPS for CPU

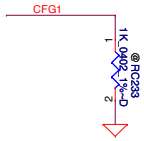




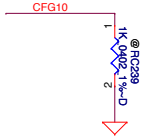


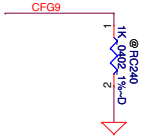


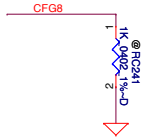
EAR-STALL/NOT STALL RESET SEQUENCE AFTER PCU PLL IS LOCKE	
CFG0	1:(Default) Normal Operation; No stall 0:Lane Reversed

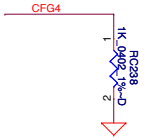


PCH/PCH LESS MODE SELECTION	
CFG1	1:(Default) Normal Operation 0:Lane Reversed









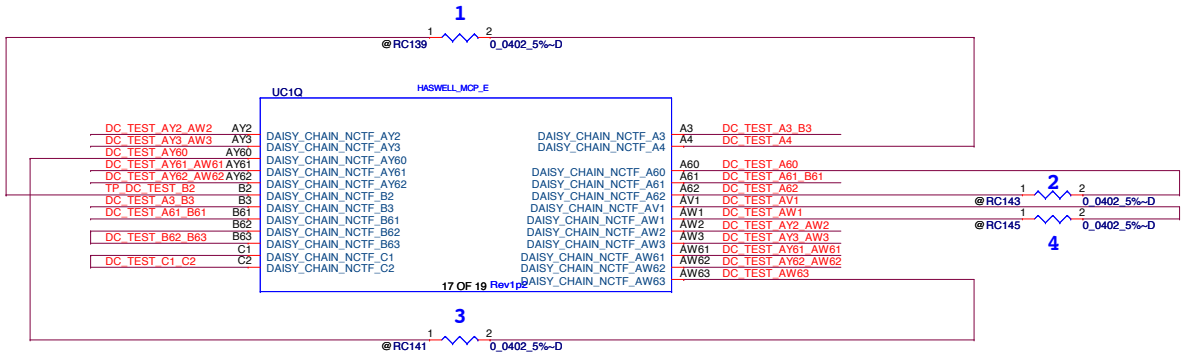
SAFE MODE BOOT	
CFG10	1: POWER FEATURES ACTIVATED DURING RESET 0: POWER FEATURES (ESPECIALLY CLOCK GATINE ARE NOT ACTIVATED

NO SVID PROTOCOL CAPABLE VR CONNECTED	
CFG9	1: VRS support SVID protocol are present 0:No VR support SVID is present The chip will not generate(OR Respond to) SVID activity

ALLOW THE USE OF NOA ON LOCKED UNITS	
CFG8	1: Enable(Default): Noa will be disable in locked units and enable in un-locked units 0: Enable Noa will be available pegardless of the locking of the unit

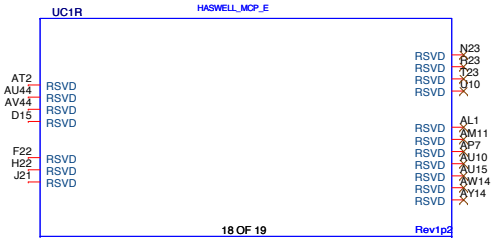
Display Port Presence Strap	
CFG4	1 : Disabled; No Physical Display Port attached to Embedded Display Port 0 : Enabled; An external Display Port device is connected to the Embedded Display Port

Compal Electronics, Inc.
Title: MCP(8/12) CFG, RSVD
Size: Document Number: LA-9832P
Rev: 0.5
Date: Thursday, June 13, 2013
Sheet 13 of 64

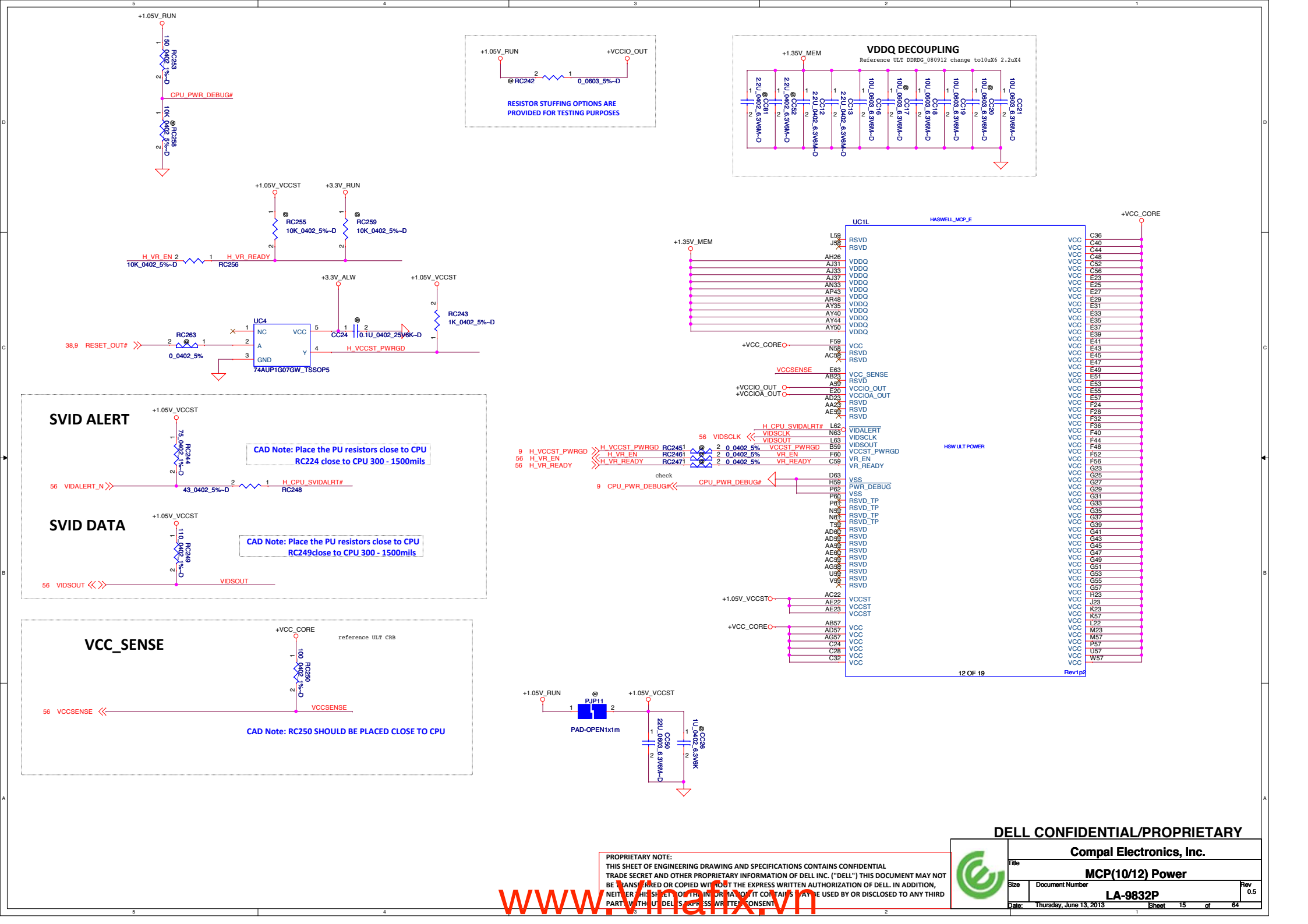


Package Daisy Chain:

1. B2-PKG-C1-PCB-C2-PKG-B3-PCB-A3-PKG-A4
2. A62-PKG-A61-PCB-B61-PKG-B62-PCB-B63-PKG-A60
3. AY60-PKG-AW61-PCB-AY61-PKG-AW62-PCB-AY62-PKG-AW63
4. AW1-PKG-AW3-PCB-AY3-PKG-AW2-PCB-AY2-PKG-AV1



Compal Electronics, Inc.
Title: MCP(9/12) TP,RSVD
Size: Document Number: LA-9832P
Rev: 0.5
Date: Thursday, June 13, 2013
Sheet 14 of 64



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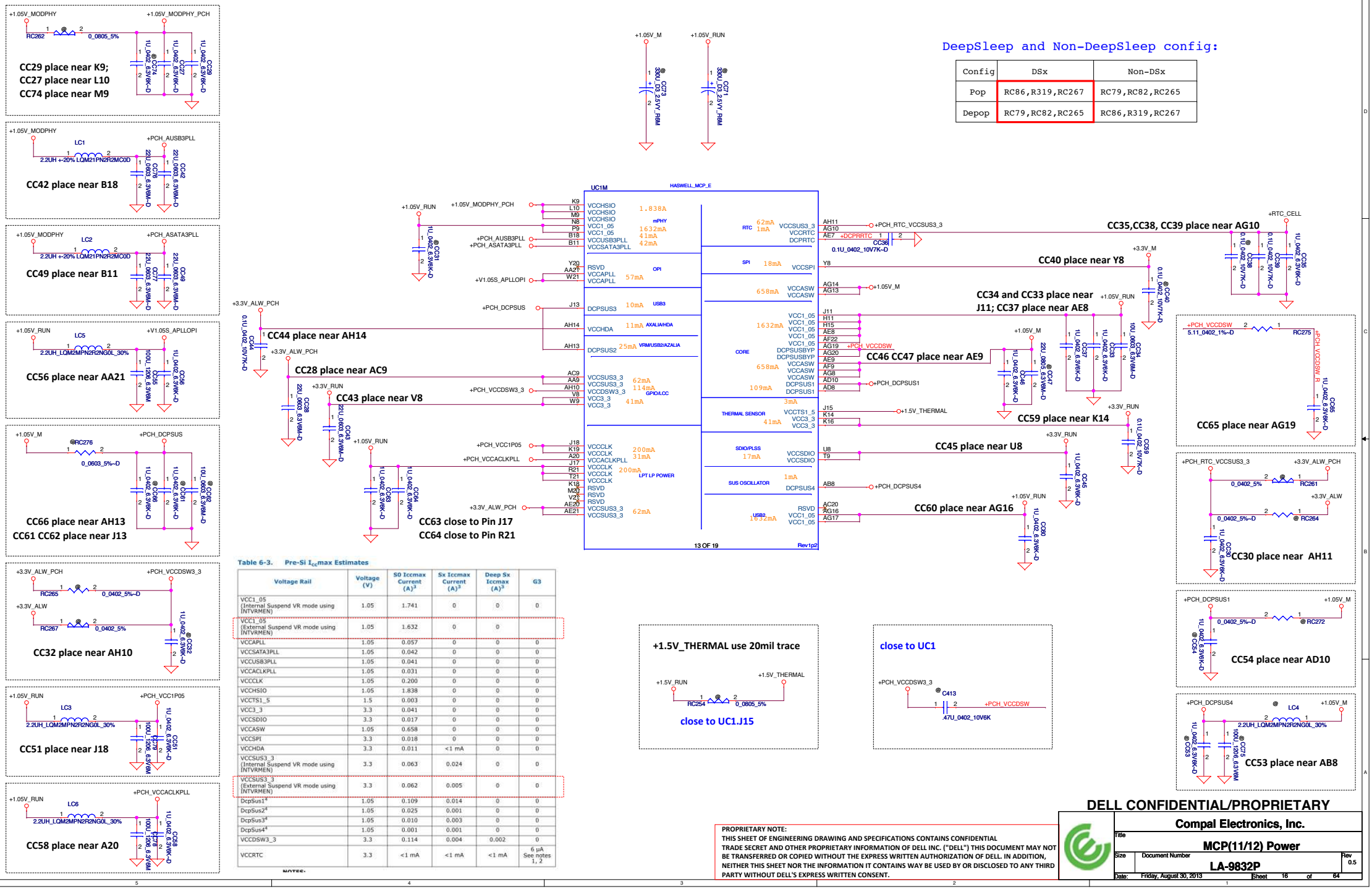
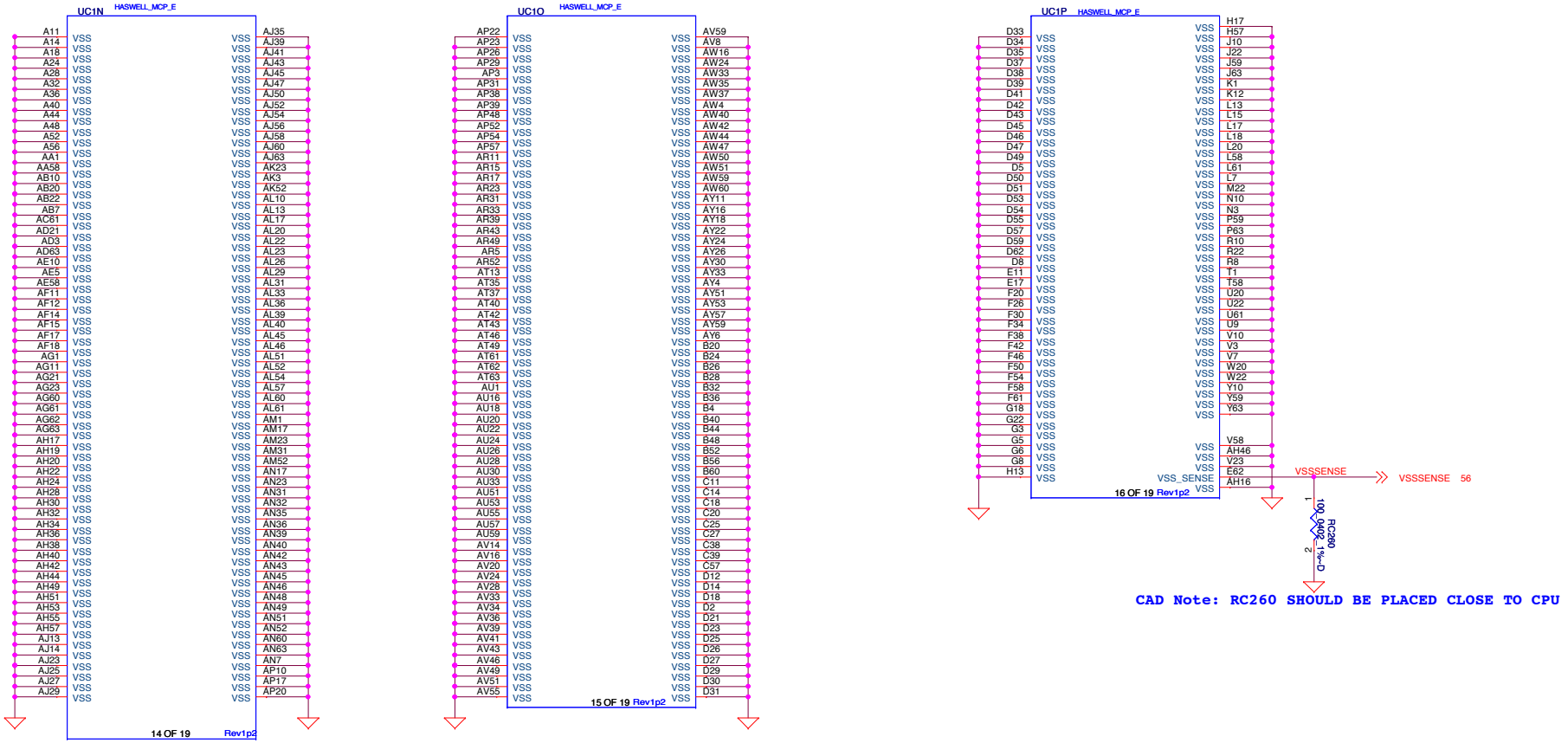
Compal Electronics, Inc.

Title: MCP(10/12) Power

Size: | Document Number: LA-9832P | Rev: 0.5

Date: Thursday, June 13, 2013 | Sheet 15 of 64





Compal Electronics, Inc.

Title: MCP(12/12) VSS

Size: | Document Number: LA-9832P | Rev: 0.5

Date: Thursday, June 13, 2013 | Sheet 17 of 64

JDIMM1 H=8mm

2-3A to 1 DIMMs/channel

Reverse Type

All VREF traces should have 10 mil trace width

8 DDR_A_DQS#[0..7]
8 DDR_A_D[0..63]
8 DDR_A_DQS[0..7]
8 DDR_A_MA[0..15]

Layout Note:
Place near JDIMM1

Note:
Check voltage tolerance of VREF_DQ at the DIMM socket

Layout Note:
Place near JDIMM1.203,204

JDIMM1 / CONN@

CONCR_0706F0BE80F

P/N:SP07000VB00

CAD NOTE
PLACE THE CAP NEAR TO DIMM RESET PIN

DDR3L SODIMM ODT GENERATION

Interleaved Memory

DELL CONFIDENTIAL/PROPRIETARY

Compal Electronics, Inc.	
Title	DDRIII DIMM1
Size	Document Number: LA-9832P
Rev	0.5
Date:	Thursday, June 13, 2013
Sheet	18 of 64

JDIMM2 H=4mm *2-3A to 1 DIMMs/channel*

Reverse Type

8 DDR_B_DQS#[0..7]
8 DDR_B_D[0..63]
8 DDR_B_DQS[0..7]
8 DDR_B_MA[0..15]

All VREF traces should have 10 mil trace width

Layout Note:
Place near JDIMM2

Layout Note:
Place near JDIMM2.203,204

Note:
Check voltage tolerance of VREF_DQ at the DIMM socket

+SM_VREF_DQ1_DIMM2 — RD7 0_0402_5% — +DIMM2_VREF_DQ

CD32 2.2U_0402_6.3V6M-D
CD33 0.1U_0402_25V6K-D

+1.35V_MEM

CD35 1U_0402_6.3V6K-D
CD36 1U_0402_6.3V6K-D
CD37 1U_0402_6.3V6K-D
CD38 1U_0402_6.3V6K-D
CD39 1U_0402_6.3V6K-D
CD40 1U_0402_6.3V6K-D
CD41 1U_0402_6.3V6K-D
CD42 1U_0402_6.3V6K-D

+1.35V_MEM

CD45 10U_0603_6.3V6M-D
CD46 10U_0603_6.3V6M-D
CD47 10U_0603_6.3V6M-D
CD48 10U_0603_6.3V6M-D
CD49 10U_0603_6.3V6M-D
CD50 10U_0603_6.3V6M-D
CD51 10U_0603_6.3V6M-D
CD52 10U_0603_6.3V6M-D
CD62 330U_D3_2.5VY_R6M

+0.675V_DDR_VTT

CD54 0.1U_0402_25V6K-D
CD55 0.1U_0402_25V6K-D
CD56 0.1U_0402_25V6K-D
CD57 0.1U_0402_25V6K-D
CD58 10U_0603_6.3V6M-D
CD59 10U_0603_6.3V6M-D

+3.3V_RUN — RD10 0_0402_5% — +3.3V_RUN

CD60 0.1U_0402_25V6K-D
CD61 2.2U_0402_6.3V6M-D
RD11 0_0402_5%

+0.675V_DDR_VTT

JDIMM2 CONN@

		1	VREF_DQ	VSS	2		
DDR_B_D23		3	VSS	DQ4	4	DDR_B_D22	
DDR_B_D17		5	DQ0	DQ5	6	DDR_B_D16	
		7	DQ1	VSS	8		
		9	VSS	DQS0#	10	DDR_B_DQS#2	
		11	DM0	DQS0	12	DDR_B_DQS2	
DDR_B_D21		13	VSS	VSS	14		
DDR_B_D18		15	DQ2	DQ6	16	DDR_B_D19	
		17	DQ3	DQ7	18	DDR_B_D20	
DDR_B_D3		19	VSS	VSS	20		
DDR_B_D2		21	DQ8	DQ12	22	DDR_B_D4	
		23	DQ9	DQ13	24	DDR_B_D5	
DDR_B_DQS#0		25	VSS	VSS	26		
DDR_B_DQS0		27	DQS1#	DM1	28		
		29	DQS1	RESET#	30	DDR3_DRAMRST#	DDR3_DRAMRST# 18
DDR_B_D0		31	VSS	VSS	32		
DDR_B_D1		33	DQ10	DQ14	34	DDR_B_D6	
		35	DQ11	DQ15	36	DDR_B_D7	
DDR_B_D12		37	VSS	VSS	38		
DDR_B_D8		39	DQ16	DQ20	40	DDR_B_D13	
		41	DQ17	DQ21	42	DDR_B_D9	
DDR_B_DQS#1		43	VSS	VSS	44		
DDR_B_DQS1		45	DQS2#	DM2	46		
		47	DQS2	VSS	48		
DDR_B_D14		49	VSS	DQ22	50	DDR_B_D11	
DDR_B_D15		51	DQ18	DQ23	52	DDR_B_D10	
		53	DQ19	VSS	54		
DDR_B_D31		55	VSS	DQ28	56	DDR_B_D30	
DDR_B_D25		57	DQ24	DQ29	58	DDR_B_D26	
		59	DQ25	VSS	60		
		61	VSS	DQS3#	62	DDR_B_DQS#3	
		63	DM3	DQS3	64	DDR_B_DQS3	
DDR_B_D27		65	VSS	VSS	66		
DDR_B_D24		67	DQ26	DQ30	68	DDR_B_D29	
		69	DQ27	DQ31	70	DDR_B_D28	
		71	VSS	VSS	72		
8 DDR_CKE2_DIMMB	DDR_CKE2_DIMMB	73	CKE0	CKE1	74	DDR_CKE3_DIMMB	DDR_CKE3_DIMMB 8
		75	VDD	VDD	76		
		77	NC	A15	78	DDR_B_MA15	
8 DDR_B_BS2	DDR_B_BS2	79	BA2	A14	80	DDR_B_MA14	
		81	VDD	VDD	82		
DDR_B_MA12		83	A12/BC#	A11	84	DDR_B_MA11	
DDR_B_MA9		85	A9	A7	86	DDR_B_MA7	
		87	VDD	VDD	88		
DDR_B_MA8		89	A8	A6	90	DDR_B_MA6	
DDR_B_MA5		91	A5	A4	92	DDR_B_MA4	
		93	VDD	VDD	94		
DDR_B_MA3		95	A3	A2	96	DDR_B_MA2	
DDR_B_MA1		97	A1	A0	98	DDR_B_MA0	
		99	VDD	VDD	100		
8 M_CLK_DDR2	M_CLK_DDR2	101	CK0	CK1	102	M_CLK_DDR3	M_CLK_DDR3 8
8 M_CLK_DDR#2	M_CLK_DDR#2	103	CK0#	CK1#	104	M_CLK_DDR#3	M_CLK_DDR#3 8
		105	VDD	VDD	106		
DDR_B_MA10		107	A10/AP	BA1	108	DDR_B_BS1	DDR_B_BS1 8
8 DDR_B_BS0	DDR_B_BS0	109	BA0	RAS#	110	DDR_B_RAS#	DDR_B_RAS# 8
		111	VDD	VDD	112		
8 DDR_B_WE#	DDR_B_WE#	113	WE#	S0#	114	DDR_CS2_DIMMB#	DDR_CS2_DIMMB# 8
8 DDR_B_CAS#	DDR_B_CAS#	115	CAS#	ODT0	116	M_ODT2	M_ODT2 18
		117	VDD	VDD	118		
DDR_B_MA13		119	A13	ODT1	120	M_ODT3	M_ODT3 18
8 DDR_CS3_DIMMB#	DDR_CS3_DIMMB#	121	S1#	NC	122		
		123	VDD	VDD	124		
		125	TEST	VREF_CA	126		
		127	VSS	VSS	128		
DDR_B_D32		129	DQ32	DQ36	130	DDR_B_D33	
DDR_B_D35		131	DQ33	DQ37	132	DDR_B_D34	
		133	VSS	VSS	134		
DDR_B_DQS#4		135	DQS4#	DM4	136		
DDR_B_DQS4		137	DQS4	VSS	138		
		139	VSS	DQ38	140	DDR_B_D39	
DDR_B_D36		141	DQ34	DQ39	142	DDR_B_D37	
DDR_B_D38		143	DQ35	VSS	144		
		145	VSS	DQ44	146	DDR_B_D44	
DDR_B_D40		147	DQ40	DQ45	148	DDR_B_D41	
DDR_B_D45		149	DQ41	VSS	150		
		151	VSS	DQS5#	152	DDR_B_DQS#5	
		153	DM5	DQS5	154	DDR_B_DQS5	
		155	VSS	VSS	156		
DDR_B_D43		157	DQ42	DQ46	158	DDR_B_D47	
DDR_B_D42		159	DQ43	DQ47	160	DDR_B_D46	
		161	VSS	VSS	162		
DDR_B_D52		163	DQ48	DQ52	164	DDR_B_D51	
DDR_B_D49		165	DQ49	DQ53	166	DDR_B_D55	
		167	VSS	VSS	168		
DDR_B_DQS#6		169	DQS6#	DM6	170		
DDR_B_DQS6		171	DQS6	VSS	172		
		173	VSS	DQ54	174	DDR_B_D48	
DDR_B_D50		175	DQ50	DQ55	176	DDR_B_D54	
DDR_B_D53		177	DQ51	VSS	178		
		179	VSS	DQ60	180	DDR_B_D56	
DDR_B_D63		181	DQ56	DQ61	182	DDR_B_D57	
DDR_B_D62		183	DQ57	VSS	184		
		185	VSS	DQS7#	186	DDR_B_DQS#7	
		187	DM7	DQS7	188	DDR_B_DQS7	
		189	VSS	VSS	190		
DDR_B_D58		191	DQ58	DQ62	192	DDR_B_D60	
DDR_B_D59		193	DQ59	DQ63	194	DDR_B_D61	
		195	VSS	VSS	196		
		197	SA0	EVENT#	198		
		199	VDDSPD	SDA	200		DDR_XDP_WAN_SMBDAT 18,20,25,31,7,9
		201	SA1	SCL	202		DDR_XDP_WAN_SMBCLK 18,20,25,31,7,9
+0.675V_DDR_VTT		203	VTT	VTT	204	+0.675V_DDR_VTT	
		205	BOSS1	BOSS2	206		

CONCR_0708E0BE40F
P/N:SP07000QA00

CAD NOTE
PLACE THE CAP NEAR TO DIMM RESET PIN

CD34 0.1U_0402_25V6K-D

+SM_VREF_CA_DIMMB — RD13 0_0402_5% — +SM_VREF_CA_DIMM

CD43 2.2U_0402_6.3V6M-D
CD44 0.1U_0402_25V6K-D

Interleaved Memory

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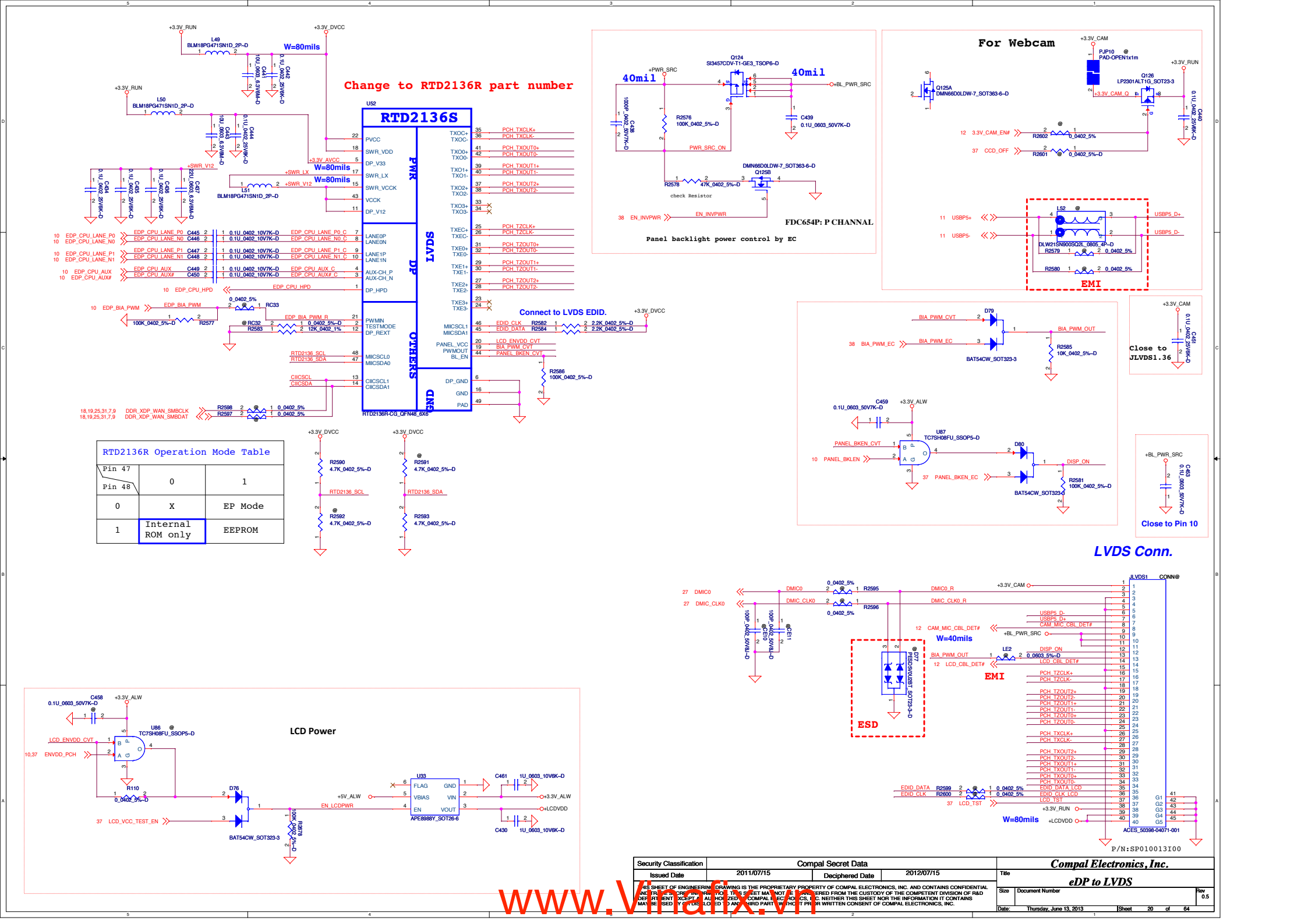
Compal Electronics, Inc.

Title: DDRIII DIMM2

Size: | Document Number: LA-9832P | Rev: 0.5

Date: Thursday, June 13, 2013 | Sheet 19 of 64



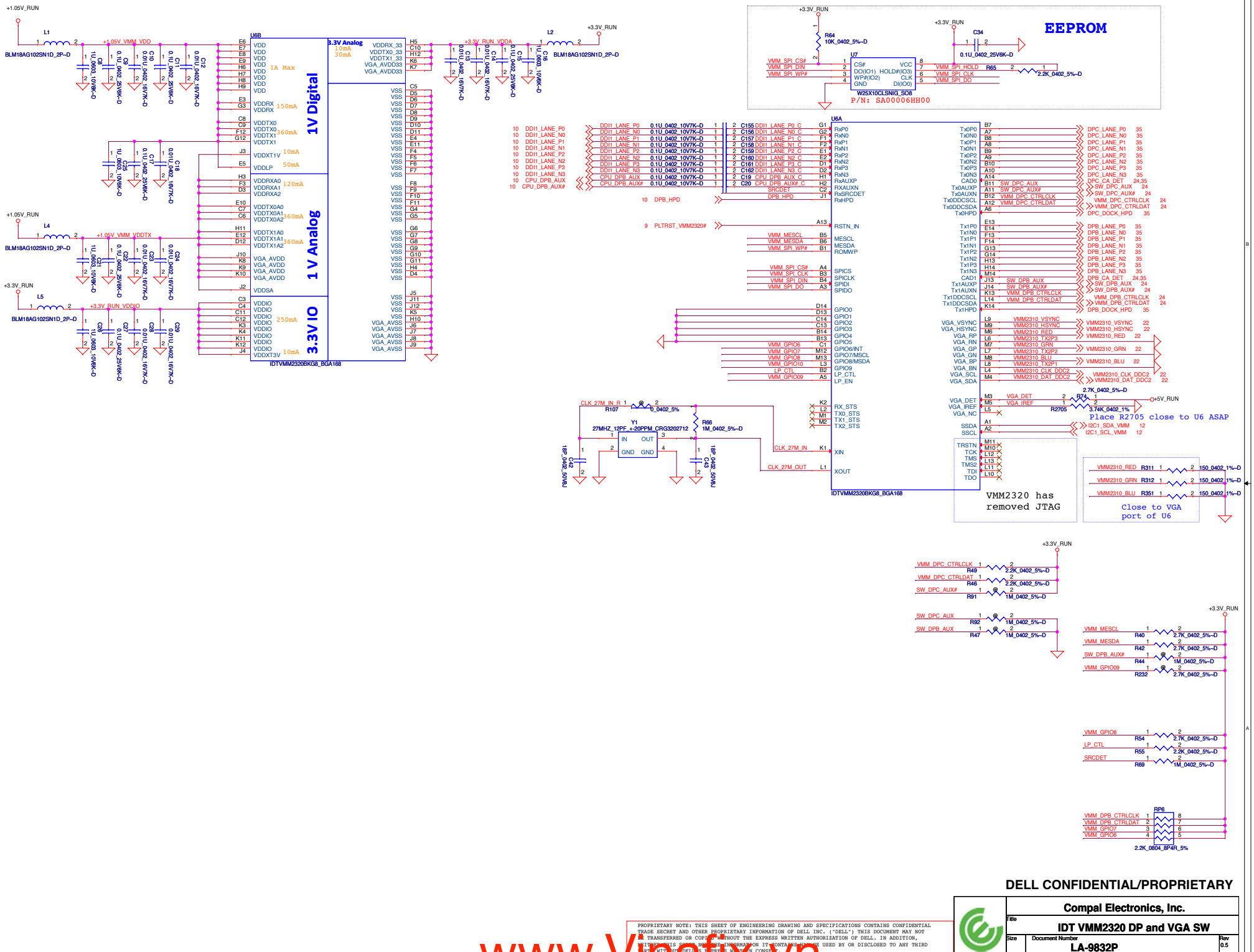
Security Classification	Compal Secret Data		
Issued Date	2011/07/15	Deciphered Date	2012/07/15

Compal Electronics, Inc.

Title: eDP to LVDS

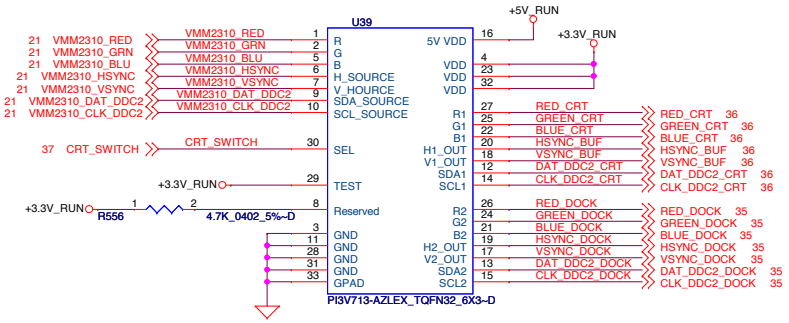
Size	Document Number	Rev
		0.5

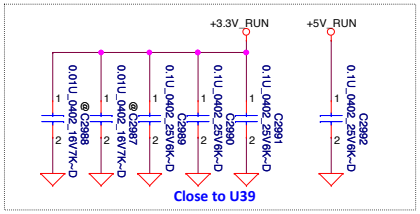
Date: Thursday, June 13, 2013 Sheet 20 of 64



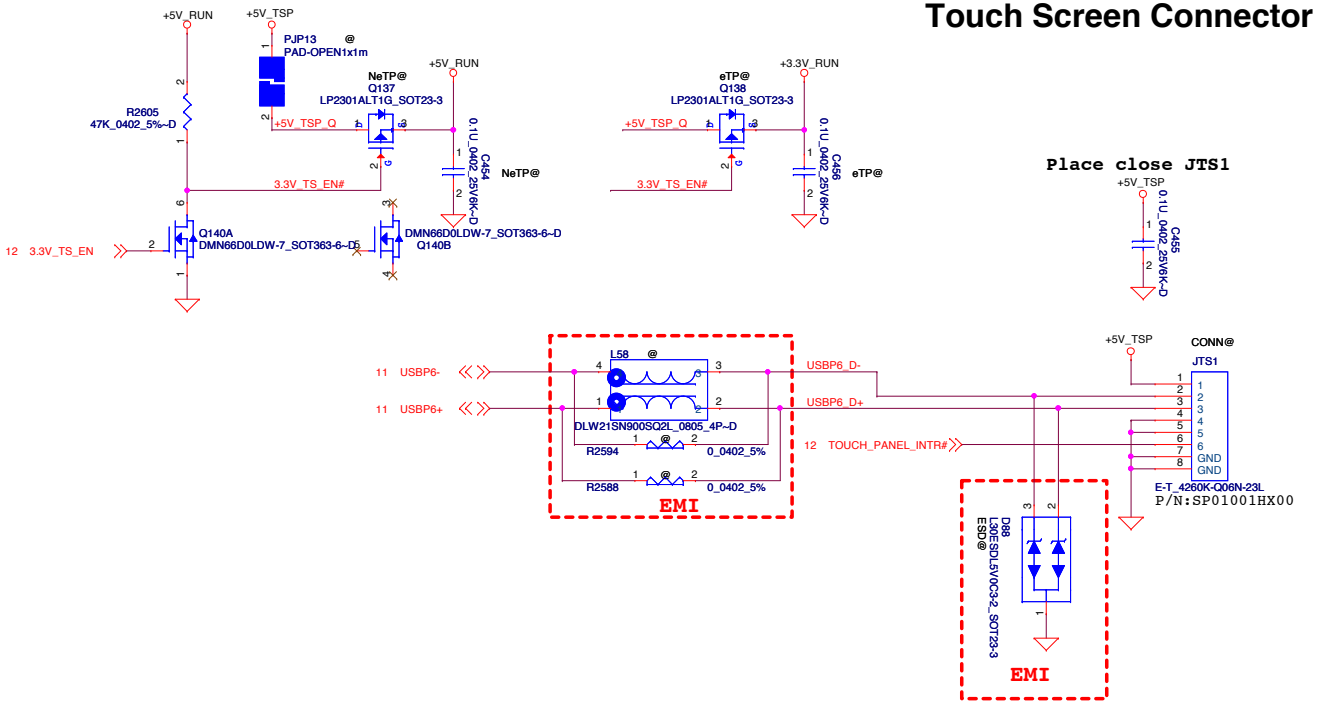
CRT SW for MB/DOCK

SEL1/SEL2	Chanel	Source
0	A=B1	MB
1	A=B2	APR/SPR



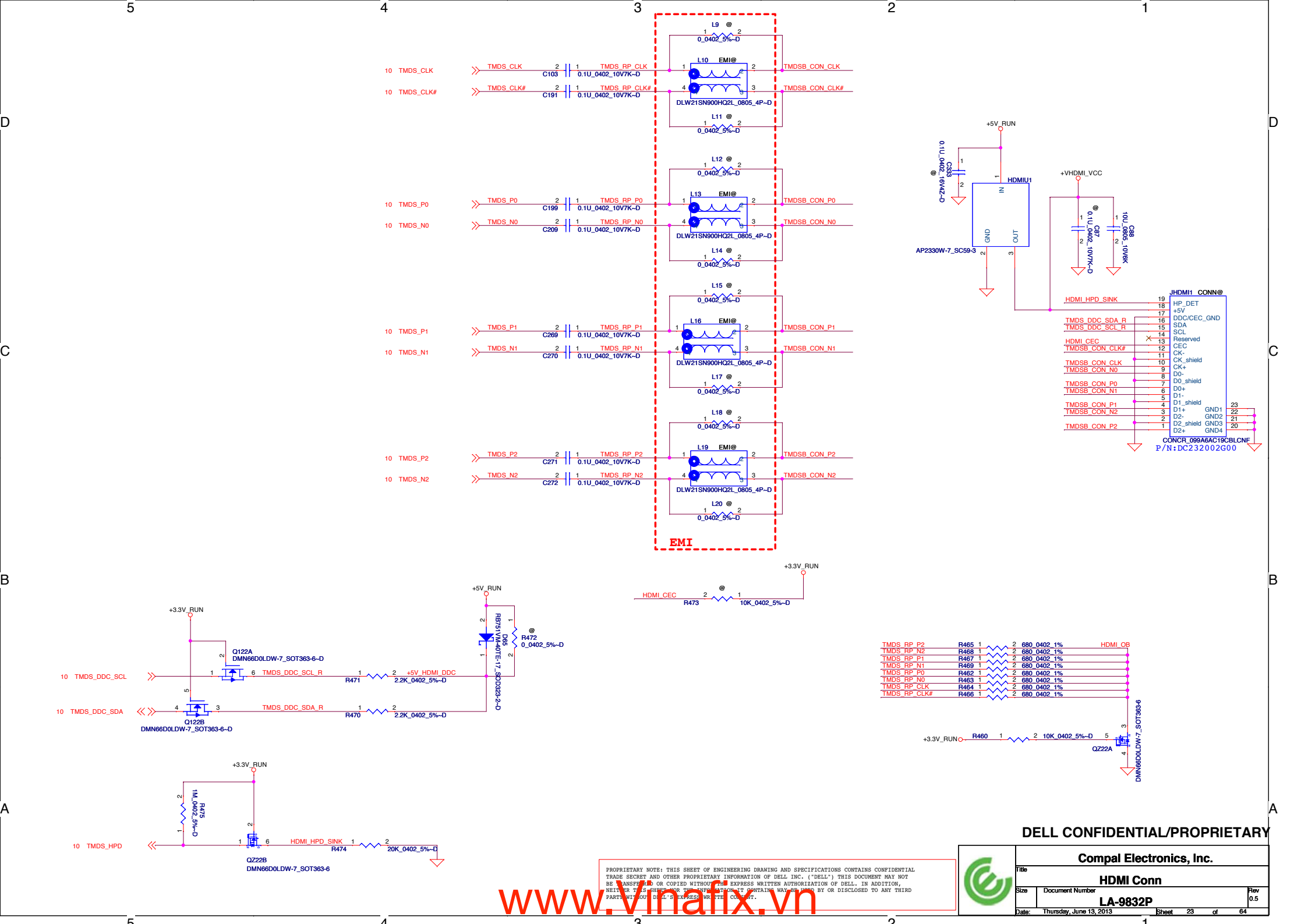


Touch Screen Connector



Security Classification	Compal Secret Data		
Issued Date	2011/07/15	Deciphered Date	2012/07/15

Compal Electronics, Inc.	
Title	CRT switch/Conn and TS
Size	Document Number
Rev	0.5
Date:	Thursday, June 13, 2013
Sheet	22 of 64



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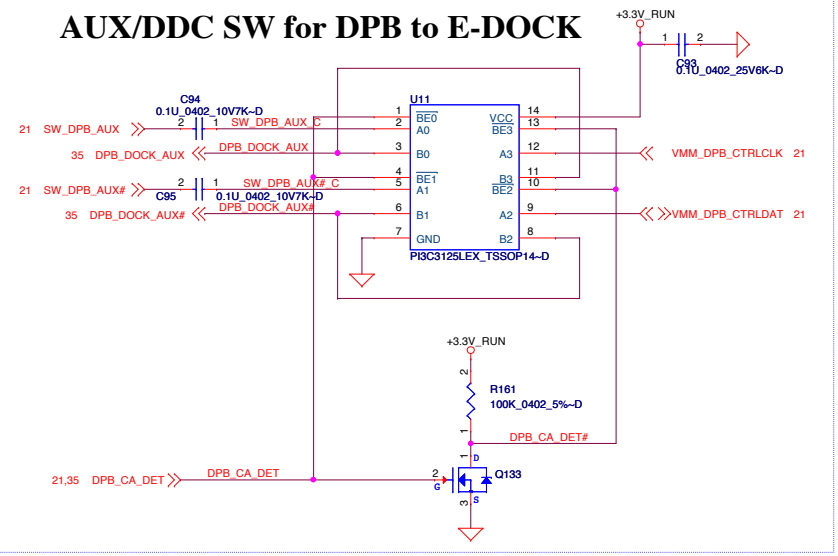
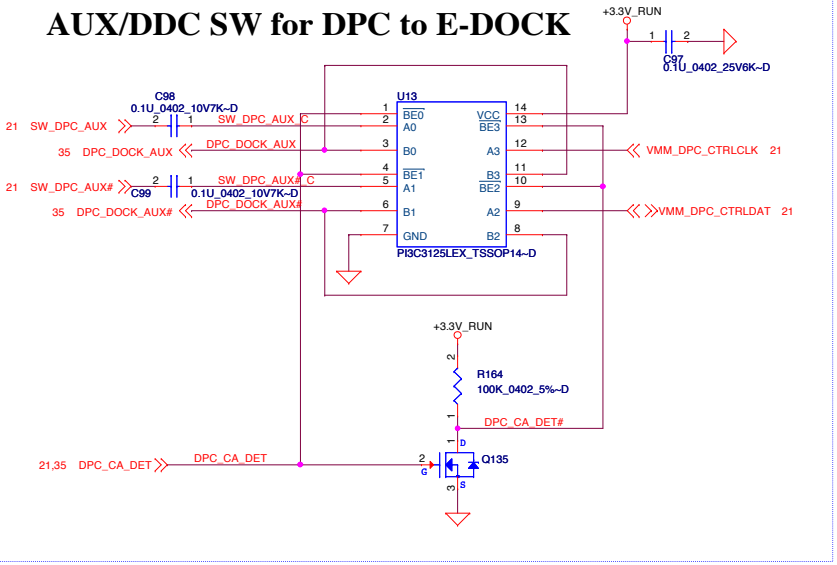
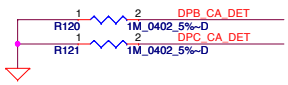
Compal Electronics, Inc.		
Title: HDMI Conn		
Size	Document Number: LA-9832P	Rev: 0.5
Date: Thursday, June 13, 2013	Sheet 23 of 64	

AUX/DDC SW for DPB to E-DOCK



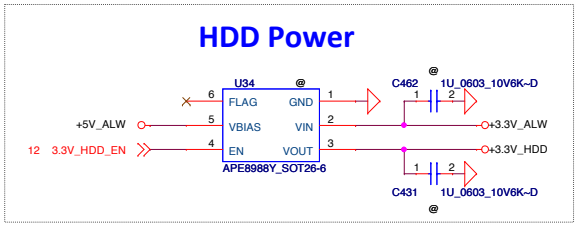
AUX/DDC SW for DPC to E-DOCK

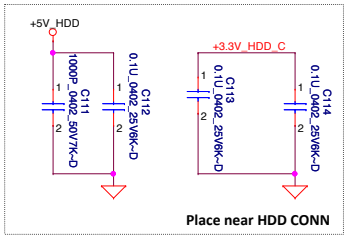


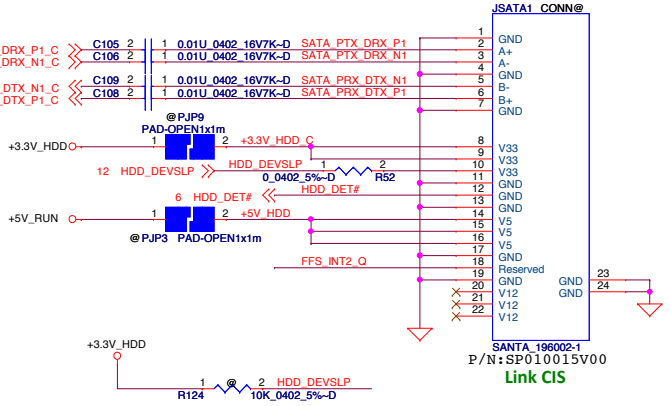


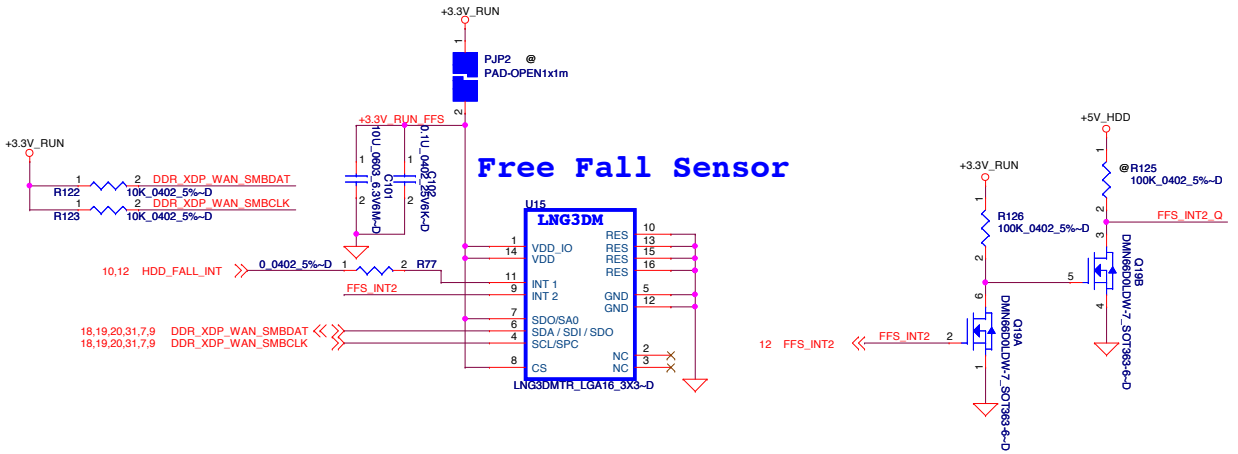
DELL CONFIDENTIAL/PROPRIETARY

Compal Electronics, Inc.		
Title: DP SW_DP125		
Size	Document Number: LA-9832P	Rev: 0.5
Date: Thursday, June 13, 2013	Sheet 24 of 64	









DELL CONFIDENTIAL/PROPRIETARY

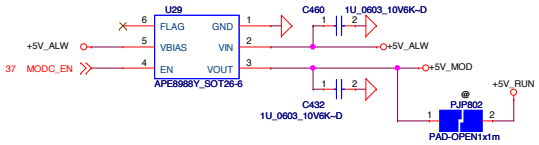
Compal Electronics, Inc.

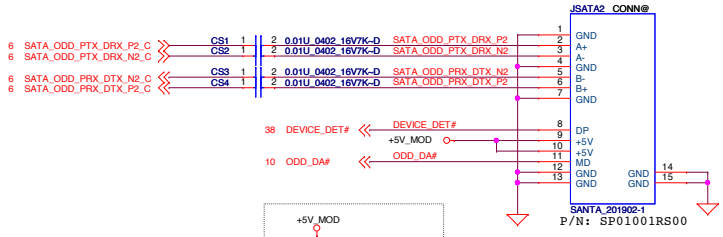
Title: HDD CONN

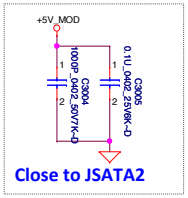
Size | Document Number: LA-9832P | Rev: 0.5

Date: Thursday, June 13, 2013 | Sheet 25 of 64

ODD power







Compal Electronics, Inc.

Title: ODD module

Size: | Document Number: LA-9832P | Rev: 0.5

Date: Thursday, June 13, 2013 | Sheet 26 of 64

Internal Speakers Header

40 mils trace keep 10 mil spacing

DVDD_IO should match with HDA Bus level

EMI

ESD

EMI Close to U17

Close to U17 pin5

Close to U17 pin6

BCLK: Audio serial data bus bit clock input/output
LRCK: Audio serial data bus word clock input/output

Place R136 close to codec

Place R142 close to codec

Analog 5V

Analog 3.3V

2A: 80 mil width

SLEEVE/RING2 : keep 40mils trace
AUD_HP_OUT_R/AUD_HP_OUT_L : keep 15mils trace

Place C134 close to Codec

Place close to Codec

Notes:
Keep PVDD supply and speaker traces routed on the DGND plane.
Keep away from AGND and other analog signals

Place closely to Pin 13.

Add for solve pop noise and detect issue

Place closely to Pin 14

Realtek feedback
Prevent the Noise from Combo Jack while system entry into S3 / S4 /S (for Global Headset)

Pay attention to Audio no sound issue.

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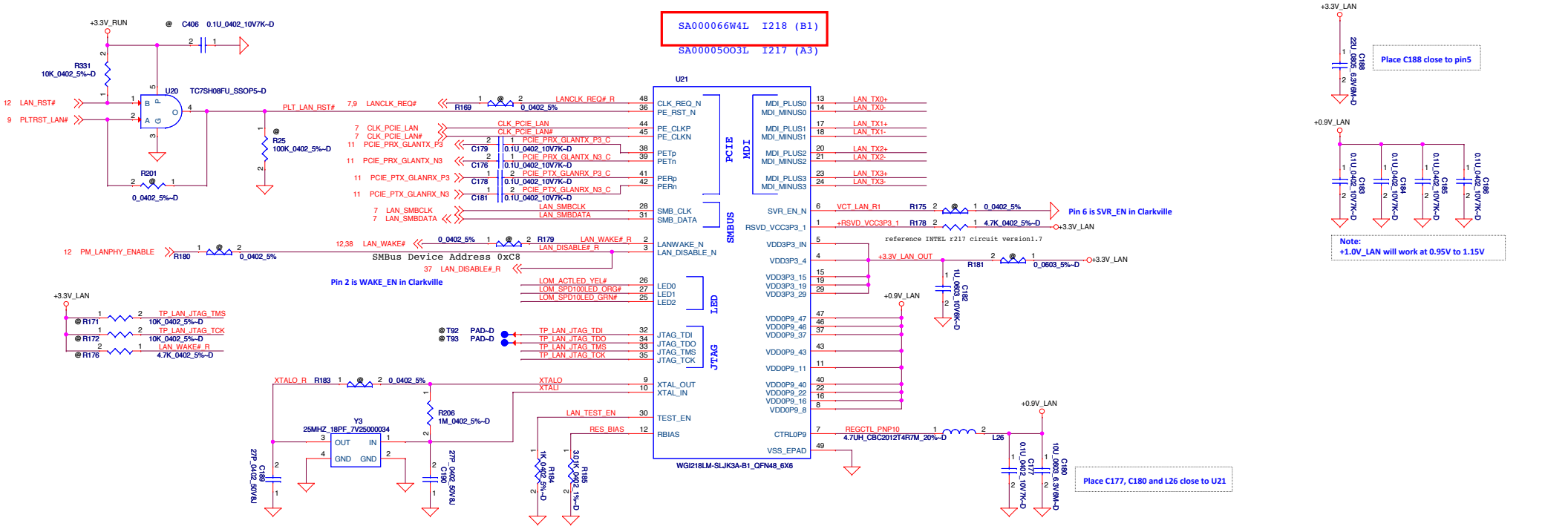
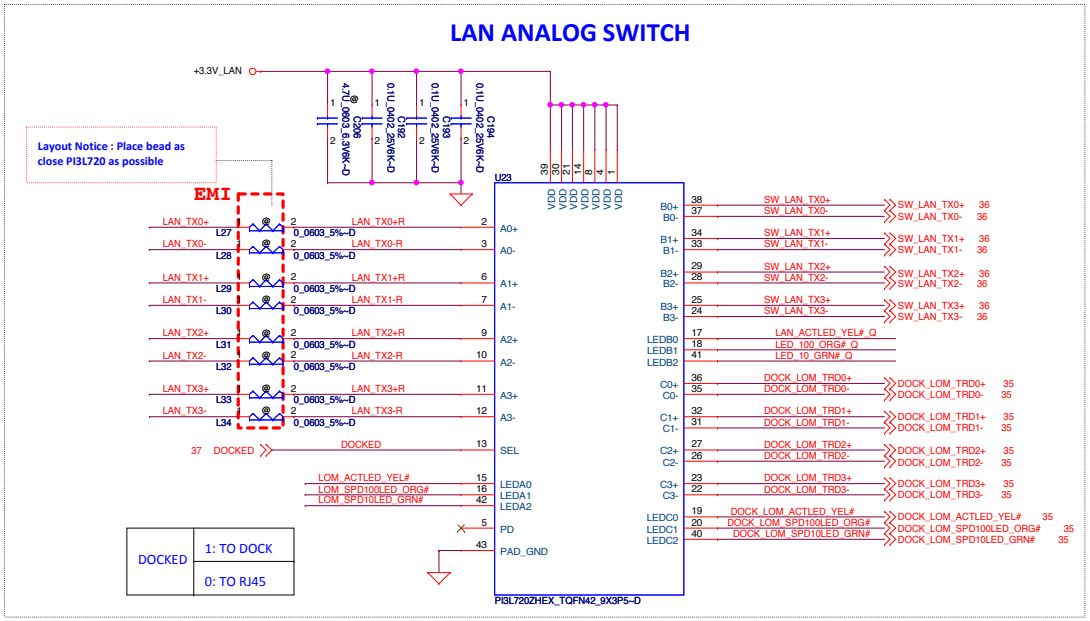
Compal Electronics, Inc.	
Title	Azalia (HD) Codec - ALC3226
Size	Document Number: LA-9832P
Rev	0.5
Date:	Friday, July 26, 2013
Sheet	27 of 64

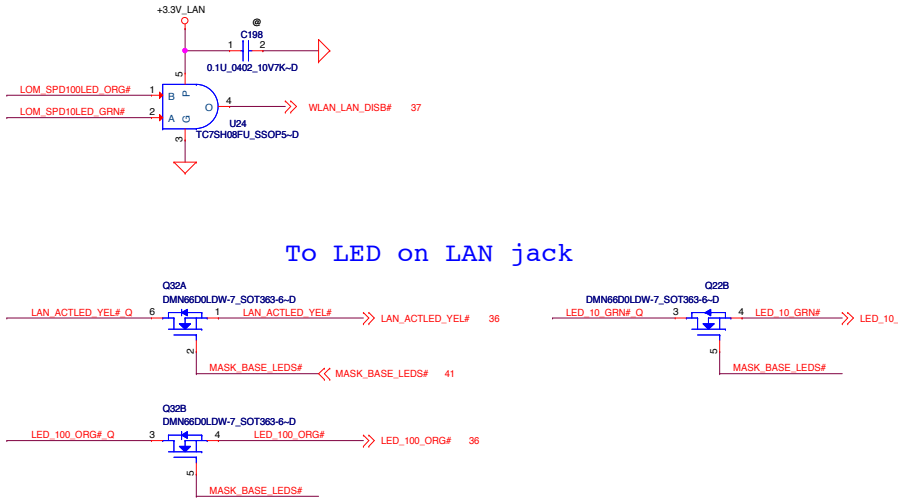
SA000066W4L I218 (B1)

SA00005OO3L I217 (A3)



LAN ANALOG SWITCH





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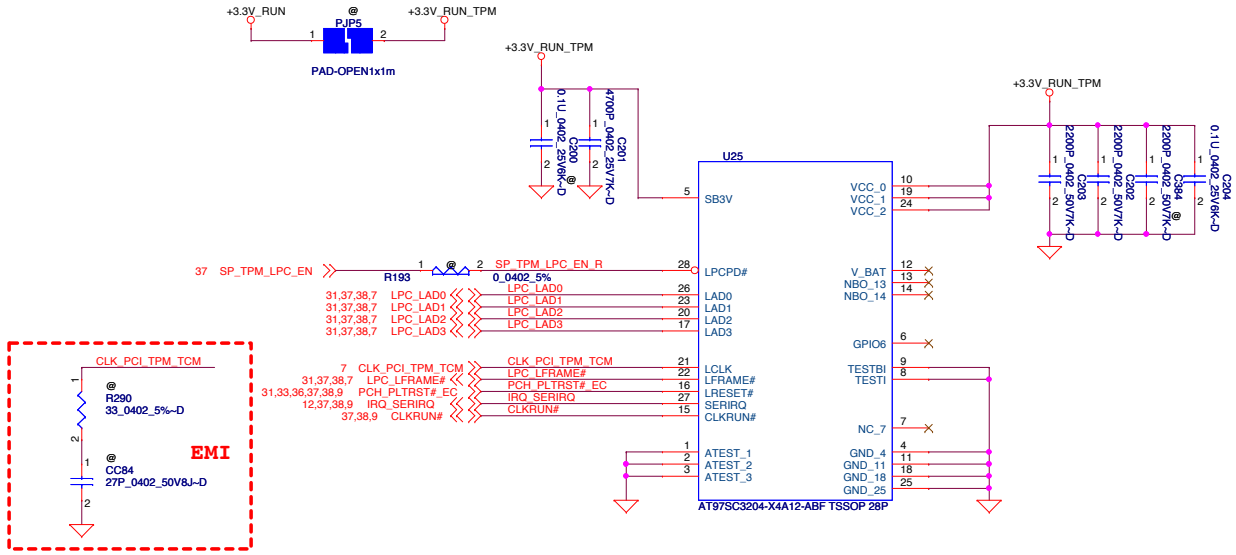
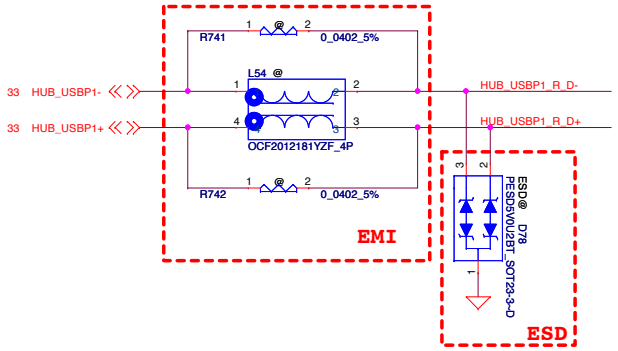
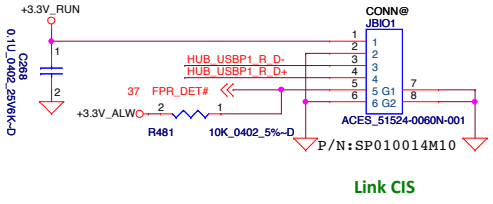
Compal Electronics, Inc.	
Title	LAN Lewisville / LAN SW
Size	Document Number: LA-9832P
Rev	0.5
Date:	Tuesday, August 13, 2013
Sheet	28 of 64

ATMEL TPM



Finger print module

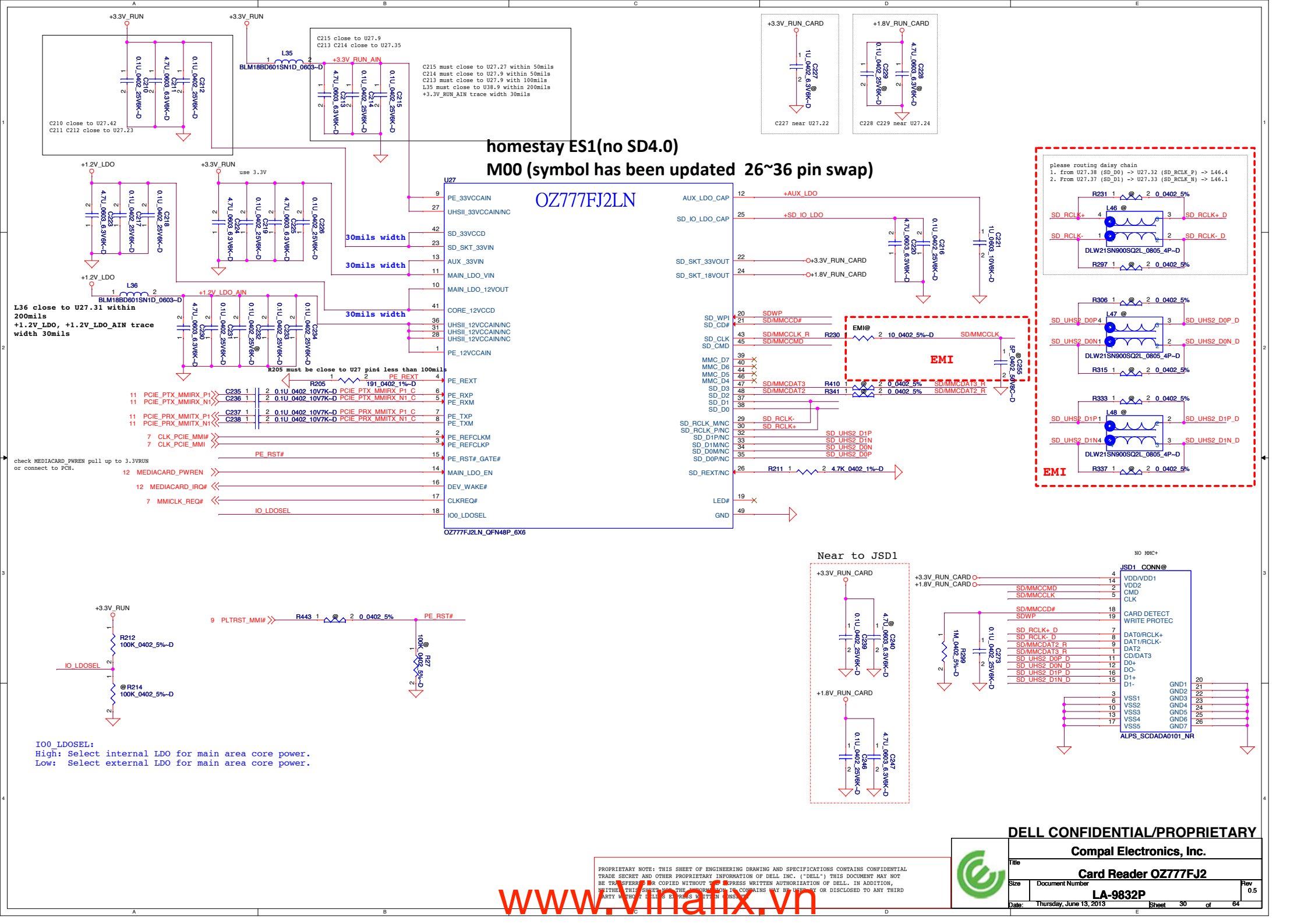




Link CIS

DELL CONFIDENTIAL/PROPRIETARY

Compal Electronics, Inc.		
Title: TPM/FP		
Size	Document Number: LA-9832P	Rev: 0.5
Date: Thursday, June 13, 2013	Sheet 29 of 64	



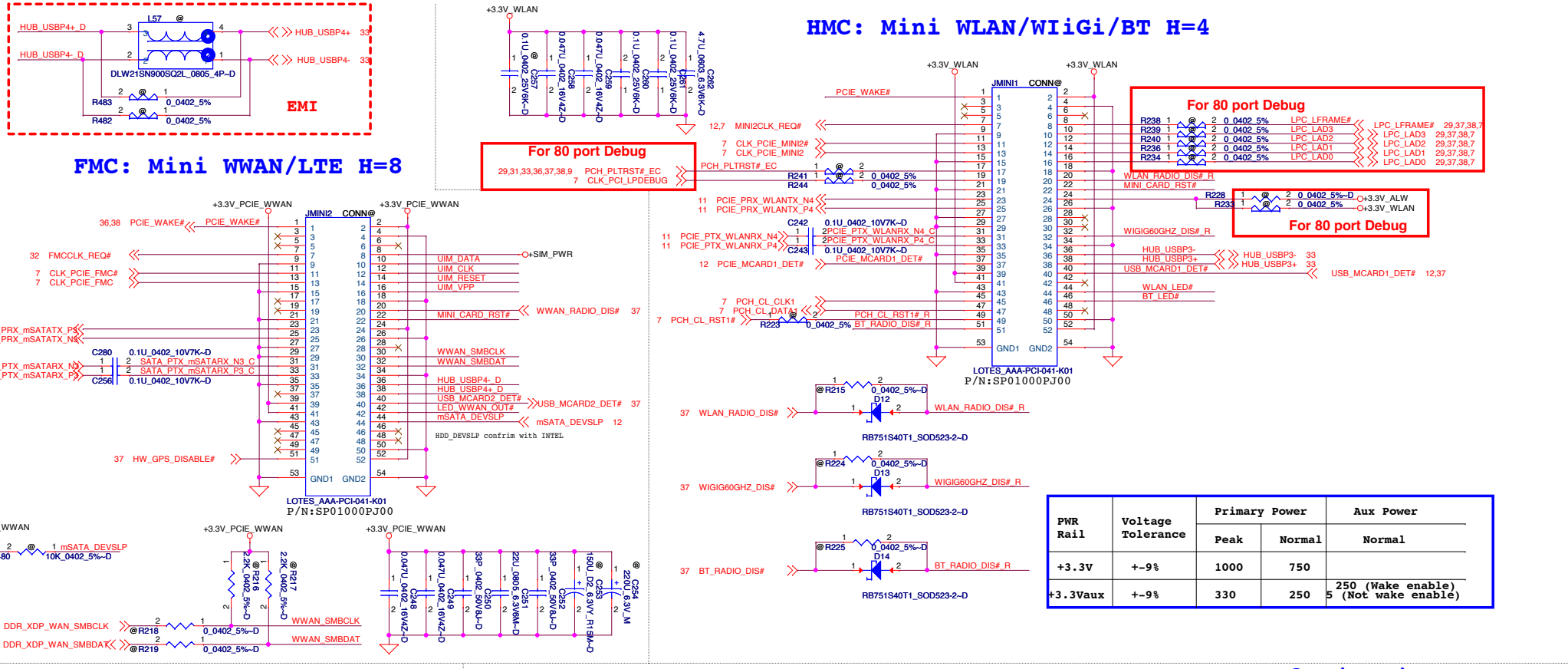
Compal Electronics, Inc.

Title: Card Reader OZ777FJ2

Size | Document Number: LA-9832P | Rev: 0.5

Date: Thursday, June 13, 2013 | Sheet 30 of 64

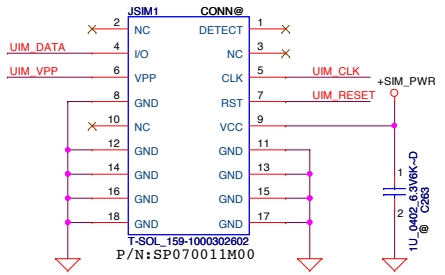
HMC: Mini WLAN/WIiGi/BT H=4



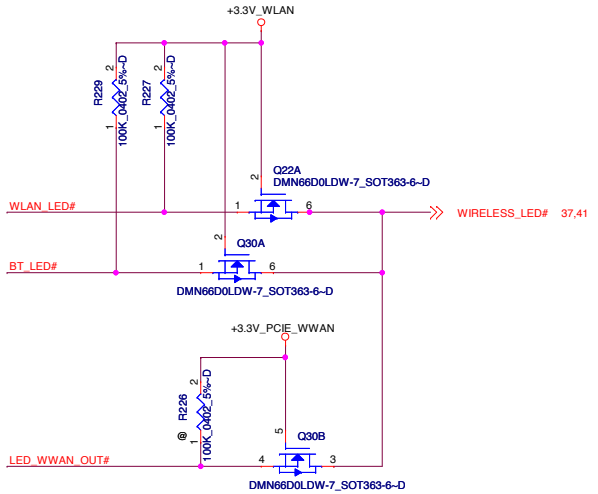
PWR Rail	Voltage Tolerance	Primary Power		Aux Power
		Peak	Normal	Normal
+3.3V	+-9%	1000	750	
+3.3Vaux	+-9%	330	250	250 (Wake enable) 5 (Not wake enable)

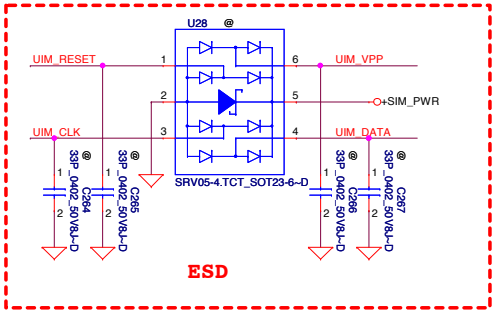
FMC: Mini WWAN/LTE H=8

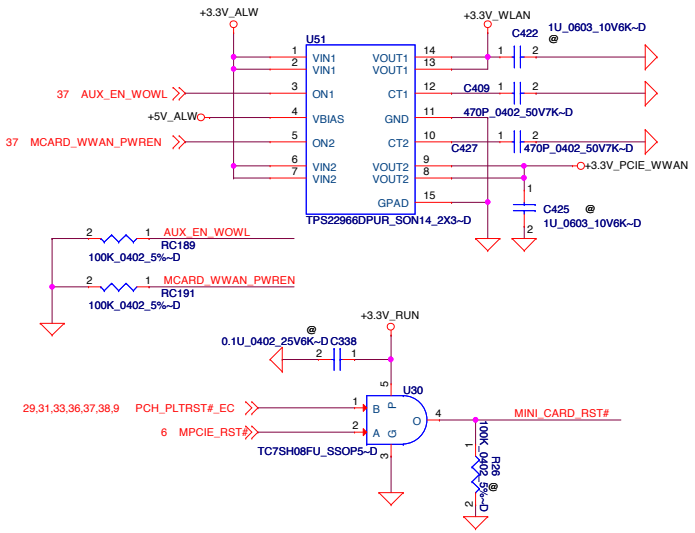
uSIM Card Push-Push



LED control circuit







Compal Electronics, Inc.

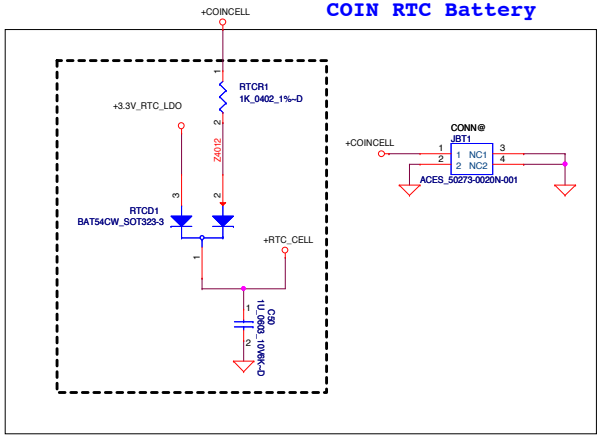
Title: Mini Card/SIM Card

Size | Document Number: LA-9832P | Rev: 0.5

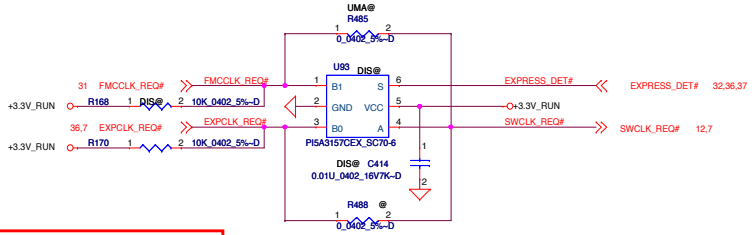
Date: Thursday, June 13, 2013 | Sheet 31 of 64

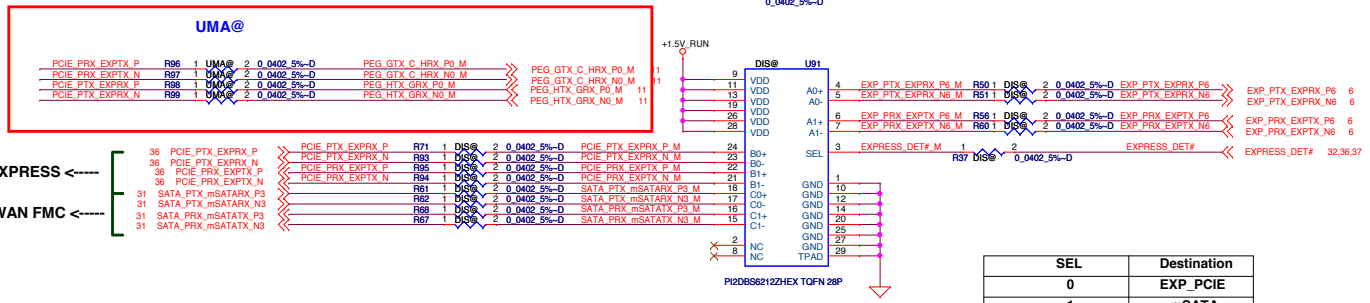
EXP/FMC PCIe clock/REQ Switch

COIN RTC Battery



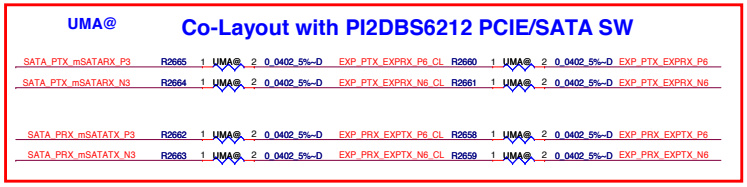
B \ S	EXPRESS_DET#
EXPCLK_REQ#	0
FMCCLK_REQ#	1





SEL	Destination
0	EXP_PCIE
1	mSATA

Co-Layout with PI2DBS6212 PCIE/SATA SW

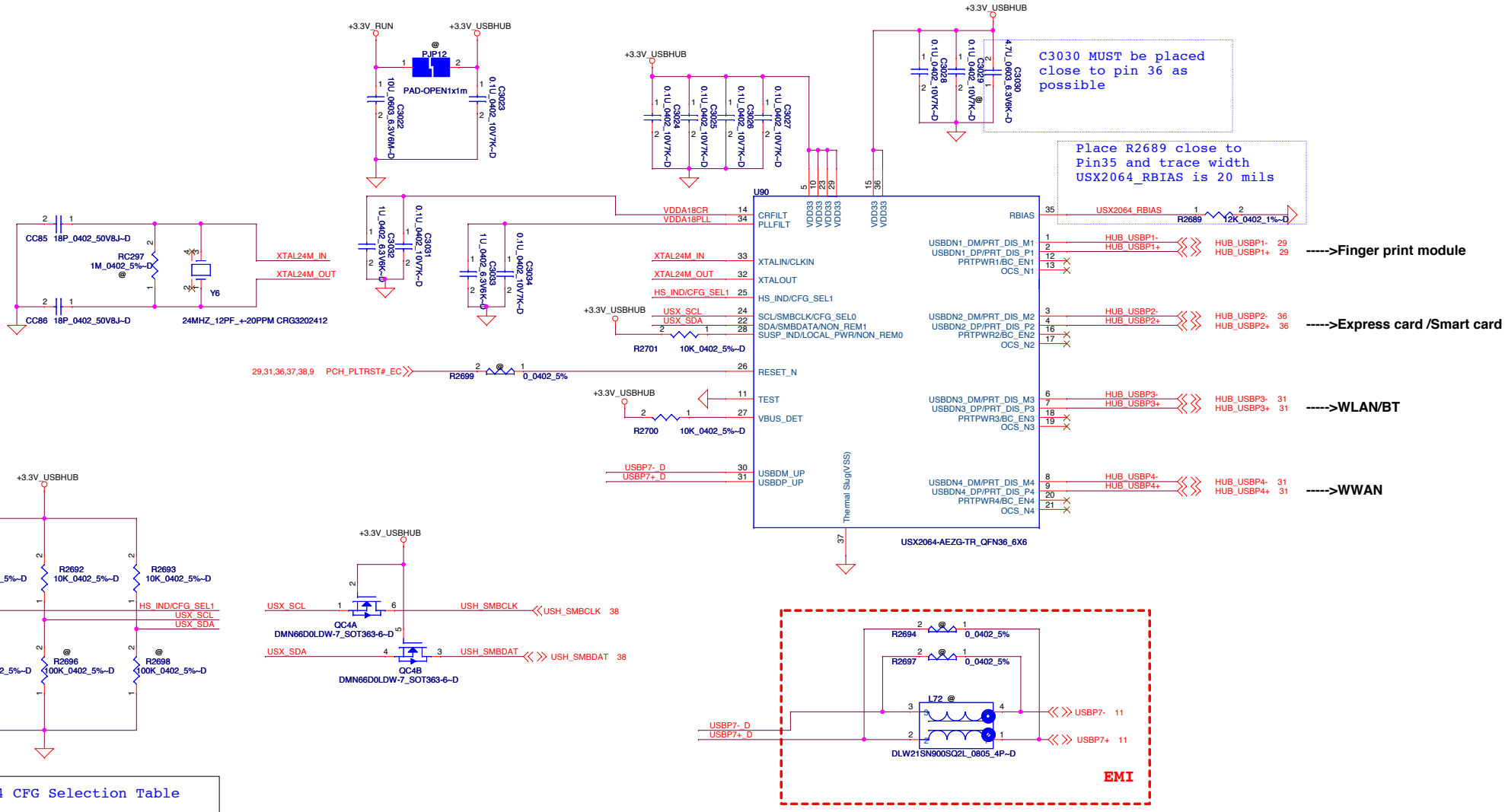


Compal Electronics, Inc.

Title: RTC Batt/PCIE_SATA SW

Size: | Document Number: LA-9832P | Rev: 0.5

Date: Thursday, June 13, 2013 | Sheet 32 of 64



USX2064 CFG Selection Table		
CFG_SEL[0] / CFG_SEL[1]	0	1
0	Default	SMBus slave device
1	Bus-powered operation	I2C EEPROM

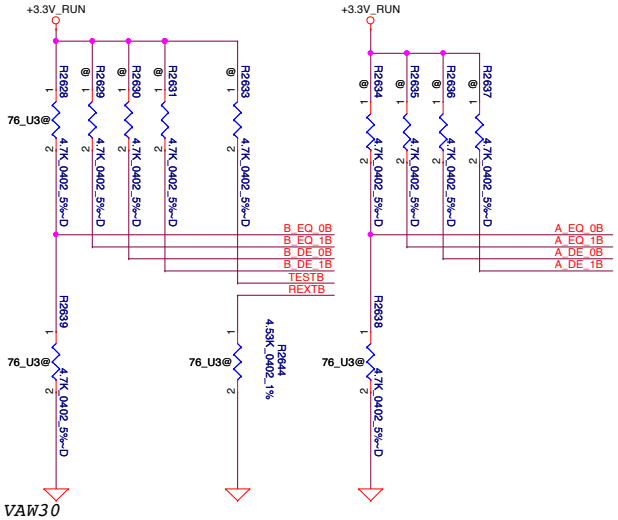
Compal Electronics, Inc.

Title: USB2.0 HUB-USX2064

Size | Document Number: LA-9832P | Rev: 0.5

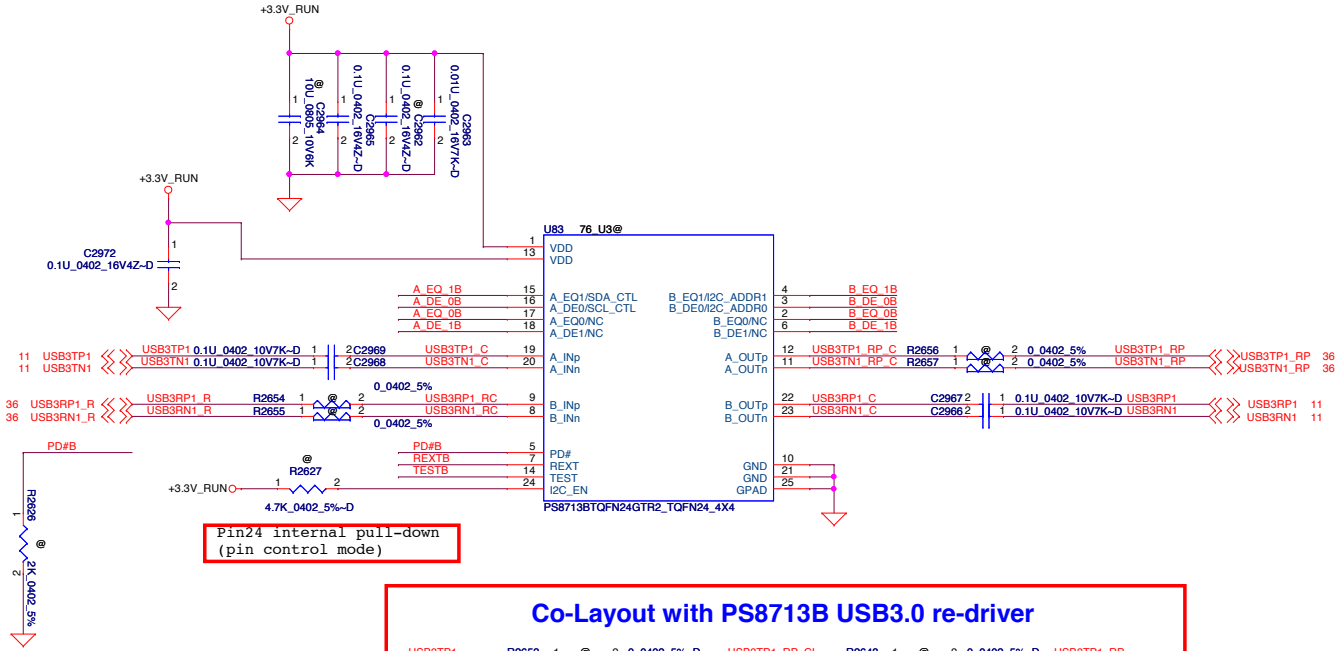
Date: Monday, June 17, 2013 | Sheet 33 of 64

USB 3.0 Re-driver for IOB



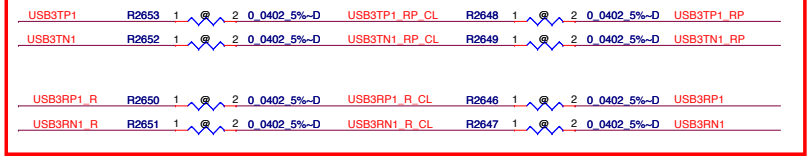
ONLY FOR VAW30

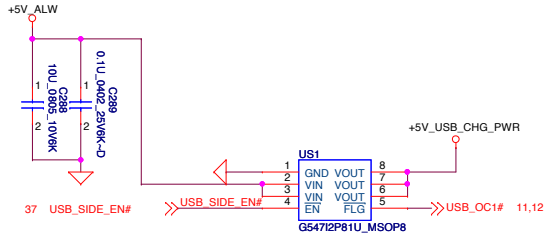
Pericom (Main) SA00006WV00	Parade (2nd) SA00005OR20
POP:R2638, R2639	POP:R2628
POP:R2644 (SD00000U200)	POP:R2644 (SD034453180)
A channel EQ 3db DE -3.5db B channel EQ 3db DE -3.5db	A channel EQ 9.5db DE 3.5db B channel EQ 13db DE 3.5db

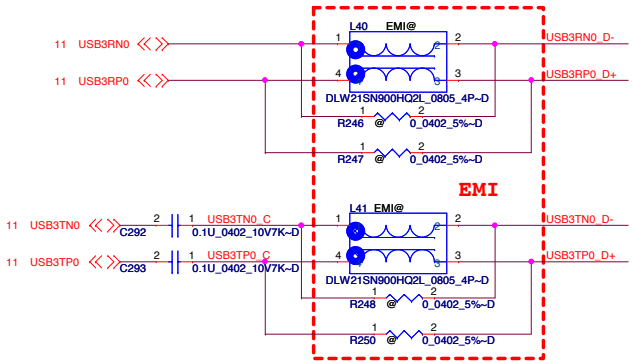


Pin24 internal pull-down
(pin control mode)

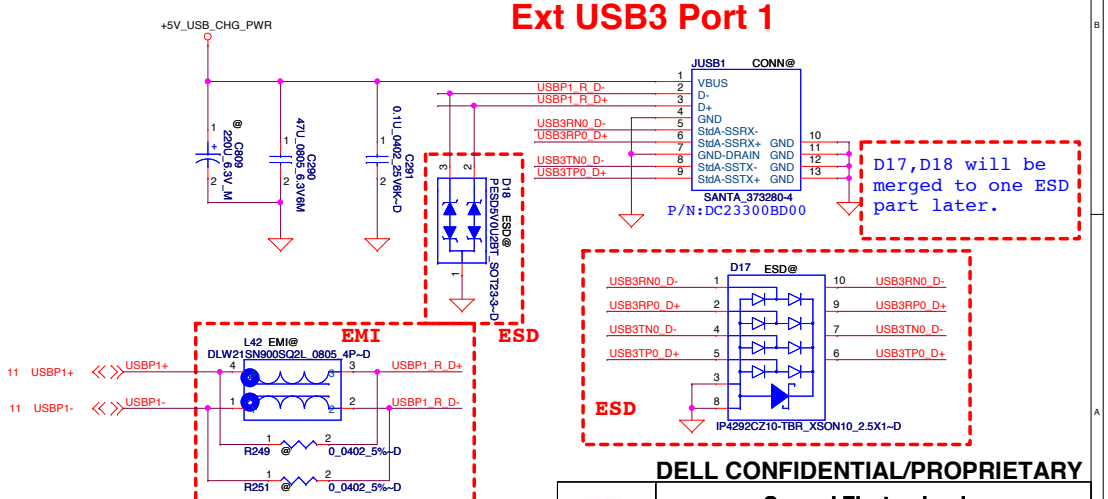
Co-Layout with PS8713B USB3.0 re-driver





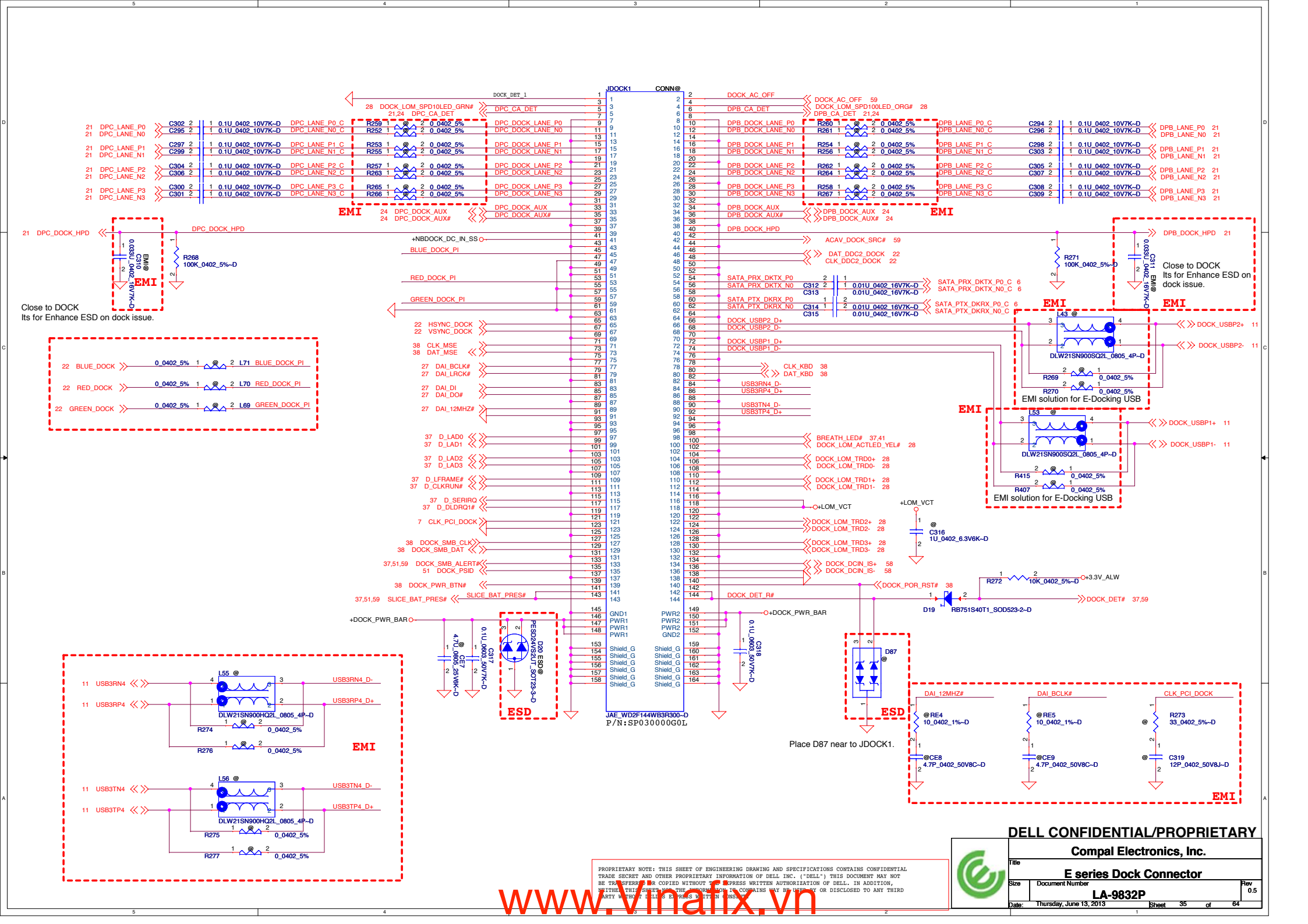


Ext USB3 Port 1



DELL CONFIDENTIAL/PROPRIETARY

Compal Electronics, Inc.	
Title	USB on MB/Redriver
Size	Document Number: LA-9832P
Rev	0.5
Date: Friday, August 30, 2013	Sheet 34 of 64



DELL CONFIDENTIAL/PROPRIETARY

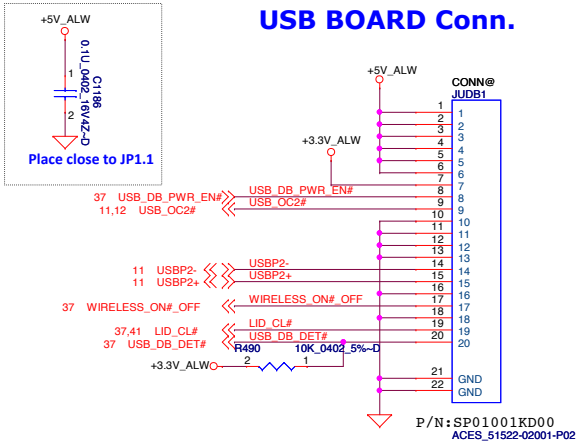
Compal Electronics, Inc.

Title: E series Dock Connector

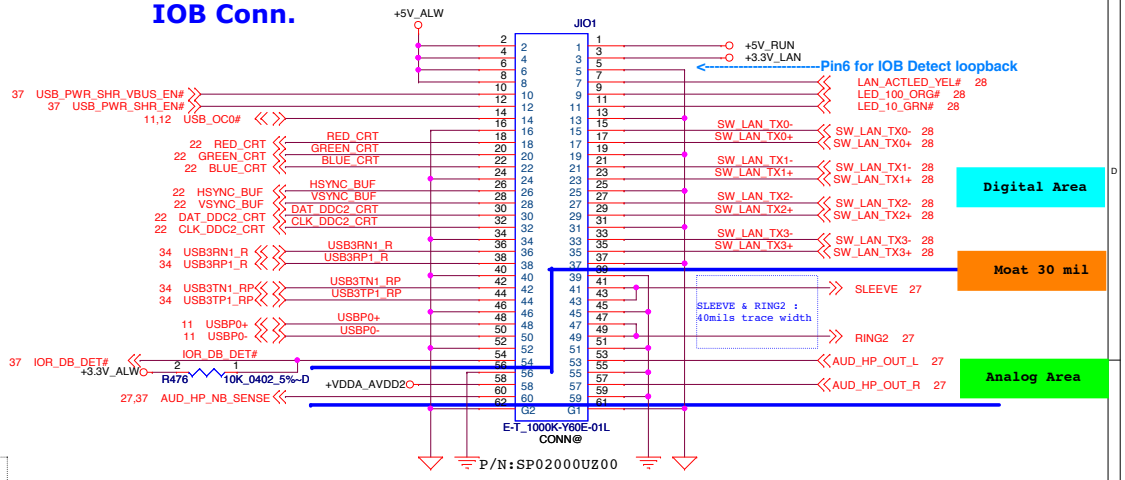
Size | Document Number: LA-9832P | Rev: 0.5

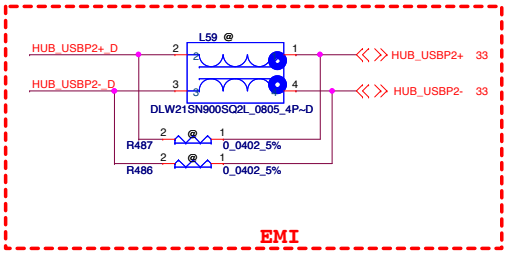
Date: Thursday, June 13, 2013 | Sheet 35 of 64

USB BOARD Conn.

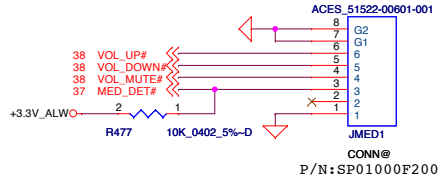


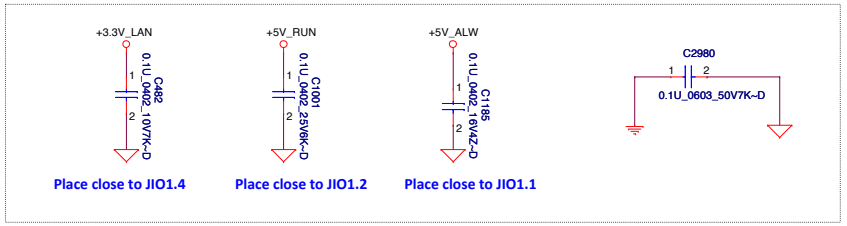
IOB Conn.



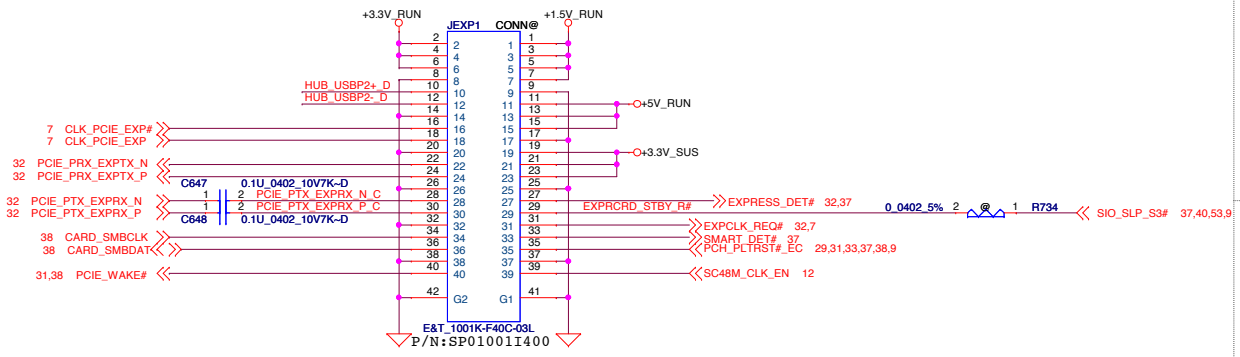


MEDIA BOARD Conn.

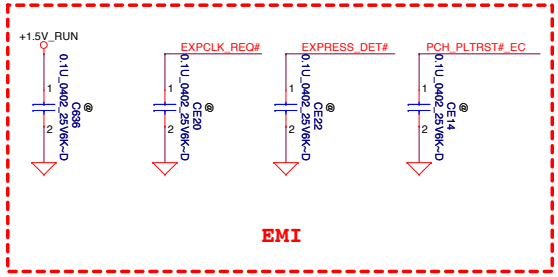


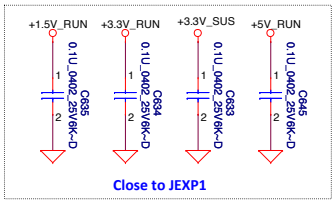


Express/Smart Card Conn.

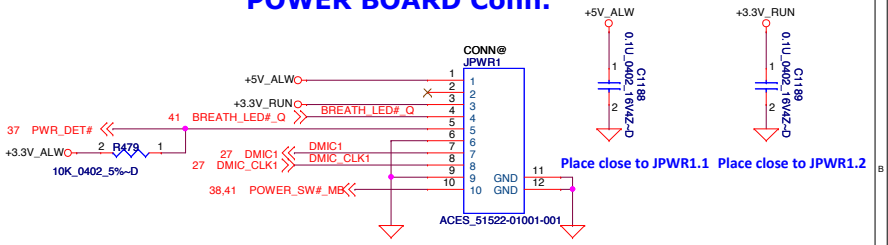


Link CIS

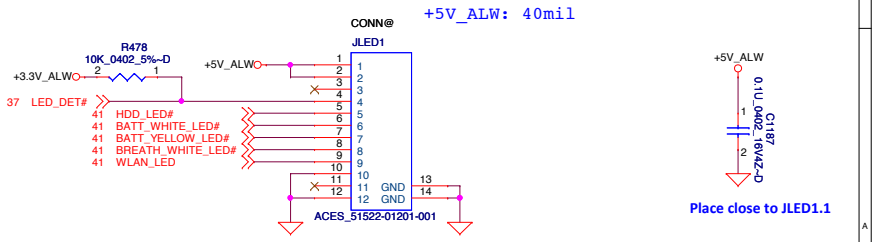




POWER BOARD Conn.



LED EXTERNAL BOARD Conn.

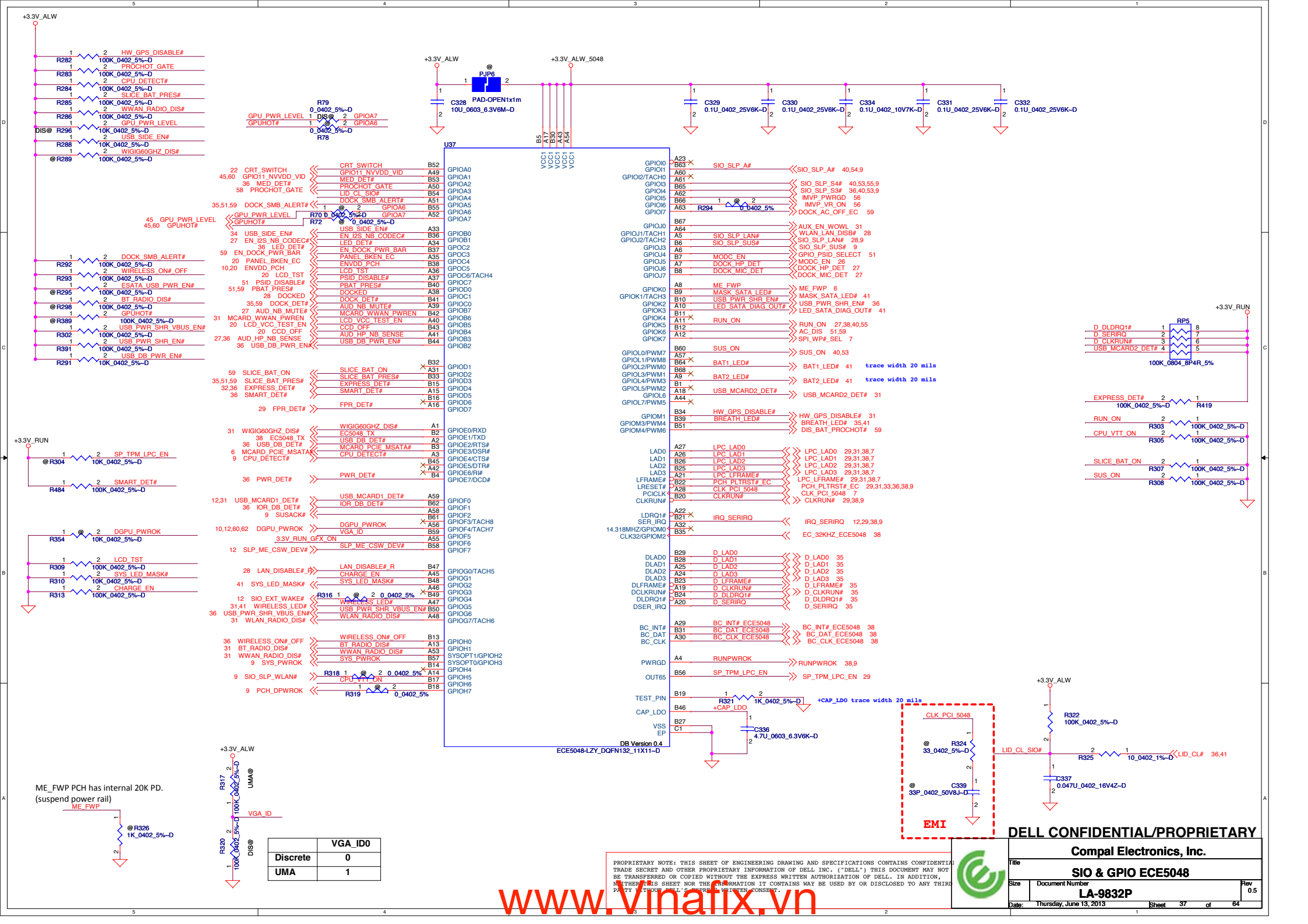


Compal Electronics, Inc.

Title: I/O Conn

Size | Document Number: LA-9832P | Rev: 0.5

Date: Thursday, August 22, 2013 | Sheet 36 of 64


+3.3V_ALW
+3.3V_ALW_5048
+3.3V_RUN
U37
DB Version 0.4
ECE5048-LZY_DQFN132_11X11~D
ME_FWP PCH has internal 20K PD.
(suspend power rail)
VGA_ID
Discrete 0
UMA 1
EMI
DELL CONFIDENTIAL/PROPRIETARY
Compal Electronics, Inc.
SIO & GPIO ECE5048
LA-9832P
Rev 0.5
Thursday, June 13, 2013
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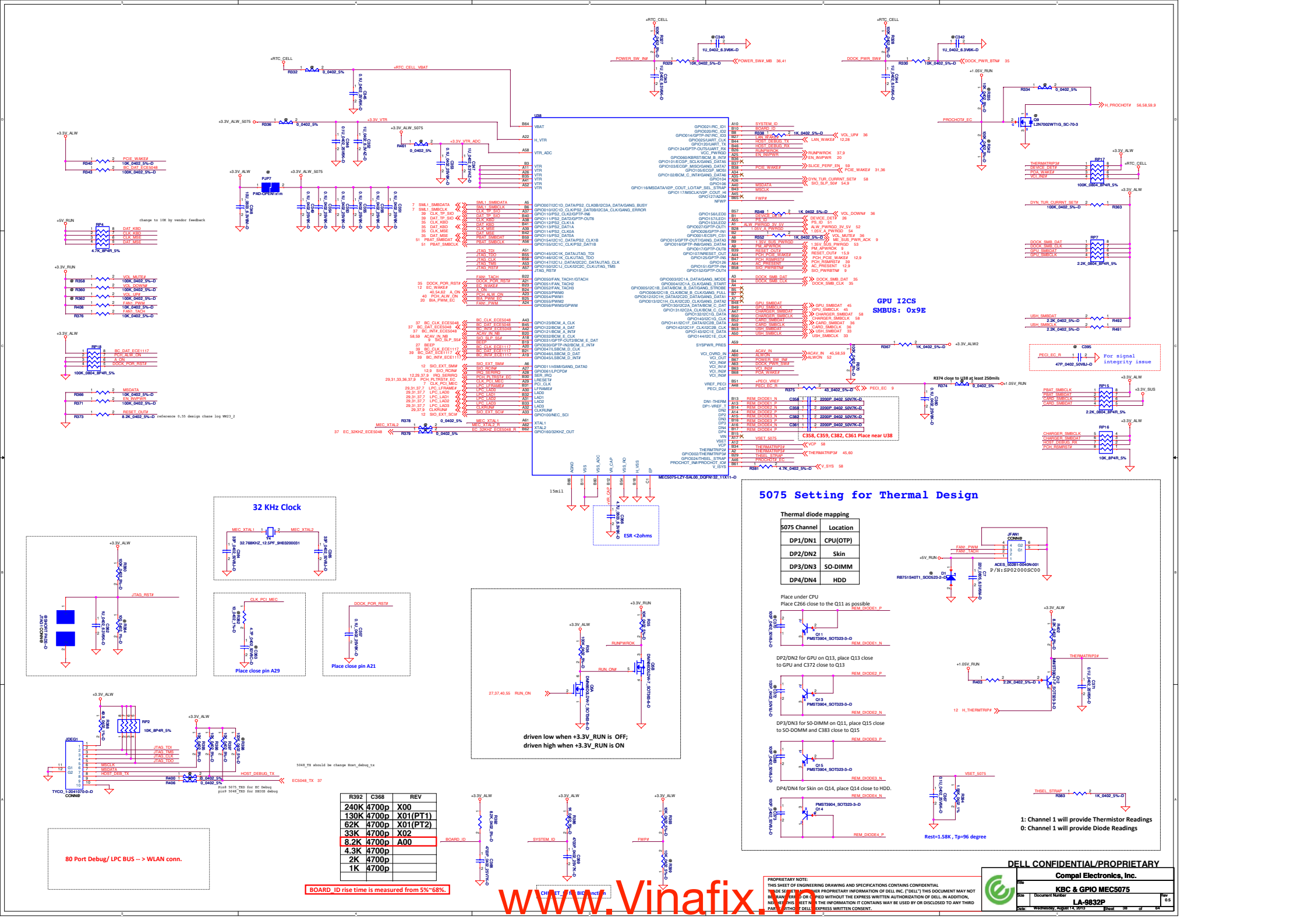
GPU I2CS
SMBUS: 0x9E
5075 Setting for Thermal Design
Thermal diode mapping
5075 Channel | Location
DP1/DN1 | CPU(OTP)
DP2/DN2 | Skin
DP3/DN3 | SO-DIMM
DP4/DN4 | HDD
Place under CPU
Place C266 close to the Q11 as possible
DP2/DN2 for GPU on Q13, place Q13 close to GPU and C372 close to Q13
DP3/DN3 for S0-DIMM on Q11, place Q15 close to SO-DOMM and C383 close to Q15
DP4/DN4 for Skin on Q14, place Q14 close to HDD.
Rest=1.58K , Tp=96 degree
1: Channel 1 will provide Thermistor Readings
0: Channel 1 will provide Diode Readings
32 KHz Clock
32.768KHZ_12.5PF_9H03200031
ESR <2ohms
C358, C359, C382, C361 Place near U38
Place close pin A29
Place close pin A21
driven low when +3.3V_RUN is OFF;
driven high when +3.3V_RUN is ON
80 Port Debug/ LPC BUS -- > WLAN conn.
BOARD_ID rise time is measured from 5%~68%.
R392 | C368 | REV
240K | 4700p | X00
130K | 4700p | X01(PT1)
62K | 4700p | X01(PT2)
33K | 4700p | X02
8.2K | 4700p | A00
4.3K | 4700p
2K | 4700p
1K | 4700p
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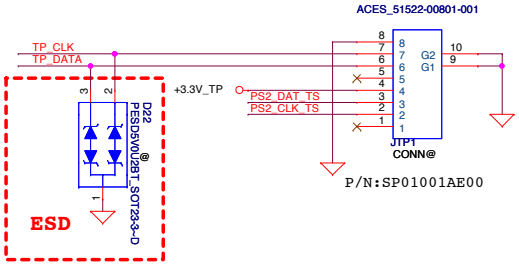
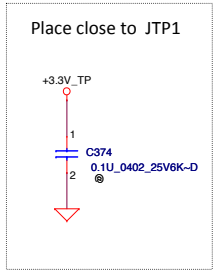
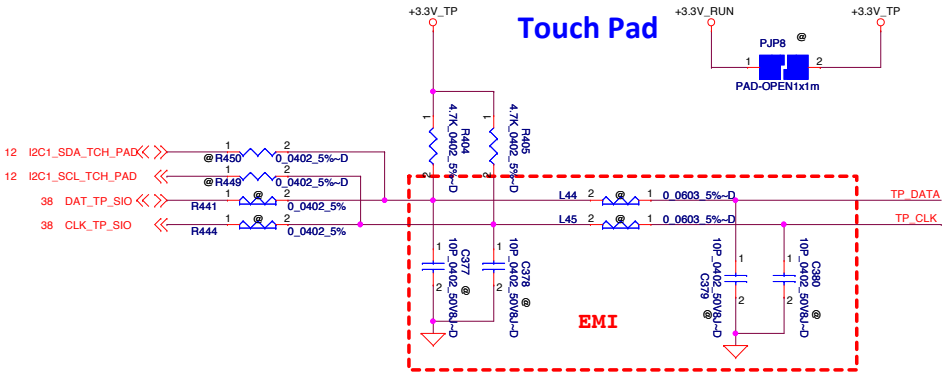
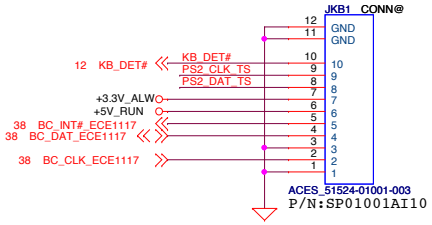
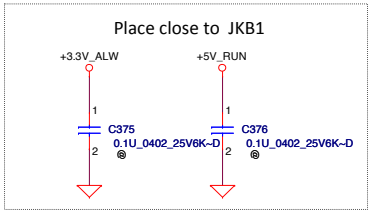
Compal Electronics, Inc.
KBC & GPIO MEC5075
LA-9832P
Wednesday, August 14, 2013
www.Vinafix.vn

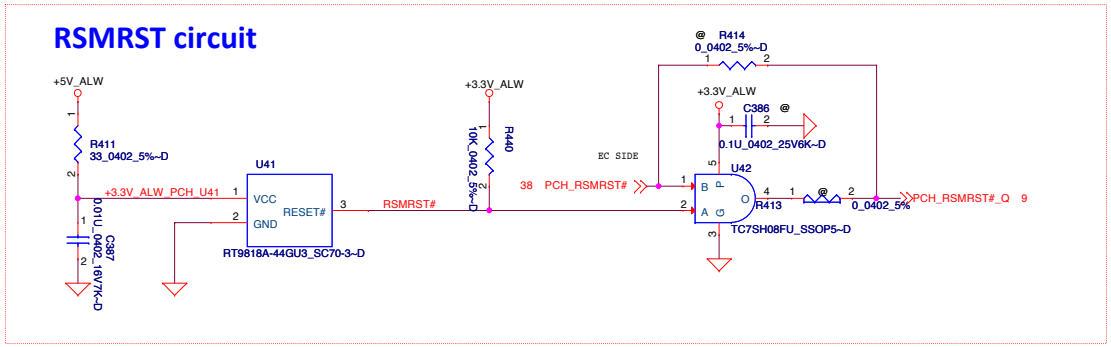












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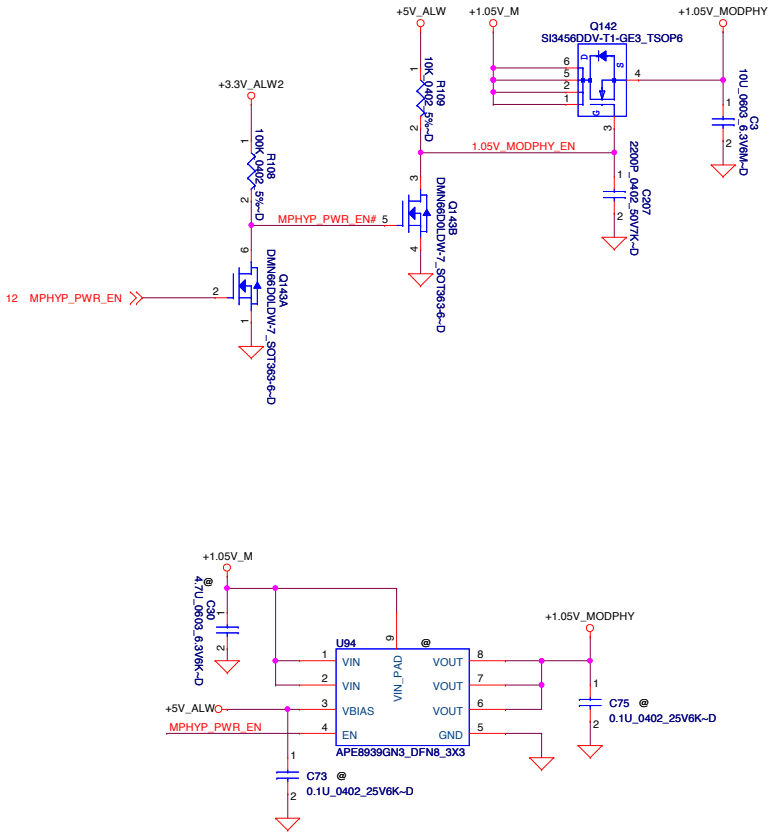
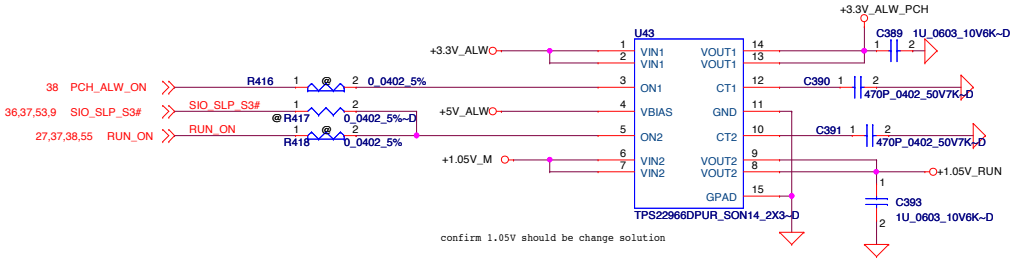
Compal Electronics, Inc.		
Title: KB/TP/RSMRST		
Size	Document Number: LA-9832P	Rev: 0.5
Date: Thursday, June 13, 2013	Sheet 39 of 64	

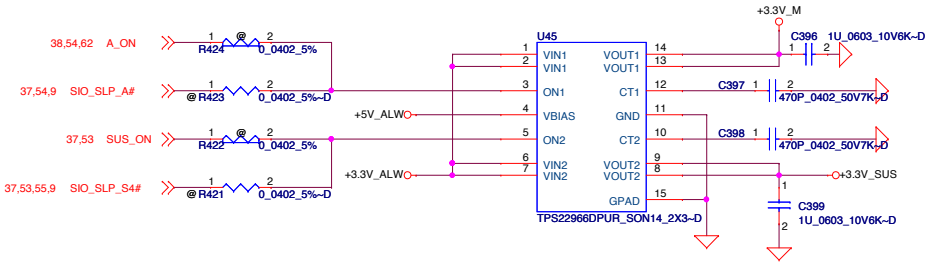
+1.05V_MODPHY source



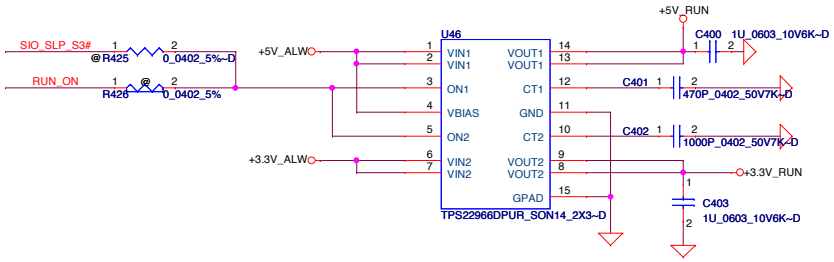
+3.3V_ALW_PCH/+1.05V_RUN source



+3.3V_SUS/+3.3V_M source



+3.3V_RUN/+5V_RUN source



Compal Electronics, Inc.

Title: POWER CONTROL

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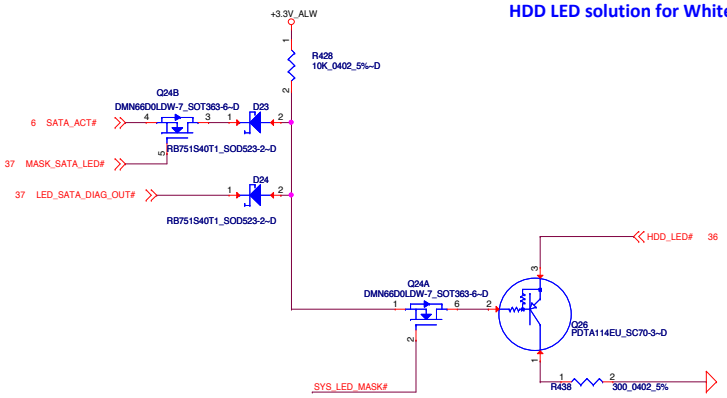
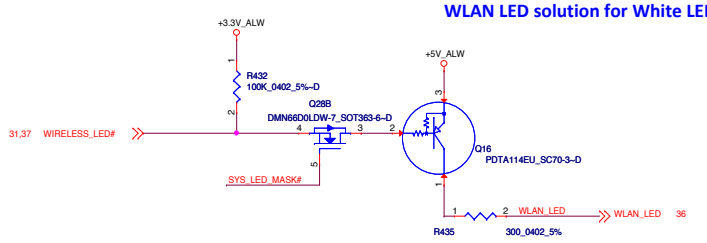
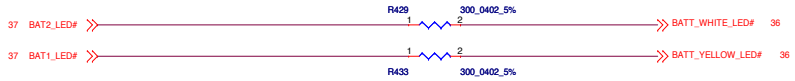
HDD LED solution for White LED



WLAN LED solution for White LED



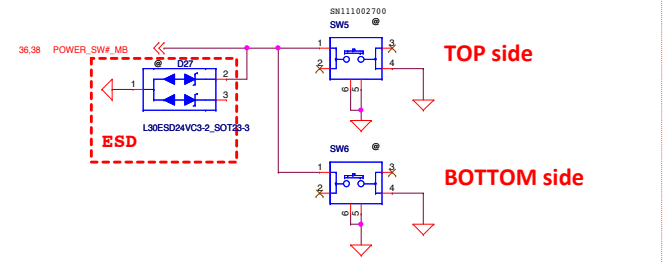
Battery LED



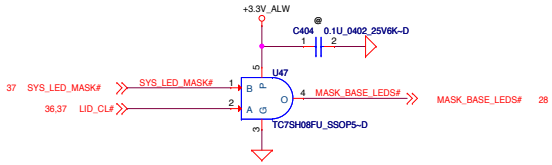
Breath LED

POWER & INSTANT ON SWITCH

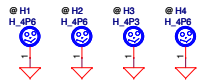
Need to change as ALW17 power switch.



Lid has beed moved to DB.



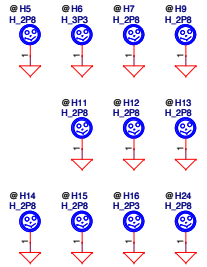
CPU stand-off hole :
Φ4.3mm X 1, Φ4.6mm X 3



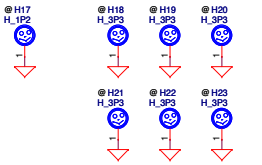
Screw hole Φ5.0mm X 1

Screw hole Φ3.3mmx2.8mm X 1

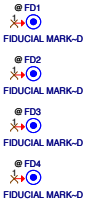
Screw hole Φ3.3mm X 1, Φ2.8mm X 14, Φ2.3mm X 1



Stand-off hole Φ3.3mm X 7,Φ1.2mm X 1



Fiducial Mark



LED Circuit Control Table

	SYS_LED_MASK#	LID_CL#
Mask All LEDs (Sniffer Function)	0	X
Mask Base MB LEDs (Lid Closed)	1	0
Do not Mask LEDs (Lid Opened)	1	1

Compal Electronics, Inc.

Title: PAD & ME & LED

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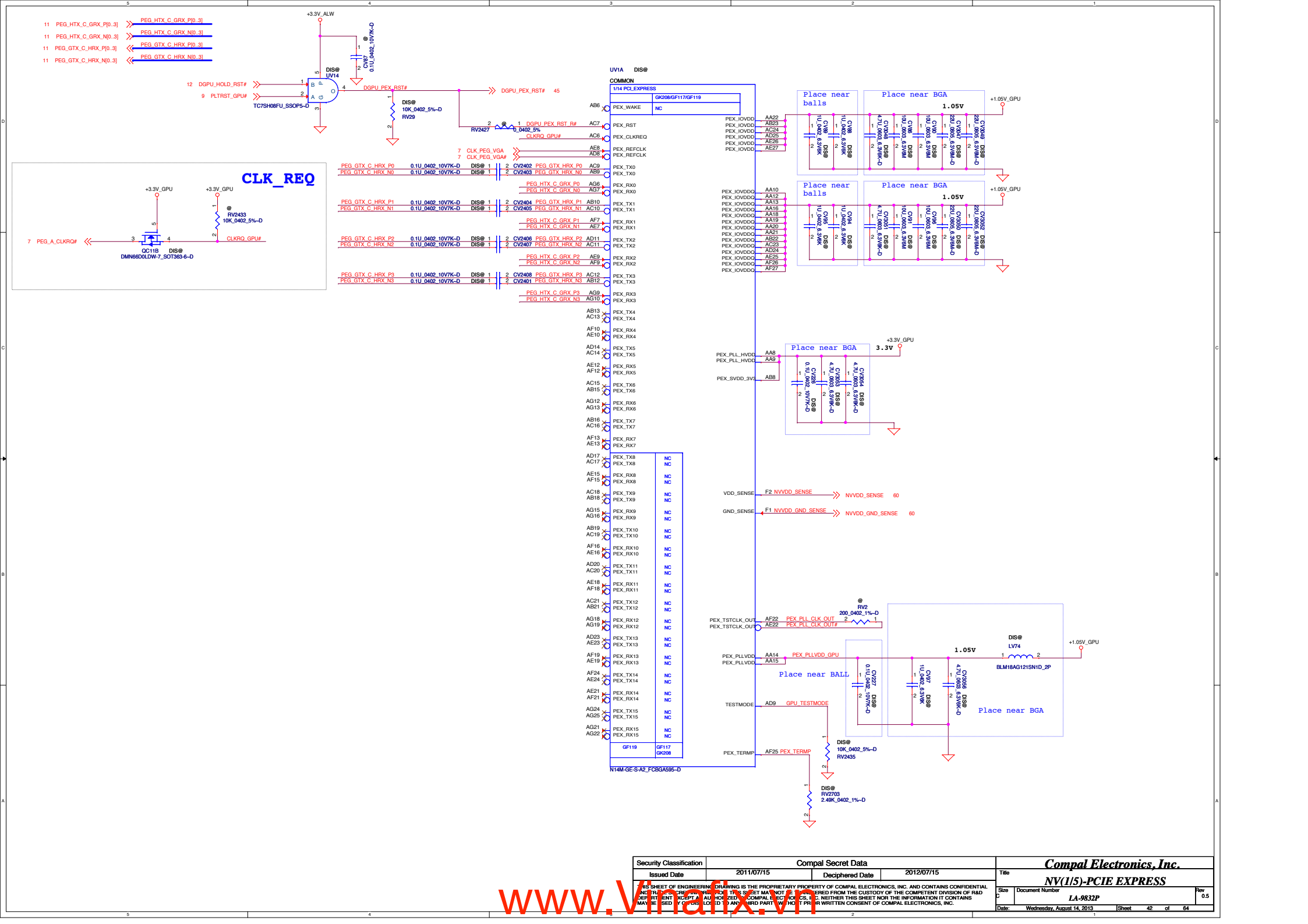
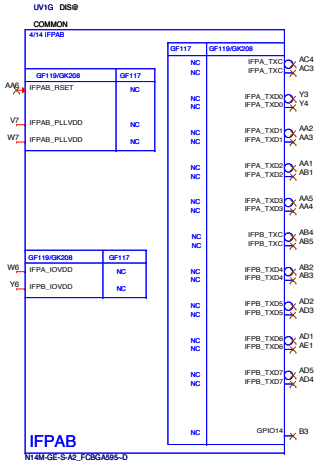
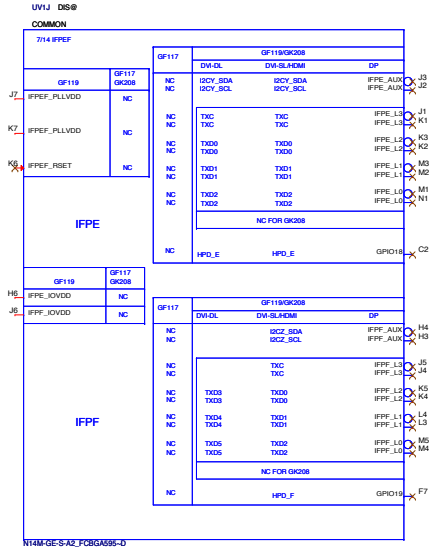
Date: Wednesday, August 14, 2013 | Sheet 41 of 64



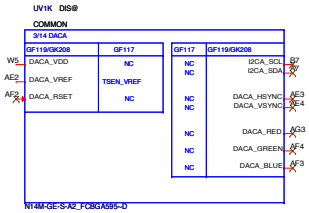
IFPA/B



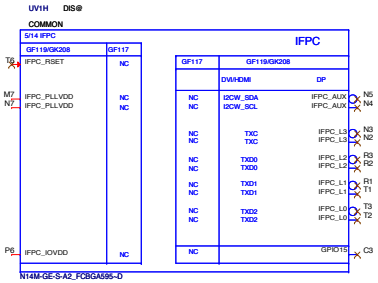
IFPE/F



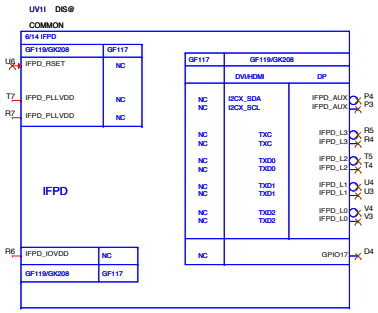
DAC_A



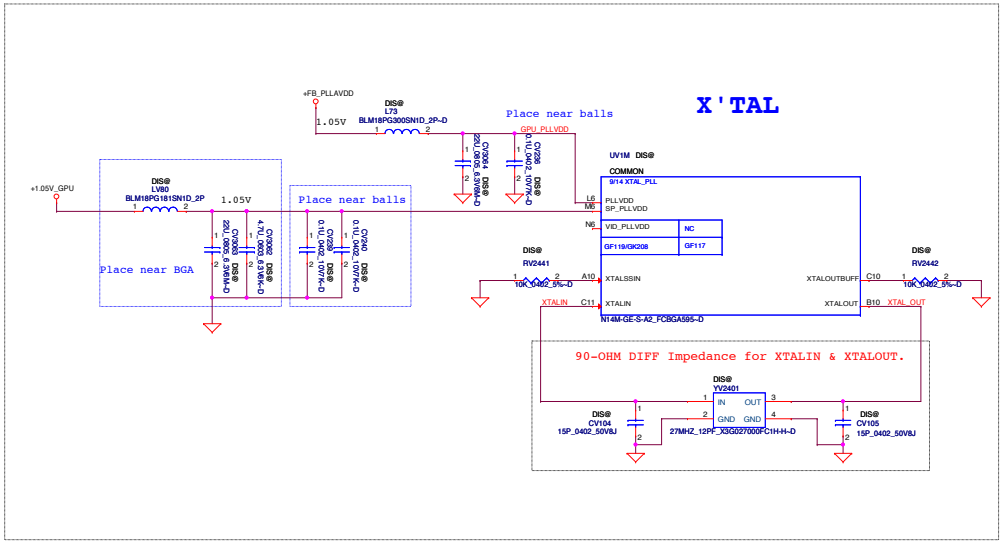
IFPC



IFPD



X'TAL



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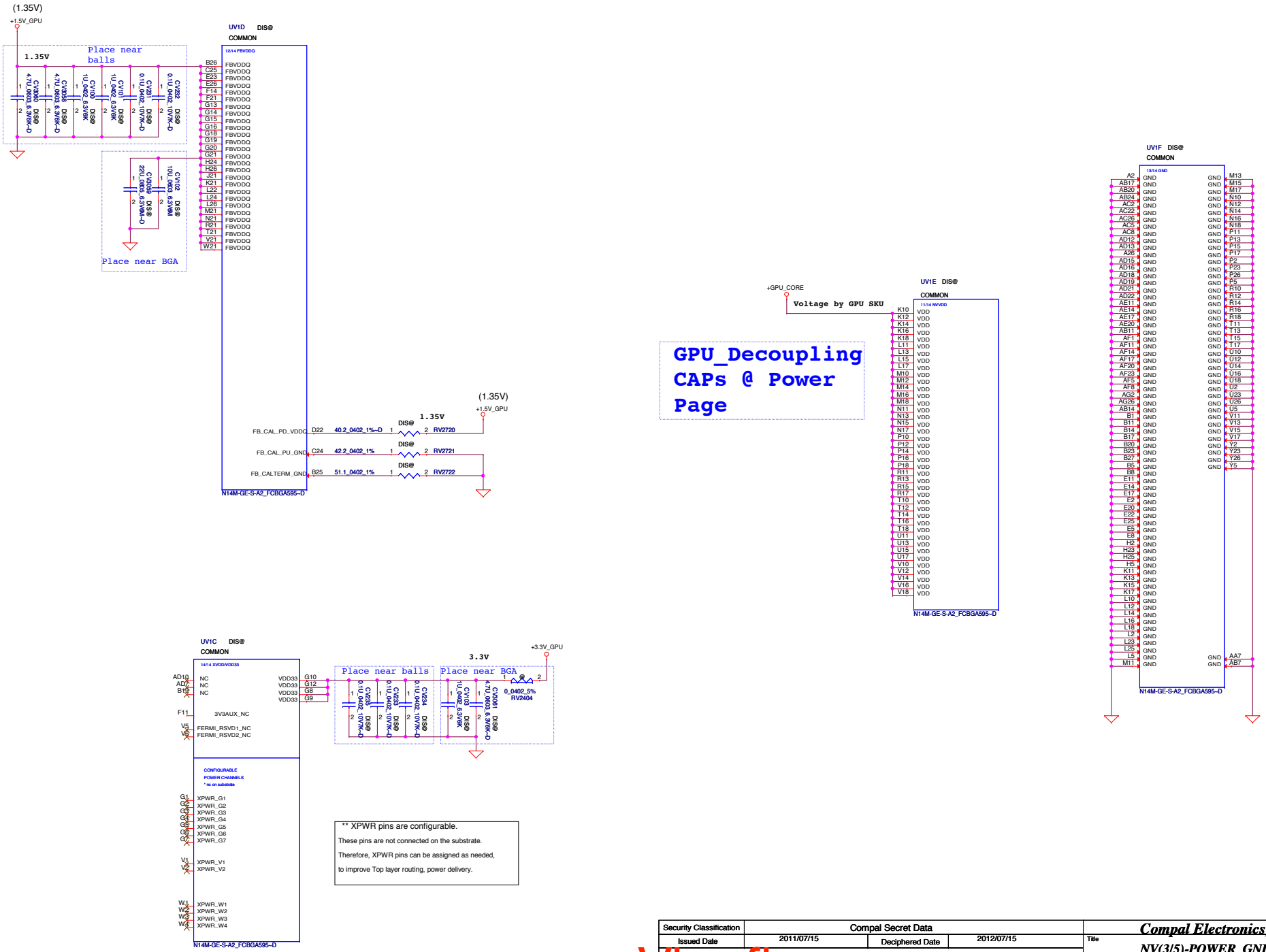
Issued Date	2011/07/15	Deciphered Date	2012/07/15

Compal Electronics, Inc.			
Title	NV(2/5)-IFP_ABCDEF_DAC_XTAL		
Size: Custom	Document Number: LA-9832P		Rev: 0.5
Date: Wednesday, August 14, 2013	Sheet 43 of 64		



Compal Electronics, Inc.			
Title: NV(3/5)-POWER_GND			
Size: C	Document Number: LA-9832P		Rev: 0.5
Date: Wednesday, August 14, 2013	Sheet 44 of 64		

GPIO

VGA_THERMDN and VGA_THERMDP:
1. 5mil track width and spacing
2. 5mil grounded gurad tracks width and spacing
3. ground referenced
4. Connect guard tracks to pin5

For Boundary Scan using.

UV1N DIS@
COMMON
8/14 MISC1

THERMDN E12
THERMDP F12

T186 GPU_JTAG_TCK AE5 JTAG_TCK
T187 GPU_JTAG_TMS AD6 JTAG_TMS
T188 GPU_JTAG_TDI AE6 JTAG_TDI
T189 GPU_JTAG_TDO AF6 JTAG_TDO
T190 GPU_JTAG_TRST# AG4 JTAG_TRST

RV88 10K_0402_5% DIS@

I2CS_SCL D9 I2CS_SCL 2.2K_0402_5%~D RV49
I2CS_SDA D8 I2CS_SDA 2.2K_0402_5%~D RV50
I2CC_SCL A9 I2CC_SCL 2.2K_0402_5%~D RV45
I2CC_SDA B9 I2CC_SDA 2.2K_0402_5%~D RV46

GF117	GF119 GK208
NC	I2CB_SCL C9
NC	I2CB_SDA C8

+3.3V_GPU

GPIO0 C6
GPIO1 B2
GPIO2 D6
GPIO3 C7
GPIO4 C9
GPIO5 A3
GPIO6 A4
GPIO7 B6
GPIO8 A6 GPIO8_THERMATRIP# RV48 DIS@ 100K_0402_5%~D
GPIO9 F8 GPIO09_GPUHOT# RV34 DIS@ 100K_0402_5%~D
GPIO10 C5
GPIO11 E7 GPIO11_NVVDD_VID_R
GPIO12 D7 GPIO12_AC_DETECT RV35 DIS@ 100K_0402_5%~D
GPIO13 B4 GPIO13_NVVDD_PSI_R RV2446 DIS@ 100K_0402_5%~D

GK208	GF117	GF119
GPIO16	NC	GPIO16 D5
GPIO20	NC	GPIO20 C5
GPIO8	NC	GPIO21 C4

GK208	
OVERT	

N14M-GE-S-A2_FCBGA595~D

I2CS SMBUS: 0x9E

I2CS_SCL → QC9A DIS@ DMN66D0LDW-7_SOT363-6-D → GPU_SMBCLK 38
I2CS_SDA → QC9B DIS@ DMN66D0LDW-7_SOT363-6-D → GPU_SMBDAT 38

+3.3V_GPU
42 DGPU_PEX_RST# RV76 DIS@ 0_0402_5%~D RV75 @ 0_0402_5%~D
GPIO8_THERMATRIP# → QC8A DIS@ DMN66D0LDW-7_SOT363-6-D → THERMATRIP3# 38,60

+3.3V_GPU
GPIO11_NVVDD_VID_R → QC8B DIS@ DMN66D0LDW-7_SOT363-6-D → GPIO11_NVVDD_VID 37,60

+3.3V_GPU
GPIO12_AC_DETECT → QC8A DIS@ DMN66D0LDW-7_SOT363-6-D
RV74 DIS@ 0_0402_5%~D GPU_PWR_LEVEL → GPU_PWR_LEVEL 37
RV73 @ 0_0402_5%~D ACAV_IN → ACAV_IN 38,58,59
GPIO13_NVVDD_PSI_R → QC8B DIS@ DMN66D0LDW-7_SOT363-6-D → GPIO13_NVVDD_PSI 60

+3.3V_GPU
GPIO09_GPUHOT# → QC11A DIS@ DMN66D0LDW-7_SOT363-6-D → GPUHOT# 37,60

UV1L DIS@
COMMON
10/14 MISC2

GF117/GF119/GK208	
VMON_IN0 E10	NC
VMON_IN1 F10	NC

STRAP0 D1 STRAP0
STRAP1 D2 STRAP1
STRAP2 E4 STRAP2
STRAP3 E3 STRAP3
STRAP4 D3 STRAP4

GF119	GF117 GK208
STRAP5_NC C1	NC

STRAPREF0 F6 MULTISTRAP_REF0_GND
@ RV2723 40.2K_0402_1%~D

GF119	GF117 GK208
MULTISTRAP_REF1_GND F4	NC
MULTISTRAP_REF2_GND F5	NC

ROM_CS D12
ROM_SI B12 ROM_SI
ROM_SO A12 ROM_SO
ROM_SCLK C12 ROM_SCLK

BUFRST D11 RV2444 DIS@ 10K_0402_5%~D

NC	PGOOD D10
GF117 GK208	GF119

NC	CEC E9
GF117 GK208 GF119	

N14M-GE-S-A2_FCBGA595~D

De-POP RV2723 for N14M-GE and Binary Strap Mode

STRAP

ROM_SI
ROM_SO
ROM_SCLK

10K_0402_1%~D RV89 DIS@
10K_0402_1%~D RV92 DIS@
10K_0402_1%~D RV90 DIS@

STRAP[3:0]
RAM_CF[3:0]
(Micron) MT41K256M16HA-107GM: 0xD = 1101
(Hynix) H5TC4G63AFR-11C: 0x4 = 0100

+3.3V_GPU

STRAP0
STRAP1
STRAP2
STRAP3
STRAP4

@ 10K_0402_1%~D RV94
DIS@ RV2651 10K_0402_1%~D
DIS@ RV2647 10K_0402_1%~D
@ RV2649 10K_0402_1%~D
DIS@ RV2653 10K_0402_1%~D

DIS@ 10K_0402_1%~D RV93
@ RV2652 10K_0402_1%~D
@ RV2648 10K_0402_1%~D
DIS@ RV2650 10K_0402_1%~D
@ RV2654 10K_0402_1%~D

Security Classification	Compal Secret Data		
Issued Date	2011/07/15	Deciphered Date	2012/07/15

Compal Electronics, Inc.
Title: NV(4/5)-GPIO_BIOS_STRAP
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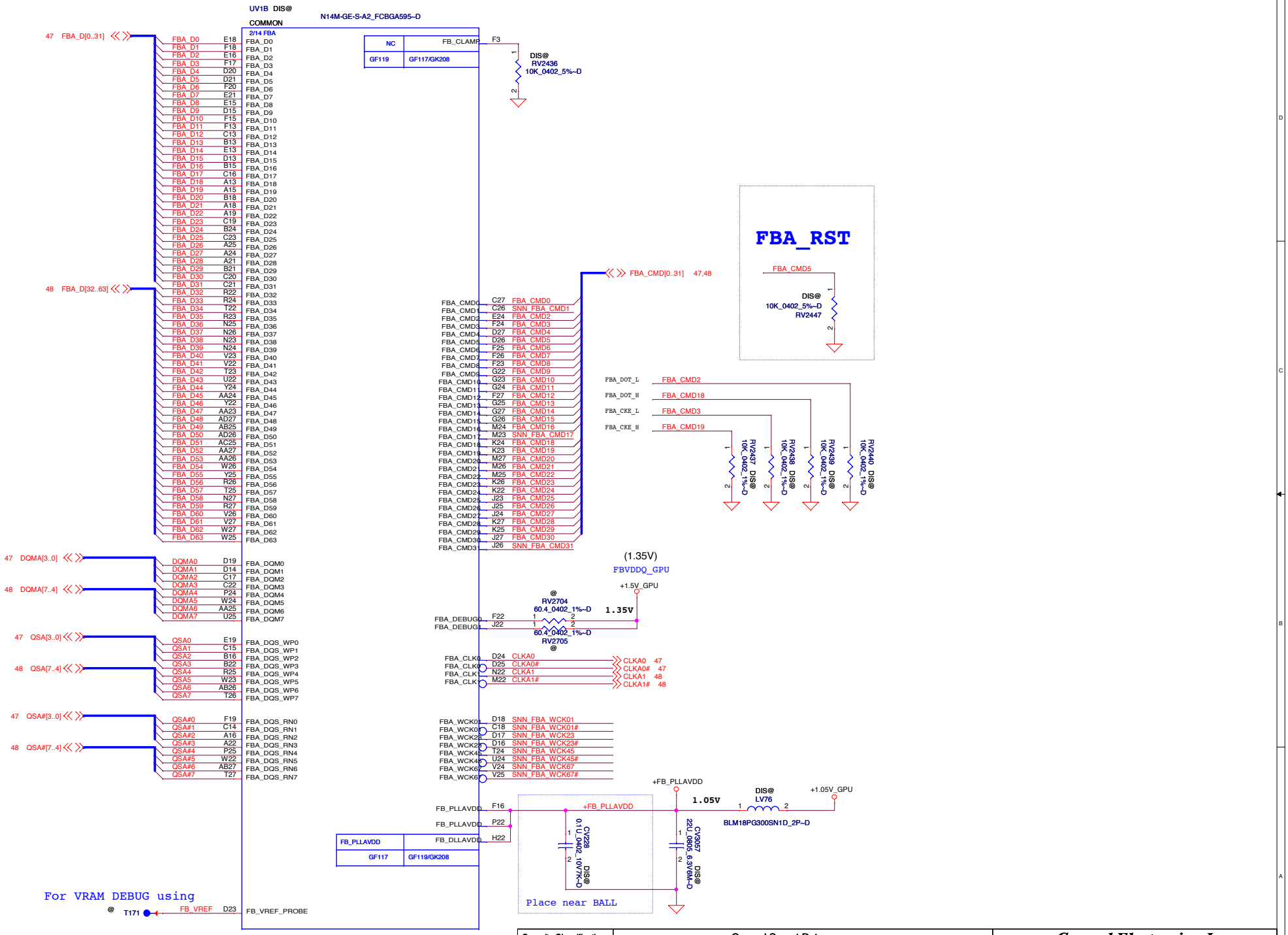
Date: Wednesday, August 14, 2013 | Sheet 45 of 64



Security Classification	Compal Secret Data		
Issued Date	2011/07/15	Deciphered Date	2012/07/15

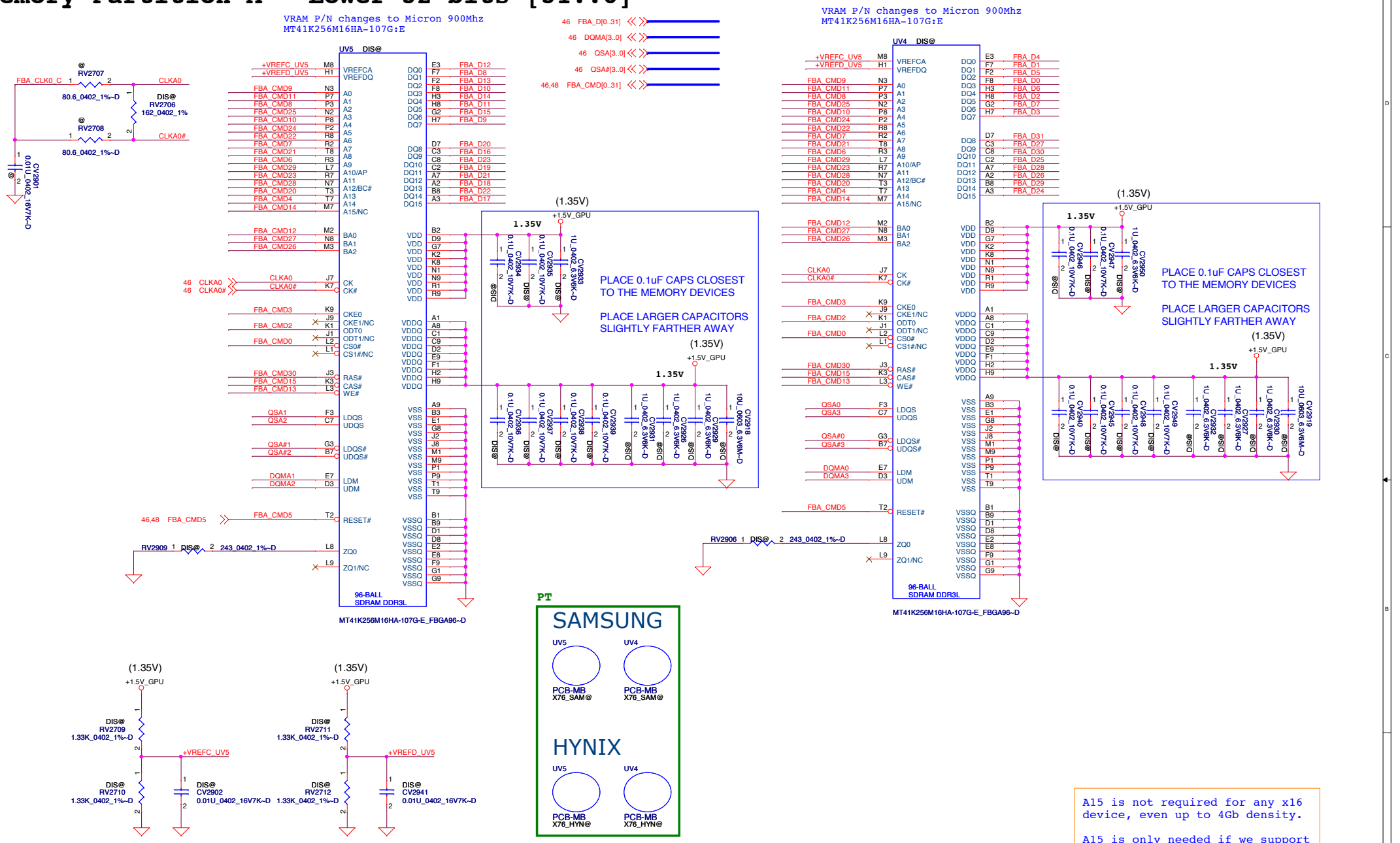
Compal Electronics, Inc.

Title: NV(5/5)-MEMORY FBA

Size: Custom | Document Number: LA-9832P | Rev: 0.5

Date: Wednesday, August 14, 2013 | Sheet 46 of 64

Memory Partition A - Lower 32 bits [31..0]



A15 is not required for any x16 device, even up to 4Gb density.

A15 is only needed if we support x8 configurations, and only at 4Gb.

Security Classification	Compal Secret Data		
Issued Date	2011/07/15	Deciphered Date	2012/07/15

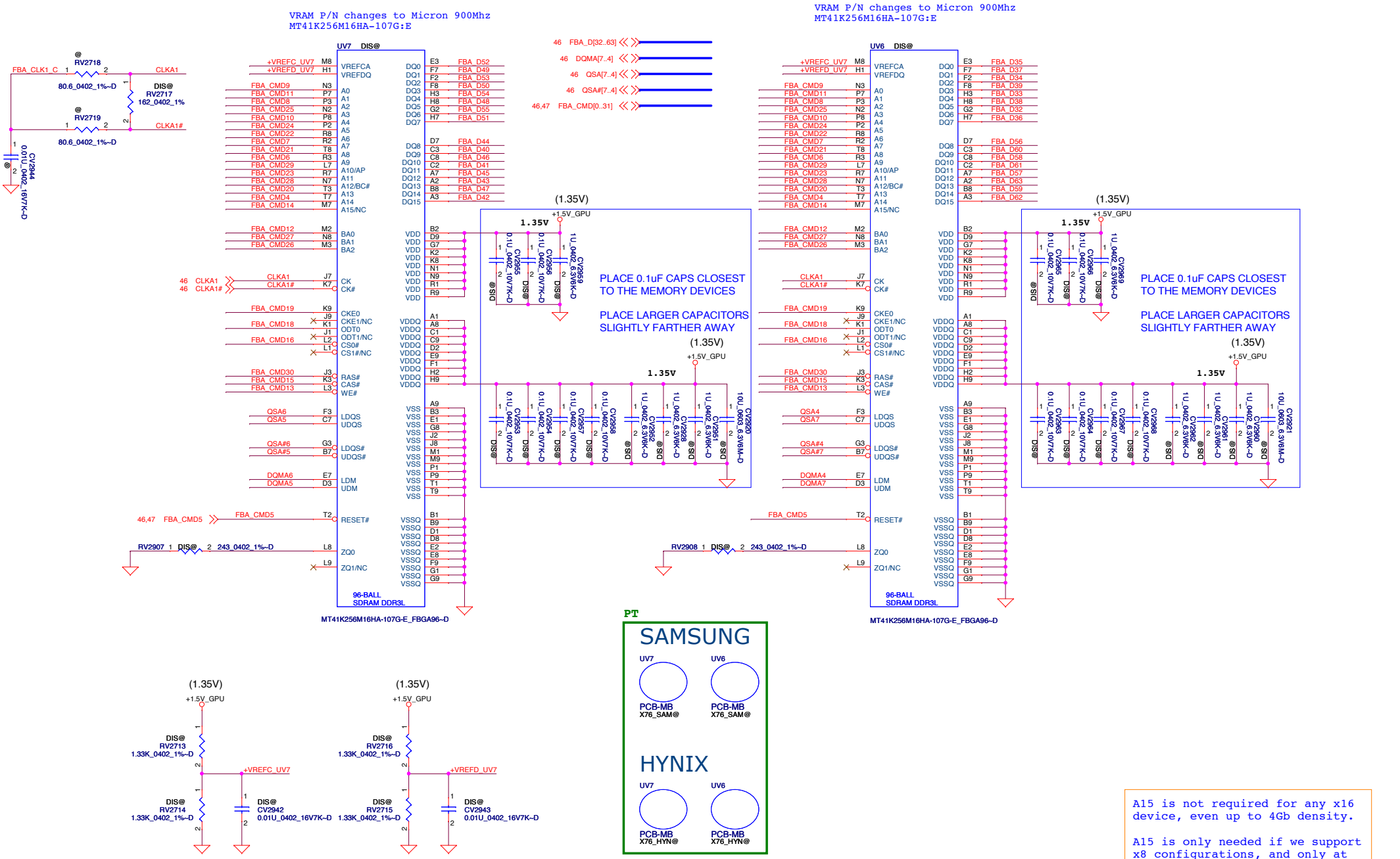
Compal Electronics, Inc.

Title: VRAM_DDR3_A Lower

Size: Custom | Document Number: LA-9832P | Rev: 0.5

Date: Thursday, June 13, 2013 | Sheet 47 of 64

Memory Partition A - Upper 32 bits [64..32]



PT

SAMSUNG

UV7	UV6
PCB-MB X76_SAM@	PCB-MB X76_SAM@

HYNIX

UV7	UV6
PCB-MB X76_HYN@	PCB-MB X76_HYN@

A15 is not required for any x16 device, even up to 4Gb density.

A15 is only needed if we support x8 configurations, and only at 4Gb.

Security Classification	Compal Secret Data		
Issued Date	2011/07/15	Deciphered Date	2012/07/15

Compal Electronics, Inc.

Title: VRAM_DDR3_A Upper

Size	Document Number	Rev
Custom	LA-9832P	0.5

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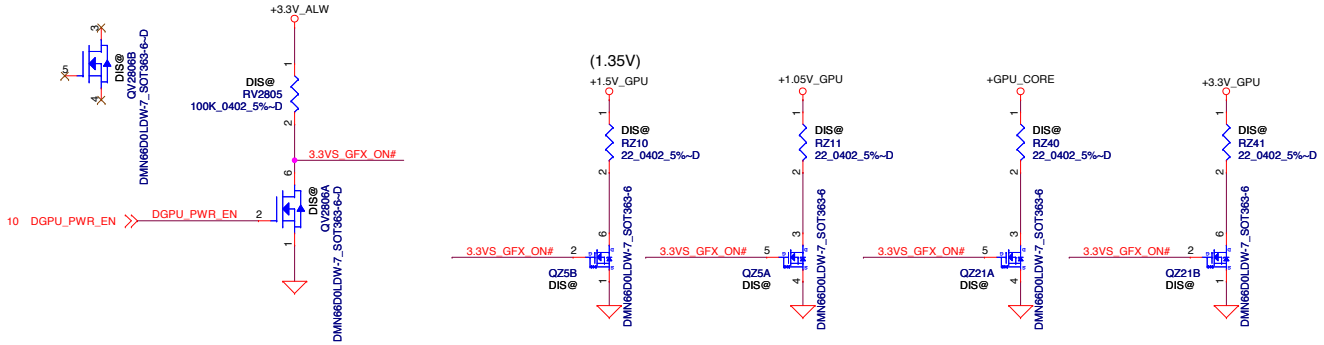
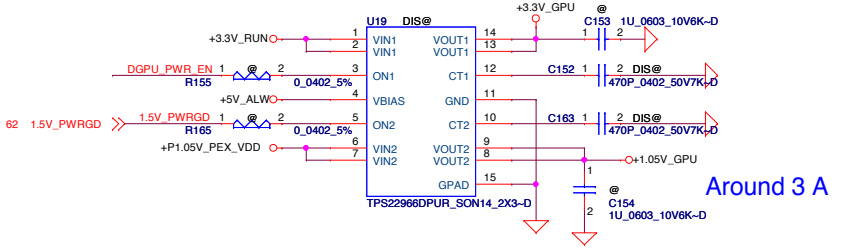
GPU Power Discharge Path



+3.3VRUN to +3.3V_RUN_GFX

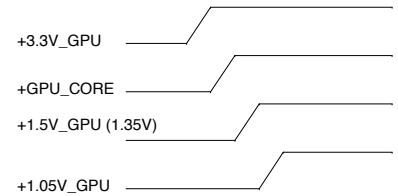
Around 1.4 A



Around 3 A

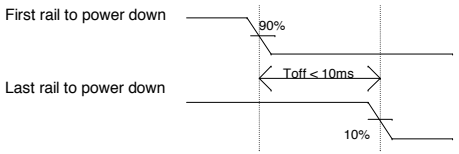
+1.05V_MP to +1.05V_PEX_VDD

GPU Power Up Power Rail Sequence

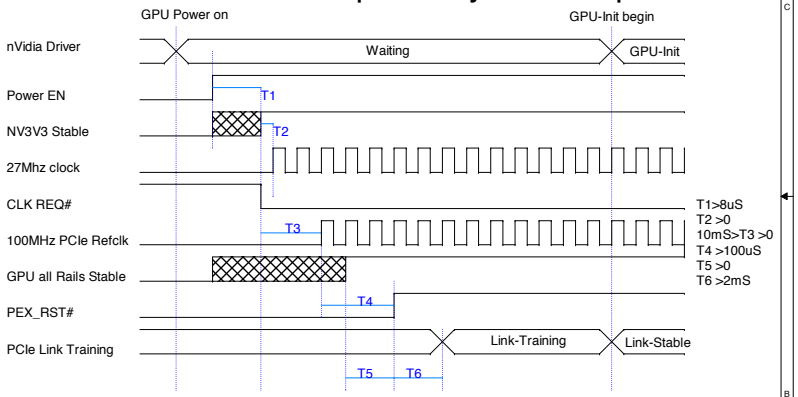


The ramp time for any rail must be more than 40us.

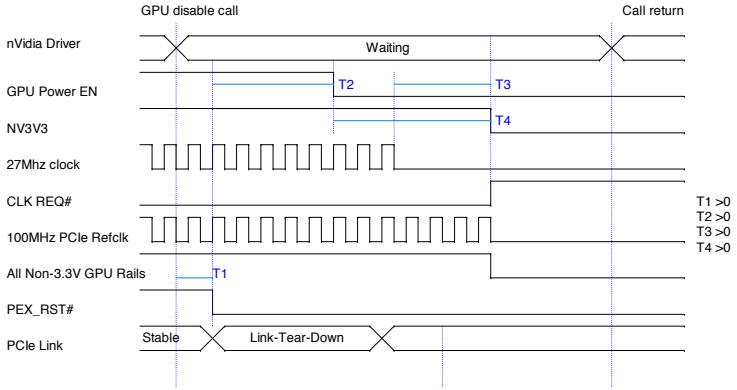
GPU Power Down Sequence



GPU Power Up Sub-system Sequence



GPU Power Down Sub-system Sequence



Security Classification	Compal Secret Data		
Issued Date	2011/07/15	Deciphered Date	2012/07/15

Compal Electronics, Inc.			
Title: VGA_DC/DC Interface			
Size	Document Number		Rev 0.5
Date: Thursday, August 15, 2013	Sheet 49 of 64		

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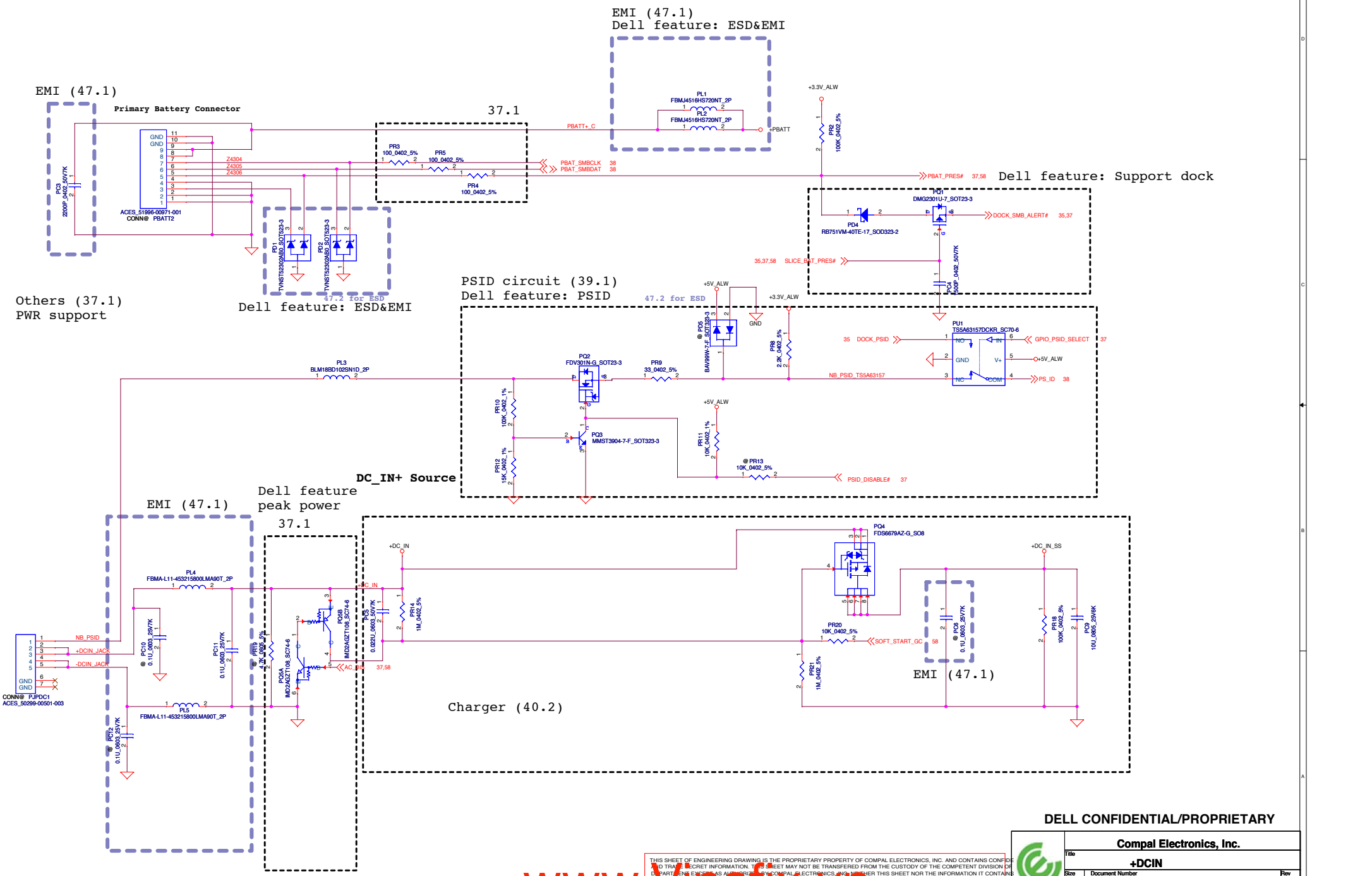
Compal Electronics, Inc.		
Title: BLANK PAGE		
Size	Document Number: LA-9832P	Rev: 0.5
Date: Thursday, June 13, 2013	Sheet 50 of 64	



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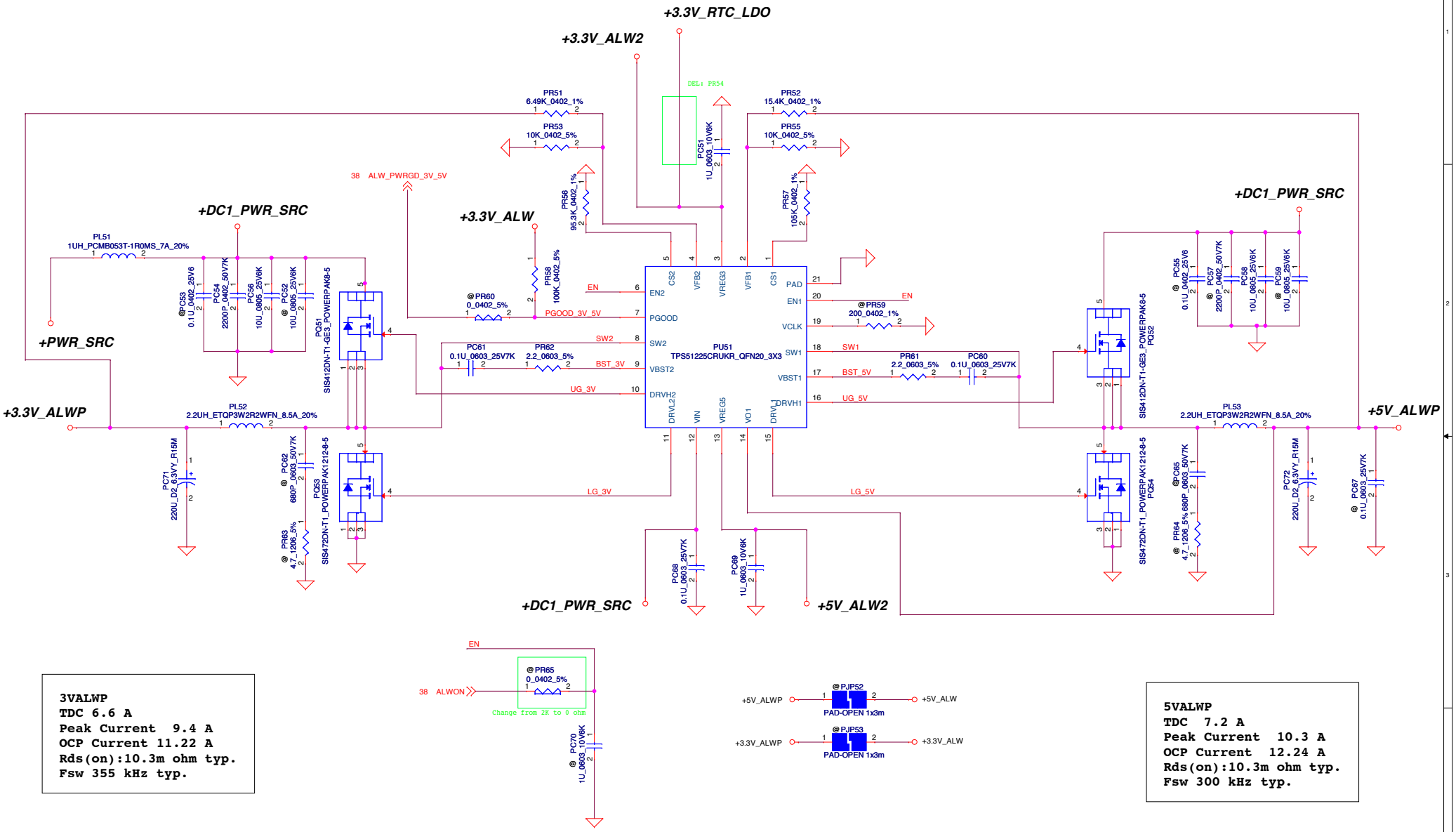
Compal Electronics, Inc.		
Title: +DCIN		
Size	Document Number: LA-XXXX	Rev: 0.1
Date: Wednesday, August 14, 2013	Sheet 51 of 64	



3VALWP
TDC 6.6 A
Peak Current 9.4 A
OCP Current 11.22 A
Rds(on):10.3m ohm typ.
Fsw 355 kHz typ.

5VALWP
TDC 7.2 A
Peak Current 10.3 A
OCP Current 12.24 A
Rds(on):10.3m ohm typ.
Fsw 300 kHz typ.

Compal Electronics, Inc.	
Title	PWR_+5V_ALW/3.3V_ALW
Size	Document Number: LA-XXXX
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Date:	Wednesday, August 14, 2013
Sheet	52 of 64

1.35Volt +/- 5%
TDC: 7.2 A
Peak Current: 10.3 A
OCP current: 12.24 A
Rds(on):14.5m ohm typ
Fsw

0.675Volt +/- 5%
TDC 0.525A
Peak Current 0.75A
OCP Current 0.8925A

+PWR_SRC
PL101
FBMA-L11-453215-121LMA90T_2
1.35V_B+
PC100 10U_0805_25V6K
PC101 10U_0805_25V6K
@ PC102 0.1U_0402_25V6
PC103 2200P_0402_50V7K
PC104 0.22U_0603_16V7K
PR100 2.2_0603_5%
BOOT_1.35V
DH_1.35V
SW_1.35V
DL_1.35V
SI4128DY-T1-GE3_SO8 PQ100
SI4194DY-T1-GE3_SO8 PQ101
+1.35V_MEN_P
PL100 2.2UH_ETQP3W2R2WFN_8.5A_20%
PC116 330U_D2_2.5VY_R15M
PC110 @ 330U_2.5V_M
PC109 @ 680P_0603_50V7K
SNUB_1.35V
@ PR103 4.7_1206_5%
+5V_ALW
PR102 5.1_0603_5%
PR101 19.6K_0402_1%
CS_1.35V
PC107 1U_0603_10V6K
VDD_1.35V
PC111 1U_0603_10V6K
+3.3V_ALW
PR104 100K_0402_5%
38 1.35V_SUS_PWRGD
1.35V_SUS_PWRGD
PR106 1M_0402_1%
1.35V_B+
@ PR107 0_0402_5%
37,40,54,9 SIO_SLP_S4#
S5_1.35V
@ PR108 0_0402_5%
37,40 SUS_ON
@ PC115 0.1U_0402_10V7K
PU100 G5616ARZ1U_TQFN20_3X3
LX DH BST VLDOIN VTT PAD VTTGND VTTSNS GND VTTREF VDDQSNS VDDQSET
DL PGND CS VPP VCC PGOOD TON S5 S3
+VLDOIN_1.35V
@ PJP101 PAD-OPEN1x1m
+1.35V_MEN_P
+0.675V_P
PC105 10U_0805_6.3V6M
PC106 10U_0805_6.3V6M
+V_DDR_REF
+V_DDR_REF
+1.35V_MEN_P
FB sense trace
when FB pull down to GND
PC112 0.033U_0402_16V7K
PR105 8.06K_0402_1%
1.35V_FB
+1.35V_MEN_P
FB sense trace
PC113 100P_0402_50V8J
PR109 10K_0402_1%
@ PC114 0.1U_0402_10V7K
@ PR110 0_0402_5%
18 0.675V_DDR_VTT_ON
@ PR111 0_0402_5%
36,37,40,9 SIO_SLP_S3#

Mode	S3	S5	+1.35V_MEN_P	+V_DDR_REF	+0.675V_P
S5	L	L	off	off	off
S3	L	H	on	on	off(Hi-Z)
S0	H	H	on	on	on

+1.35V_MEN_P
@ PJP102 JUMP_1x3m
@ PJP103 JUMP_1x3m
+1.35V_MEM

+0.675V_P
@ PJP104 PAD-OPEN1x1m
+0.675V_DDR_VTT

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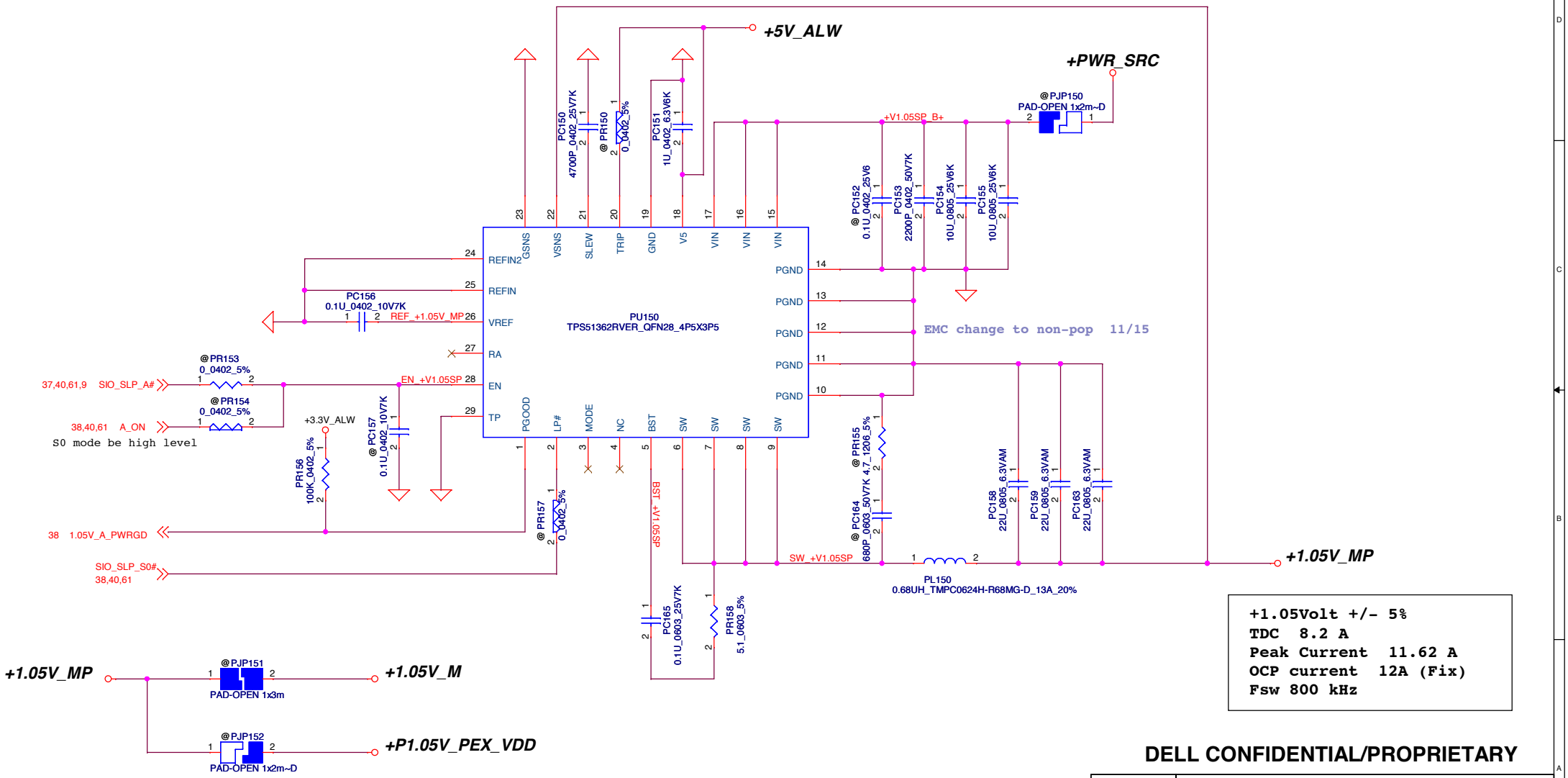
Compal Electronics, Inc.
Title: PWR_+1.35V_MEN/+0.675V_DDR
Size: Document Number: LA-XXXX Rev: 0.1
Date: Wednesday, August 14, 2013 Sheet 53 of 64



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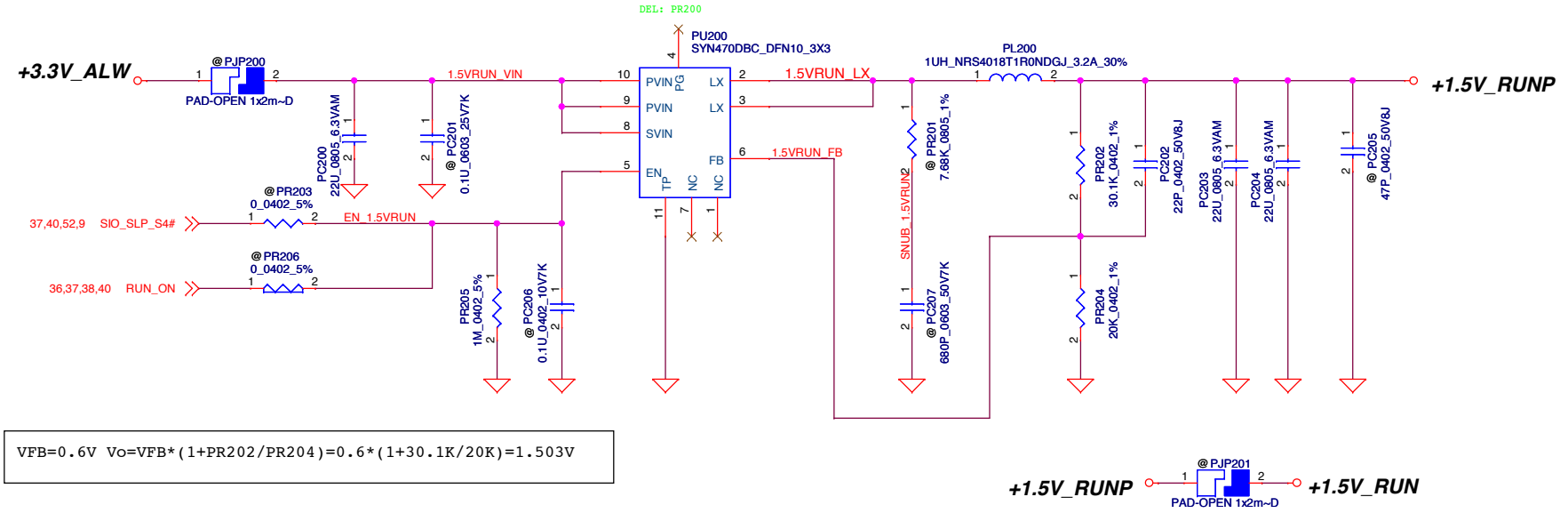
Compal Electronics, Inc.		
Title: PWR_+1.05VTTP		
Size	Document Number: LA-XXXX	Rev: 0.1
Date: Wednesday, August 14, 2013	Sheet 54 of 64	

1.5Volt
Frequency 1MHz
TDC 0.65A
Peak Current 0.93A
OCP current 3.5A (Fix)



VFB=0.6V Vo=VFB*(1+PR202/PR204)=0.6*(1+30.1K/20K)=1.503V

+1.5V_RUNP @PJP201 PAD-OPEN 1x2m~D +1.5V_RUN

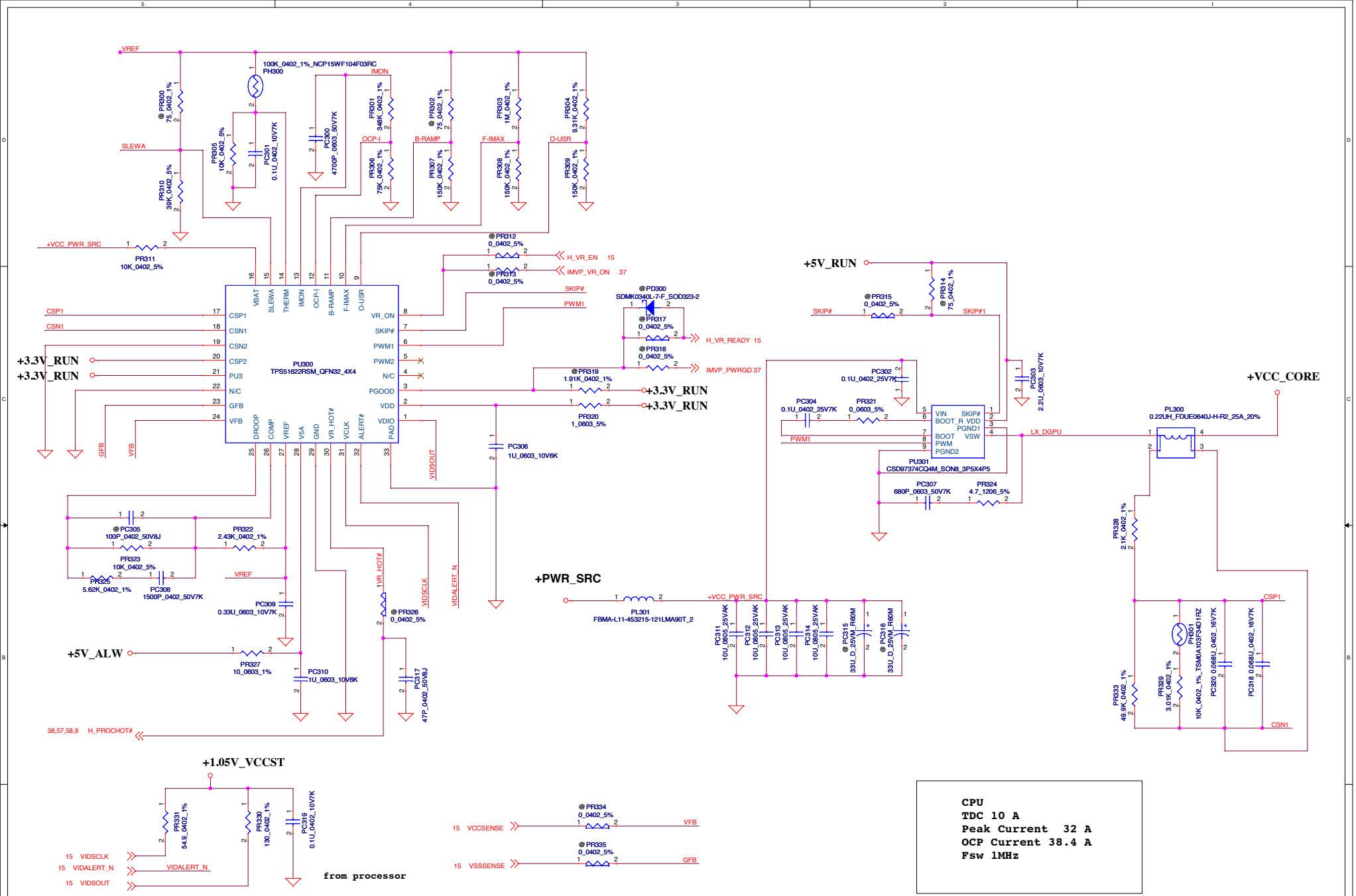
Security Classification	Compal Secret Data		
Issued Date	<Issued_Date>	Deciphered Date	<Deciphered_Date>

Compal Electronics, Inc.

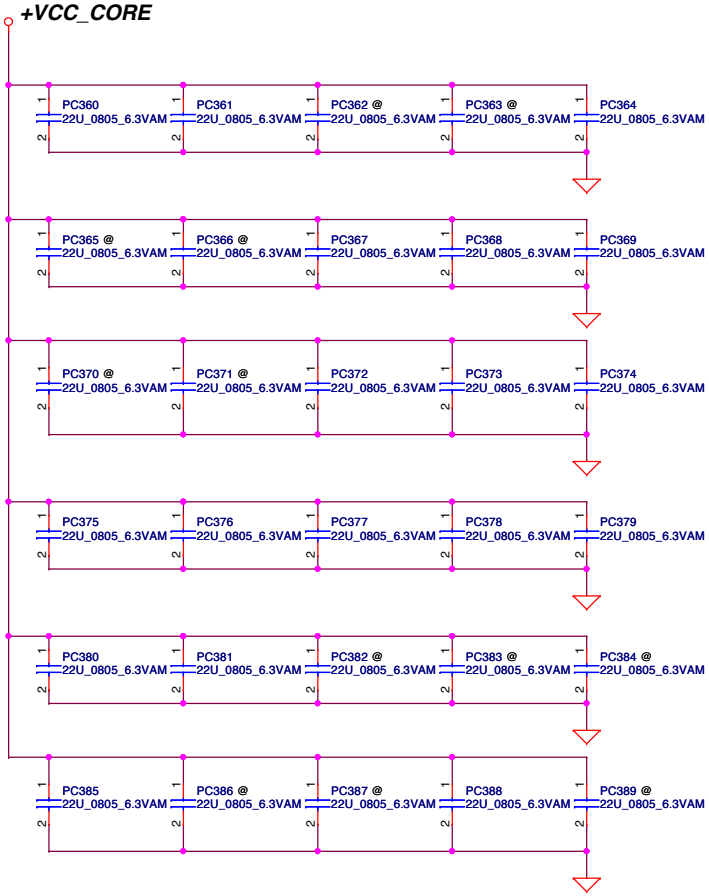
Title: PWR_1.5V_RUN

Size: B | Document Number | Rev: 1.0

Date: Wednesday, August 14, 2013 | Sheet 55 of 64



Compal Electronics, Inc.	
Title	PWR_+VCC_CORE
Size	Document Number: LA-XXXX
Rev	0.1
Date:	Wednesday, August 14, 2013
Sheet	56 of 64

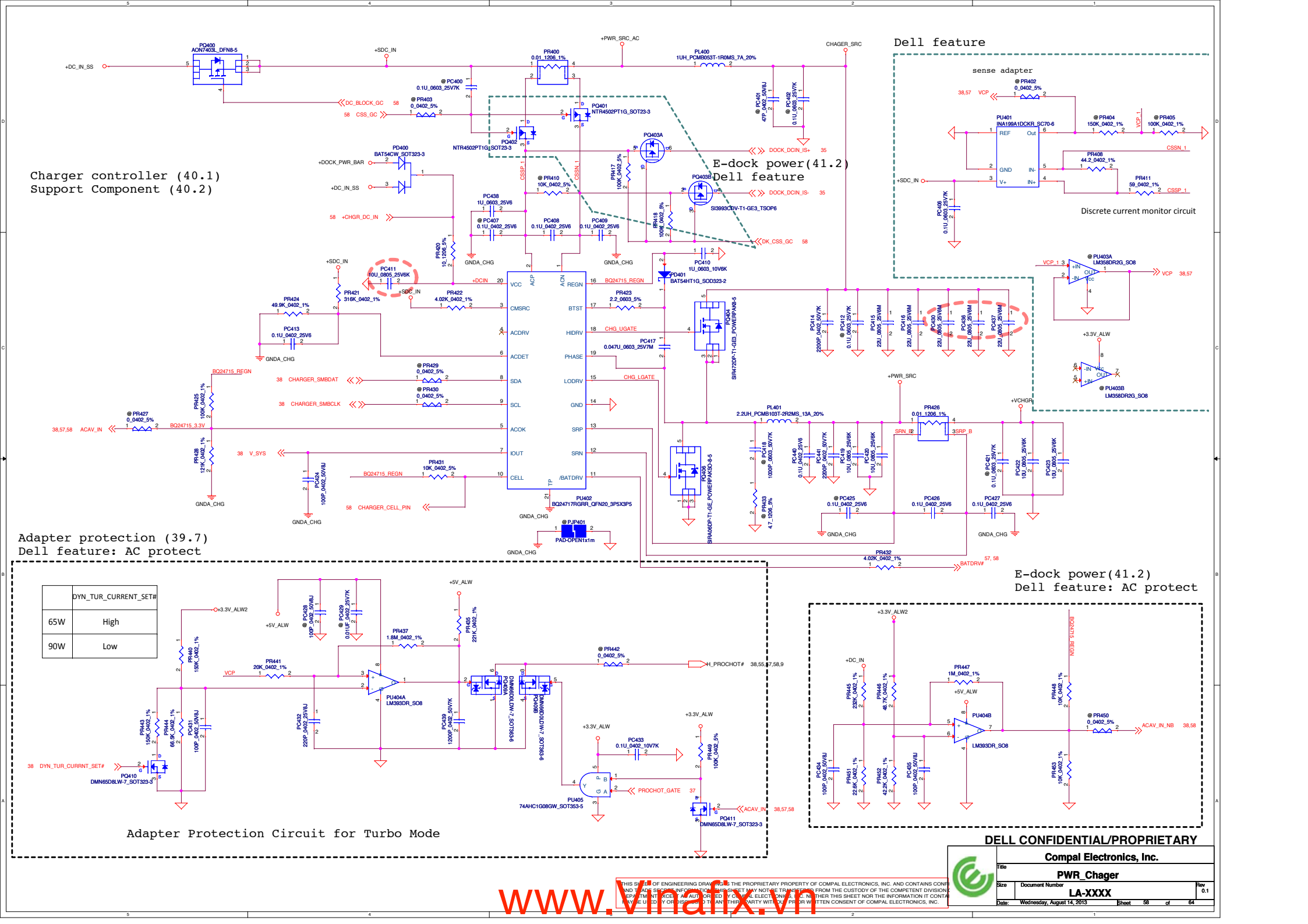


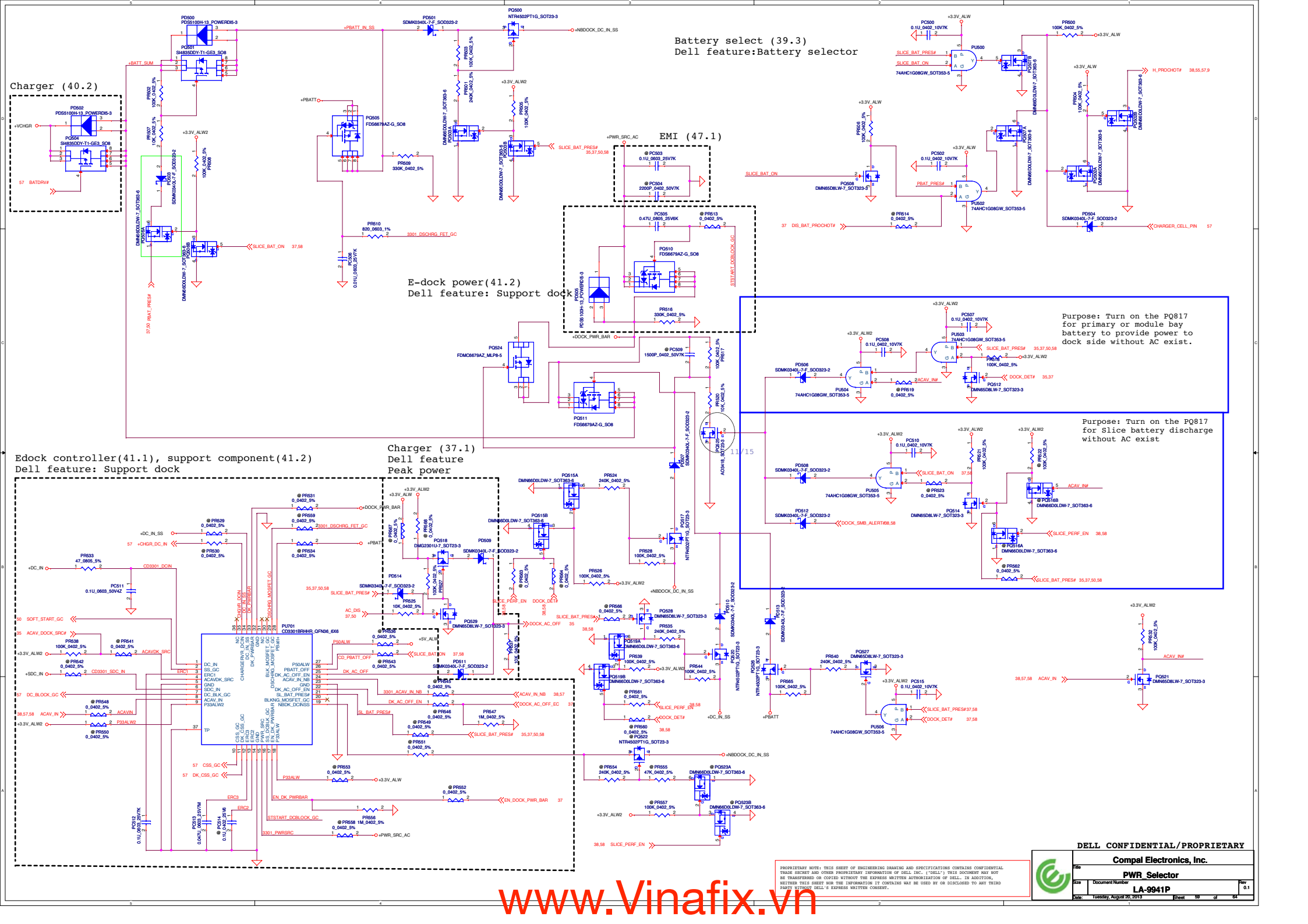
Compal Electronics, Inc.

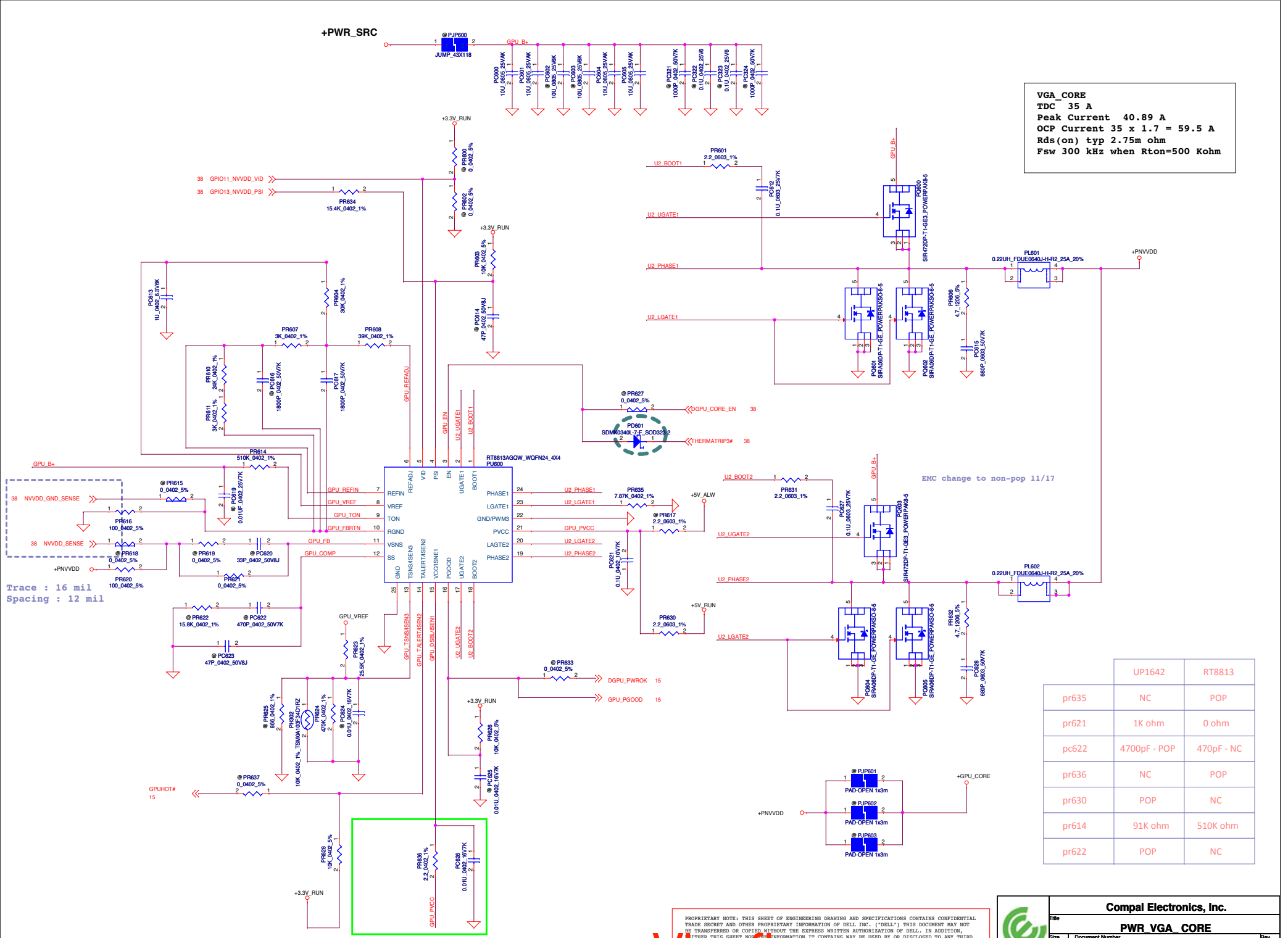
Title: PWR_PROCESSOR DECOUPLING

Size: | Document Number: LA-XXXX | Rev: 0.1

Date: Wednesday, August 14, 2013 | Sheet 57 of 64


Charger controller (40.1)
Support Component (40.2)
Dell feature
sense adapter
E-dock power(41.2)
Dell feature
Discrete current monitor circuit
Adapter protection (39.7)
Dell feature: AC protect
E-dock power(41.2)
Dell feature: AC protect
DYN_TUR_CURRENT_SET#
65W
High
90W
Low
Adapter Protection Circuit for Turbo Mode
DELL CONFIDENTIAL/PROPRIETARY
Compal Electronics, Inc.
PWR_Chager
LA-XXXX
Wednesday, August 14, 2013
www.vinafix.vn


Charger (40.2)
Battery select (39.3)
Dell feature:Battery selector
EMI (47.1)
E-dock power(41.2)
Dell feature: Support dock
Purpose: Turn on the PQ817 for primary or module bay battery to provide power to dock side without AC exist.
Purpose: Turn on the PQ817 for Slice battery discharge without AC exist
Edock controller(41.1), support component(41.2)
Dell feature: Support dock
Charger (37.1)
Dell feature
Peak power
DELL CONFIDENTIAL/PROPRIETARY
Compal Electronics, Inc.
PWR_Selector
LA-9941P
Tuesday, August 20, 2013
www.Vinafix.vn



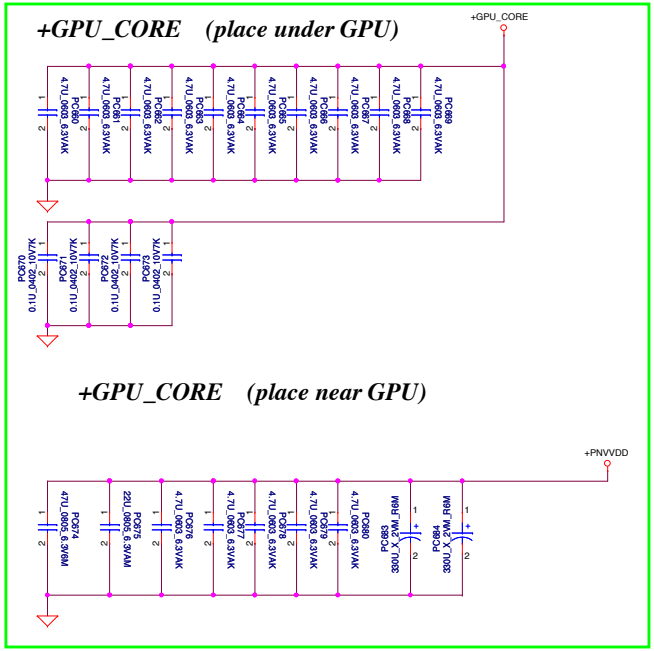
	UP1642	RT8813
pr635	NC	POP
pr621	1K ohm	0 ohm
pc622	4700pF - POP	470pF - NC
pr636	NC	POP
pr630	POP	NC
pr614	91K ohm	510K ohm
pr622	POP	NC

Compal Electronics, Inc.

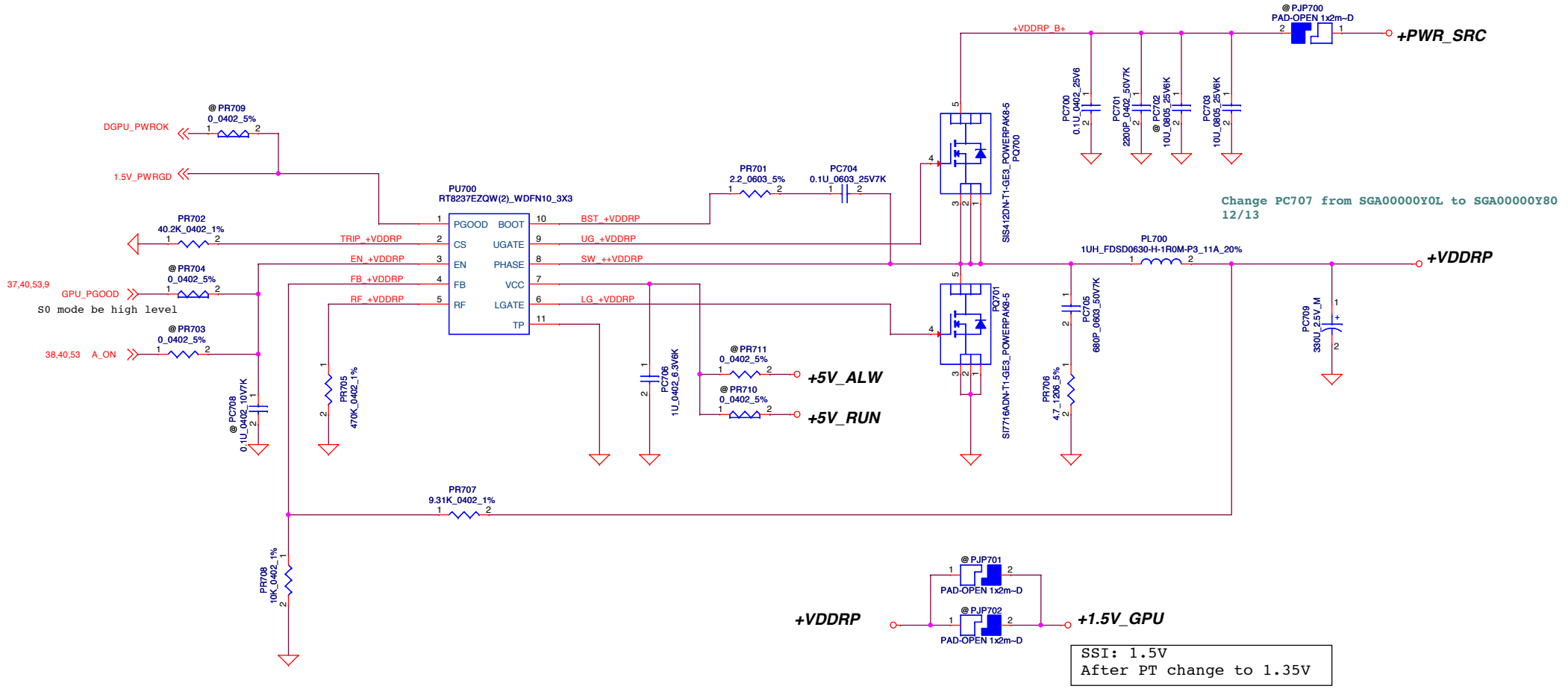
Title: PWR_VGA_CORE

Size: Document Number: LA-XXXX Rev: 0.1

Date: Wednesday, August 14, 2013 Sheet 60 of 64



Compal Electronics, Inc.		
Title	PWR_GPU_ DECOUPLING	
Size	Document Number: LA-8821P	Rev: 0.1
Date: Wednesday, August 14, 2013	Sheet 61 of 64	



Compal Electronics, Inc.	
Title	PWR_+1.5VDDR
Size	Document Number: LA-9391P
Rev	0.1
Date:	Wednesday, August 14, 2013
Sheet	62 of 64

VAW30 Version Change List (P. I. R. List) Page 1

Item	Page#	Title	Date	Request Owner	Issue Description	Solution Description	Rev.
1	58	Adapter Protection Circuit	2013/1/30	Power	PC432 220pF is not popular part	Change to 0402 size	X00
2	59	P59-PWR_Selector	2013/2/4	Power	Battery voltage leakage to docking if only battery	Add: PD513, PQ526, PR565, PR540, PQ527, PU506, PC515	X00
3	56	Vcore fine tune	2013/2/7	Power	Vcore fine tune	Modify: PR306, PR301, PR333, PR328, PR325, PR322, PL300	X00
4	57	Vcorecapacitor reduce	2013/2/7	Power	Vcore output capacitor reduce	NC: PC371 ,PC386, PC370 ,PC382,PC383	X00
5	58	Charger	2013/2/18	Power	Reserve H_PROCHOT# delay time fine tune by soft ware	Add "MODULE_BATT_PRES#" and PR454(Cancel 3/19)	X00
6	59	P59-PWR_Selector	2013/2/26	Power	Adjust divider resistor for MOSFET	Change from 240K to 100K: PR503, PR528, PR544, PR565	X00
7	59	P59-PWR_Selector	2013/2/26	Power	Adjust divider resistor for MOSFET	Change from 47K to 240K: PR501, PR524, PR535, PR540	X00
8	59	P59-PWR_Selector	2013/2/26	Power	SUT will unexpected shut down if un-docking during S0/S3	Add: PQ528, PR566	X00
9	51	"PBAT_PRES#" ESD fail	2013/3/4	Power	ESD PD1 fail, even connect 3.3V to VBUS pin	Change PD1 to PD1, PD2(TVNST52302AB0)	X00
10	59	P59-PWR_Selector	2013/3/6	Power	SB903380020 FDN338P derating fail	PQ500, PQ517,PQ520,PQ522,PQ526 change to SB000007900, PQ1change to SB00000PJ00	X00
11	51	PC5 down size	2013/3/12	Power	PC5 down size	Change PC5 from 0805 to 0603 size	X00
12	51,59	AC_DIS# net change	2013/3/12	Power	AC_DIS# should high enable, not low enable	AC_DIS# change to AC_DIS	X00
13		EMC open issue	2013/3/18	Power	Add parts for EMI	PR606,PC615, PR632, PC628, PR706, PC705, PR324, PC307	X00
14	60, 62	PU600, PU601 VCC	2013/3/19	Power	DIS S3 power consumption voer 200mW	Add PR630 PR711, PR710 for reserve +5V_RUN	X00
15	61	Change DGPU output cap	2013/3/19	Power	For thermal issue change DGPU power output cap.-14"	Change PC683,PC684	X00
16	62	GPU DDR change to 1.35V	2013/3/19	Power	Change VDDR output voltage from 1.5V to 1.35V	Change PR707 from 11.5K to 9.1K	X00
17	54	+1.05V dynamic load test	2013/3/19	Power	+1.05V dynamic load over spec	Change PL150 from 1uH to 0.68uH	X00
18	58	Change output chock	2013/3/20	Power	Same as 14" for height limit	Charger output choke change to 2.2uH	X00
19	60	0 ohm resistor	2013/3/21	Power	0 ohm 1% vender is not correct in ISPD	Change PR621 0ohm from 1% to 5%	X00
20	54	1.05V dynamic over spec	2013/3/21	Power	1.05V dynamic over spec	Change PL150 from 1uH to 0.68uH	X00
21	59	Modify for Peak power	2013/3/21	Power	Modify schematic	PQ529, PQ518, PR527 and PR567	X00
22	NA	Reserve	Reserve	Power	Reserve	Reserve	X01
23	60	DGPU core output ripple	2013/5/10	Power	Output ripple with a low frequence ripple	+PWR_SRC do not include feedback via	X01
24	60	DGPU core output ripple	2013/5/10	Power	Output ripple with a low frequence ripple	+PWR_SRC do not include feedback via	X01
25	59	14" 組裝問題	2013/5/10	Power	PD512 太靠邊板	Move location	X01

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Title: EE PIR(1)

Size: Document Number: LA-XXXX Rev: 1.0

Date: Wednesday, August 14, 2013 Sheet 64 of 64

VAW30 Version Change List (P. I. R. List) Page 1

Item	Page#	Title	Date	Request Owner	Issue Description	Solution Description	Rev.
1	56	14" Vcore find tune	2013/5/29	Power	14" Vcore find tune for LL and DIMON	PR328=2.4K->2.1K; PR333=30K->49.9K; PR301=390K->348K	X02
2	NA	Reserve	Reserve	Power	Reserve	Reserve	X02
3	58	EMI solution	2013/5/31	EMI	EMI: 200~225MHz boardband	Populate bead 120 ohm on PJP100 and PL301, populate 0.1uF on pc302 and pc700, 2200pF on pc701.	X02
4	58	EMI solution	2013/5/31	EMI	EMI: 200~225MHz boardband	PC419 add parallel PC441:2200pF and PC440: 0.1uF	X02
5	62	Thermal de-ratgin issue	2013/6/10	Power	MLCC are exceeded thermal derating criteria	Change to X6S/X7R: PC600, PC601, PC604, PC605, PC674, PC302, PC304,PC311,PC312,PC313,PC314	X02
6	59	Change part number	2013/6/6	Power	Part number ~N0 is for other customer	PC505 SE043474KN0 change to SE043474K80	X02
7	NA	14" NPI report(4/19)	2013/6/6	Power	Co-lay need select 1 conponent	Del NC: PJP300, PL600, PJP1, PC66, PC707, PJP51,PJP400	X02
8		Selector	2013/5/30	Power	For 3V/5V volgate level, change VDS rating from 30V to 20V	PQ1, PQ518 change to 20V rating DMG2301U-7_SOT23-3	X02
9	62	14" DGPU DDR	2013/6/7	Power	Output capacitor PC709 not in PSL	Change to NCC: SF000003100	X02
XB							
1		Thermal de-ratgin issue	2013/7/10	Power	According QAD test result change MLCC back to X5R	PC674, PC302, PC304,PC311,PC312,PC313,PC314	X03
2		Change 0 ohm to short pad	2013/7/10	Power	Reduce part count	Except: PR321 and PR621	X03
3		Thermal de-ratgin issue	2013/7/10	Power	MLCC are exceeded thermal derating criteria	VAW30 change to X6S/X7R: PC302, PC304, PC311, PC312, PC313, PC314	X03

Compal Electronics, Inc.

Title: EE PIR(1)

Size: | Document Number: LA-XXXX | Rev: 1.0

Date: Wednesday, August 14, 2013 Sheet 64 of 64

Version Change List (P. I. R. List)

Item	Page#	Title	Date	Request Owner	Issue Description	Solution Description	Rev.
1	34	USB3.0 Re-driver	13'0814	EE	Pull-up and Pull-down resister	R2628, R2638, R2639, R2644	1.0
2	41	POWER BOTTON	13'0814	EE	Un-pop power botton.	SW5 and SW6	1.0
3	38	Board ID	13'0814	EE	Change board ID to REV. A00.	Change R392 to 8.2K ohm.	1.0
4	41	LED bright	13'0814	ME	change LED resister to 300 ohm	R438, R436, R435, R433 and R429	1.0
5	38	AUDIO test fail	13'0814	EE	Audio resistor change from 9.1 ohm to 18 ohm	R162 and R166	1.0
6	42~46	GPU chip PN	13'0814	EE	Update P/N of GPU chip	Change P/N of UV1 to SA00006CB1L.	1.0
7	28	LAN chip P/N	13'0814	EE	Type change to T & R	Change P/N of U21 to SA000066W4L.	1.0
8	1	change R3 PN of PCB	13'0815	EE	change R3 PN of PCB	Change from DA8000WJ000 to DA8000WJ011	1.0
9	16	BT issue	13'0822	EE	Un-pop 0.47uF between “+PCH_VCCDSW3_3” and “+PCH_VCCDSW”	C413	1.0
10	36	EMI Request	13'0822	EMI	Add D2 on “Sleeve” & “Ring2” and connect to DGND		1.0

Compal Electronics, Inc.

Title: EE PIR(1)

Size | Document Number: LA-9832P | Rev: 0.5

Date: Friday, August 30, 2013 | Sheet 65 of 64